MachXO2™ Family Data Sheet

DS1035 Version 3.3, March 2017

MachXO2 Family Data Sheet Introduction

May 2016 Data Sheet DS1035

Features

- **Flexible Logic Architecture**
  - Six devices with 256 to 6864 LUT4s and 18 to 334 I/Os
- **Ultra Low Power Devices**
  - Advanced 65 nm low power process
  - As low as 22 µW standby power
  - Programmable low swing differential I/Os
  - Stand-by mode and other power saving options
- **Embedded and Distributed Memory**
  - Up to 240 kbits sysMEM™ Embedded Block RAM
  - Up to 54 kbits Distributed RAM
  - Dedicated FIFO control logic
- **On-Chip User Flash Memory**
  - Up to 256 kbits of User Flash Memory
  - 100,000 write cycles
  - Accessible through WISHBONE, SPI, I^2C and JTAG interfaces
  - Can be used as soft processor PROM or as Flash memory
- **Pre-Engineered Source Synchronous I/O**
  - DDR registers in I/O cells
  - Dedicated gearing logic
  - 7:1 Gearing for Display I/Os
  - Generic DDR, DDRX2, DDRX4
  - Dedicated DDR/DDR2/LPDDR memory with DQS support
- **High Performance, Flexible I/O Buffer**
  - Programmable sysIO™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTL
    - PCI
    - LVDS, Bus-LVDS, MLVDS, RSDS, LVPECL
    - SSTL 25/18
    - HSTL 18
    - Schmitt trigger inputs, up to 0.5 V hysteresis
  - I/Os support hot socketing
  - On-chip differential termination
  - Programmable pull-up or pull-down mode
- **Flexible On-Chip Clocking**
  - Eight primary clocks
  - Up to two edge clocks for high-speed I/O interfaces (top and bottom sides only)
  - Up to two analog PLLs per device with fractional-n frequency synthesis
    - Wide input frequency range (7 MHz to 400 MHz)
- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - Single-chip, secure solution
  - Programmable through JTAG, SPI or I^2C
  - Supports background programming of non-volatile memory
  - Optional dual boot with external SPI memory
- **TransFR™ Reconfiguration**
  - In-field logic update while system operates
- **Enhanced System Level Support**
  - On-chip hardened functions: SPI, I^2C, timer/counter
  - On-chip oscillator with 5.5% accuracy
  - Unique TraceID for system tracking
  - One Time Programmable (OTP) mode
  - Single power supply with extended operating range
  - IEEE Standard 1149.1 boundary scan
  - IEEE 1532 compliant in-system programming
- **Broad Range of Package Options**
  - TQFP, WLCSP, ucBGA, csBGA, caBGA, ftBGA, fpBGA, QFN package options
  - Small footprint package options
    - As small as 2.5 mm x 2.5 mm
  - Density migration supported
  - Advanced halogen-free packaging

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Table 1-1. MachXO2™ Family Selection Guide

		XO2-256	XO2-640	XO2-640U[1]	XO2-1200	XO2-1200U[1]	XO2-2000	XO2-2000U[1]	XO2-4000	XO2-7000
LUTs		256	640	640	1280	1280	2112	2112	4320	6864
Distributed RAM (kbits)		2	5	5	10	10	16	16	34	54
EBR SRAM (kbits)		0	18	64	64	74	74	92	92	240
Number of EBR SRAM Blocks (9 kbits/block)		0	2	7	7	8	8	10	10	26
UFM (kbits)		0	24	64	64	80	80	96	96	256
Device Options:	HC[2]	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	HE[3]						Yes	Yes	Yes	Yes
	ZE[4]	Yes	Yes		Yes		Yes		Yes	Yes
Number of PLLs		0	0	1	1	1	1	2	2	2
Hardened Functions:	I2C	2	2	2	2	2	2	2	2	2
	SPI	1	1	1	1	1	1	1	1	1
	Timer/Counter	1	1	1	1	1	1	1	1	1
Packages						**IO**				
25-ball WLCSP[5] (2.5 mm x 2.5 mm, 0.4 mm)					18					
32 QFN[6] (5 mm x 5 mm, 0.5 mm)		21			21					
48 QFN[8, 9] (7 mm x 7 mm, 0.5 mm)		40	40							
49-ball WLCSP[5] (3.2 mm x 3.2 mm, 0.4 mm)							38			
64-ball ucBGA (4 mm x 4 mm, 0.4 mm)		44								
84 QFN[7] (7 mm x 7 mm, 0.5 mm)									68	
100-pin TQFP (14 mm x 14 mm)		55	78		79		79			
132-ball csBGA (8 mm x 8 mm, 0.5 mm)		55	79		104		104		104	
144-pin TQFP (20 mm x 20 mm)				107	107		111		114	114
184-ball csBGA[7] (8 mm x 8 mm, 0.5 mm)									150	
256-ball caBGA (14 mm x 14 mm, 0.8 mm)							206		206	206
256-ball ftBGA (17 mm x 17 mm, 1.0 mm)						206	206		206	206
332-ball caBGA (17 mm x 17 mm, 0.8 mm)									274	278
484-ball ftBGA (23 mm x 23 mm, 1.0 mm)								278	278	334

1. Ultra high I/O device.
2. High performance with regulator – VCC = 2.5 V, 3.3 V
3. High performance without regulator – V_{CC} = 1.2 V
4. Low power without regulator – V_{CC} = 1.2 V
5. WLCSP package only available for ZE devices.
6. 32 QFN package only available for HC and ZE devices.
7. 184 csBGA package only available for HE devices.
8. 48-pin QFN information is ‘Advanced’.
9. 48 QFN package only available for HC devices.

Introduction

The MachXO2 family of ultra low power, instant-on, non-volatile PLDs has six devices with densities ranging from 256 to 6864 Look-Up Tables (LUTs). In addition to LUT-based, low-cost programmable logic these devices feature Embedded Block RAM (EBR), Distributed RAM, User Flash Memory (UFM), Phase Locked Loops (PLLs), pre-engineered source synchronous I/O support, advanced configuration support including dual-boot capability and hardened versions of commonly used functions such as SPI controller, I^2C controller and timer/counter. These features allow these devices to be used in low cost, high volume consumer and system applications.

The MachXO2 devices are designed on a 65 nm non-volatile low power process. The device architecture has several features such as programmable low swing differential I/Os and the ability to turn off I/O banks, on-chip PLLs and oscillators dynamically. These features help manage static and dynamic power consumption resulting in low static power for all members of the family.

The MachXO2 devices are available in two versions – ultra low power (ZE) and high performance (HC and HE) devices. The ultra low power devices are offered in three speed grades –1, –2 and –3, with –3 being the fastest. Similarly, the high-performance devices are offered in three speed grades: –4, –5 and –6, with –6 being the fastest. HC devices have an internal linear voltage regulator which supports external V_{CC} supply voltages of 3.3 V or 2.5 V. ZE and HE devices only accept 1.2 V as the external V_{CC} supply voltage. With the exception of power supply voltage all three types of devices (ZE, HC and HE) are functionally compatible and pin compatible with each other.

The MachXO2 PLDs are available in a broad range of advanced halogen-free packages ranging from the space saving 2.5 mm x 2.5 mm WLCSP to the 23 mm x 23 mm fpBGA. MachXO2 devices support density migration within the same package. Table 1-1 shows the LUT densities, package and I/O options, along with other key parameters.

The pre-engineered source synchronous logic implemented in the MachXO2 device family supports a broad range of interface standards, including LPDDR, DDR, DDR2 and 7:1 gearing for display I/Os.

The MachXO2 devices offer enhanced I/O features such as drive strength control, slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. Pull-up, pull-down and bus-keeper features are controllable on a “per-pin” basis.

A user-programmable internal oscillator is included in MachXO2 devices. The clock output from this oscillator may be divided by the timer/counter for use as clock input in functions such as LED control, key-board scanner and similar state machines.

The MachXO2 devices also provide flexible, reliable and secure configuration from on-chip Flash memory. These devices can also configure themselves from external SPI Flash or be configured by an external master through the JTAG test access port or through the I^2C port. Additionally, MachXO2 devices support dual-boot capability (using external Flash memory) and remote field upgrade (TransFR) capability.

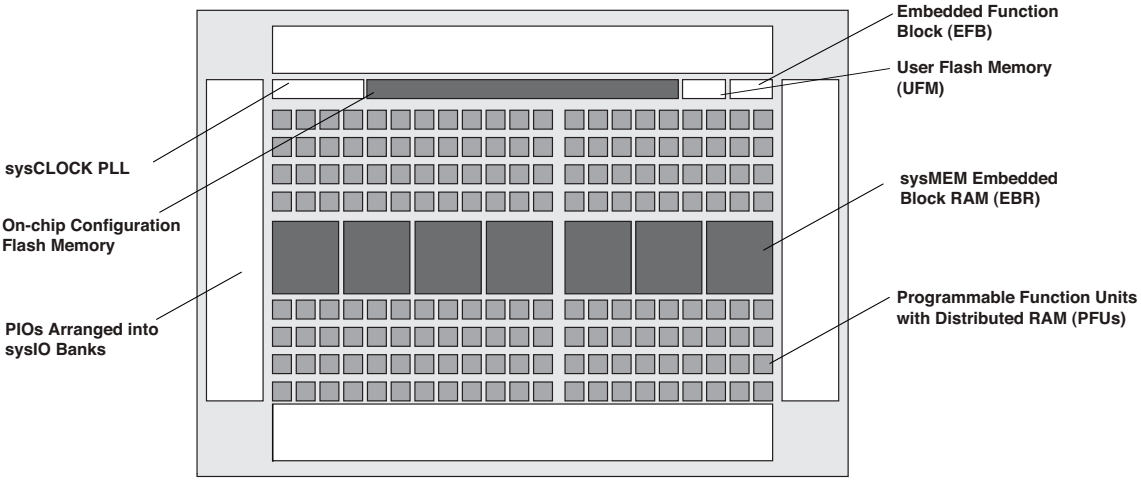
Lattice provides a variety of design tools that allow complex designs to be efficiently implemented using the MachXO2 family of devices. Popular logic synthesis tools provide synthesis library support for MachXO2. Lattice design tools use the synthesis tool output along with the user-specified preferences and constraints to place and route the design in the MachXO2 device. These tools extract the timing from the routing and back-annotate it into the design for timing verification.

Lattice provides many pre-engineered IP (Intellectual Property) LatticeCORE™ modules, including a number of reference designs licensed free of charge, optimized for the MachXO2 PLD family. By using these configurable soft core IP cores as standardized blocks, users are free to concentrate on the unique aspects of their design, increasing their productivity.

Architecture Overview

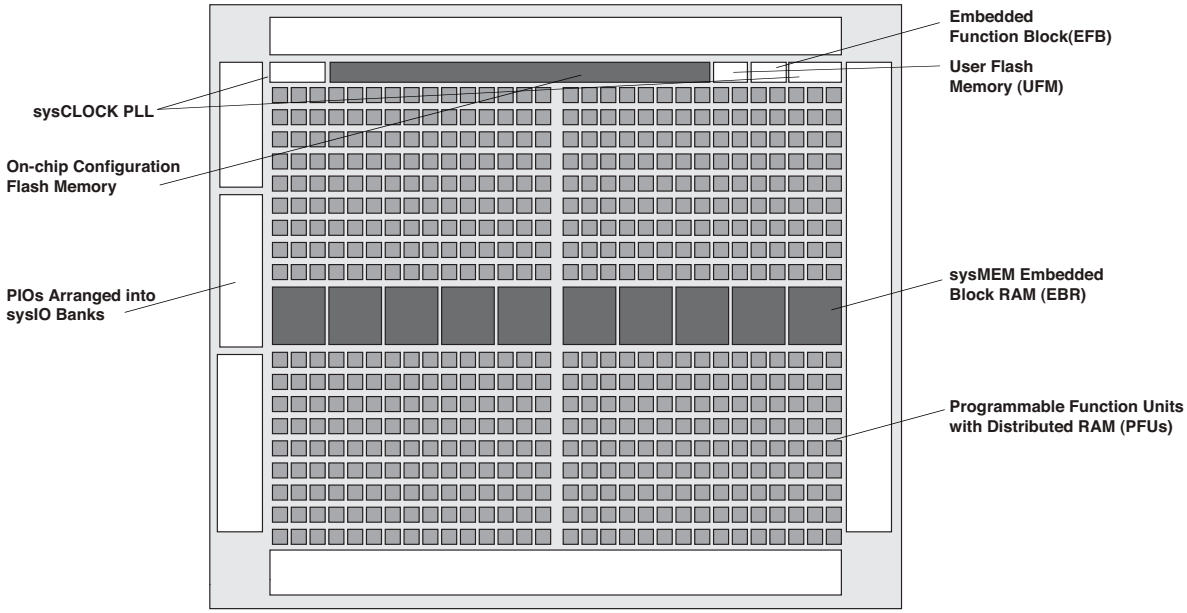
The MachXO2 family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). The larger logic density devices in this family have sysCLOCK™ PLLs and blocks of sysMEM Embedded Block RAM (EBRs). Figure 2-1 and Figure 2-2 show the block diagrams of the various family members.

Figure 2-1. Top View of the MachXO2-1200 Device



Note: MachXO2-256, and MachXO2-640/U are similar to MachXO2-1200. MachXO2-256 has a lower LUT count and no PLL or EBR blocks. MachXO2-640 has no PLL, a lower LUT count and two EBR blocks. MachXO2-640U has a lower LUT count, one PLL and seven EBR blocks.

Figure 2-2. Top View of the MachXO2-4000 Device



Note: MachXO2-1200U, MachXO2-2000/U and MachXO2-7000 are similar to MachXO2-4000. MachXO2-1200U and MachXO2-2000 have a lower LUT count, one PLL, and eight EBR blocks. MachXO2-2000U has a lower LUT count, two PLLs, and 10 EBR blocks. MachXO2-7000 has a higher LUT count, two PLLs, and 26 EBR blocks.

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The logic blocks, Programmable Functional Unit (PFU) and sysMEM EBR blocks, are arranged in a two-dimensional grid with rows and columns. Each row has either the logic blocks or the EBR blocks. The PIO cells are located at the periphery of the device, arranged in banks. The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PIOs utilize a flexible I/O buffer referred to as a sysIO buffer that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

In the MachXO2 family, the number of sysIO banks varies by device. There are different types of I/O buffers on the different banks. Refer to the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found in MachXO2-640/U and larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT usage.

The MachXO2 registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO2 architecture also provides up to two sysCLOCK Phase Locked Loop (PLL) blocks on MachXO2-640U, MachXO2-1200/U and larger devices. These blocks are located at the ends of the on-chip Flash block. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

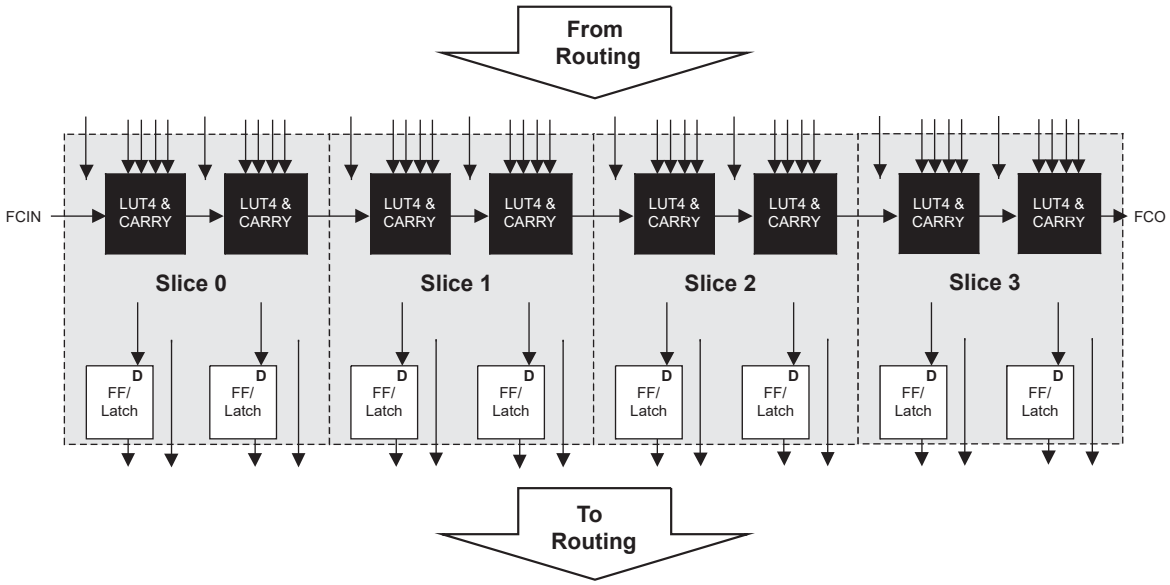
MachXO2 devices provide commonly used hardened functions such as SPI controller, I^2C controller and timer/counter. MachXO2-640/U and higher density devices also provide User Flash Memory (UFM). These hardened functions and the UFM interface to the core logic and routing through a WISHBONE interface. The UFM can also be accessed through the SPI, I^2C and JTAG ports.

Every device in the family has a JTAG port that supports programming and configuration of the device as well as access to the user logic. The MachXO2 devices are available for operation from 3.3 V, 2.5 V and 1.2 V power supplies, providing easy integration into the overall system.

PFU Blocks

The core of the MachXO2 device consists of PFU blocks, which can be programmed to perform logic, arithmetic, distributed RAM and distributed ROM functions. Each PFU block consists of four interconnected slices numbered 0 to 3 as shown in Figure 2-3. Each slice contains two LUTs and two registers. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-3. PFU Block Diagram



Slices

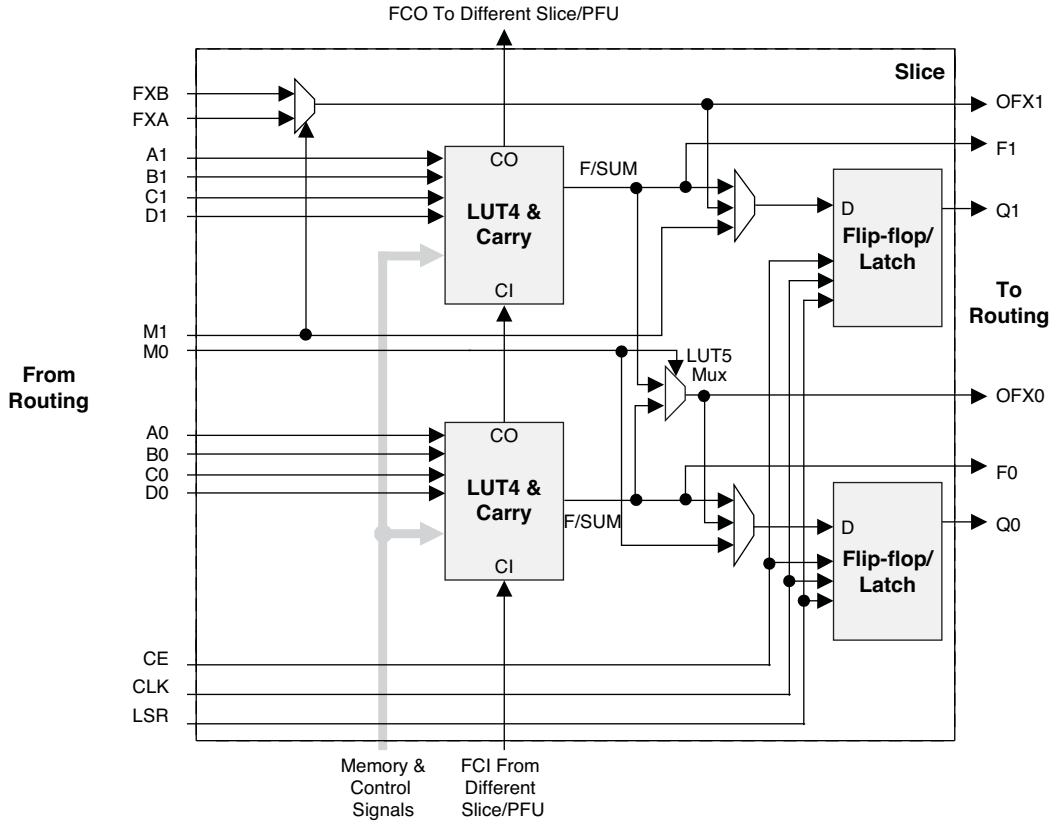
Slices 0-3 contain two LUT4s feeding two registers. Slices 0-2 can be configured as distributed memory. Table 2-1 shows the capability of the slices in PFU blocks along with the operation modes they enable. In addition, each PFU contains logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. The control logic performs set/reset functions (programmable as synchronous/ asynchronous), clock select, chip-select and wider RAM/ROM functions.

Table 2-1. Resources and Modes Available per Slice

Slice	PFU Block	
	Resources	Modes
Slice 0	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM
Slice 1	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM
Slice 2	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM
Slice 3	2 LUT4s and 2 Registers	Logic, Ripple, ROM

Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks. All slices have 15 inputs from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six for routing and one to carry-chain (to the adjacent PFU). Table 2-2 lists the signals associated with Slices 0-3.

Figure 2-4. Slice Diagram



For Slices 0 and 1, memory control signals are generated from Slice 2 as follows:

- WCK is CLK
- WRE is from LSR
- DI[3:2] for Slice 1 and DI[1:0] for Slice 0 data from Slice 2
- WAD [A:D] is a 4-bit address from slice 2 LUT input

Table 2-2. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0/M1	Multi-purpose input
Input	Control signal	CE	Clock enable
Input	Control signal	LSR	Local set/reset
Input	Control signal	CLK	System clock
Input	Inter-PFU signal	FCIN	Fast carry in[1]
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	Fast carry out[1]

1. See Figure 2-3 for connection details.
2. Requires two PFUs.

Modes of Operation

Each slice has up to four potential modes of operation: Logic, Ripple, RAM and ROM.

Logic Mode
In this mode, the LUTs in each slice are configured as 4-input combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any four input logic functions can be generated by programming this lookup table. Since there are two LUT4s per slice, a LUT5 can be constructed within one slice. Larger look-up tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other slices. Note LUT8 requires more than four slices.

Ripple Mode
Ripple mode supports the efficient implementation of small arithmetic functions. In Ripple mode, the following functions can be implemented by each slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Up/down counter with asynchronous clear
- Up/down counter with preload (sync)
- Ripple mode multiplier building block
- Multiplier support
- Comparator functions of A and B inputs
  — A greater-than-or-equal-to B
  — A not-equal-to B
  — A less-than-or-equal-to B

Ripple mode includes an optional configuration that performs arithmetic using fast carry chain methods. In this configuration (also referred to as CCU2 mode) two additional signals, Carry Generate and Carry Propagate, are generated on a per-slice basis to allow fast arithmetic functions to be constructed by concatenating slices.

RAM Mode

In this mode, a 16x4-bit distributed single port RAM (SPR) can be constructed by using each LUT block in Slice 0 and Slice 1 as a 16x1-bit memory. Slice 2 is used to provide memory address and control signals.

MachXO2 devices support distributed memory initialization.

The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of slices required to implement different distributed RAM primitives. For more information about using RAM in MachXO2 devices, please see TN1201, Memory Usage Guide for MachXO2 Devices.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR 16x4	PDPR 16x4
Number of slices	3	3

Note: SPR = Single Port RAM, PDPR = Pseudo Dual Port RAM

ROM Mode

ROM mode uses the LUT logic; hence, slices 0-3 can be used in ROM mode. Preloading is accomplished through the programming interface during PFU configuration.

For more information on the RAM and ROM modes, please refer to TN1201, Memory Usage Guide for MachXO2 Devices.

Routing

There are many resources provided in the MachXO2 devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

The design tools take the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock/Control Distribution Network

Each MachXO2 device has eight clock inputs (PCLK [T, C] [Banknum]_[2..0]) – three pins on the left side, two pins each on the bottom and top sides and one pin on the right side. These clock inputs drive the clock nets. These eight inputs can be differential or single-ended and may be used as general purpose I/O if they are not used to drive the clock nets. When using a single ended clock input, only the PCLKT input can drive the clock tree directly.

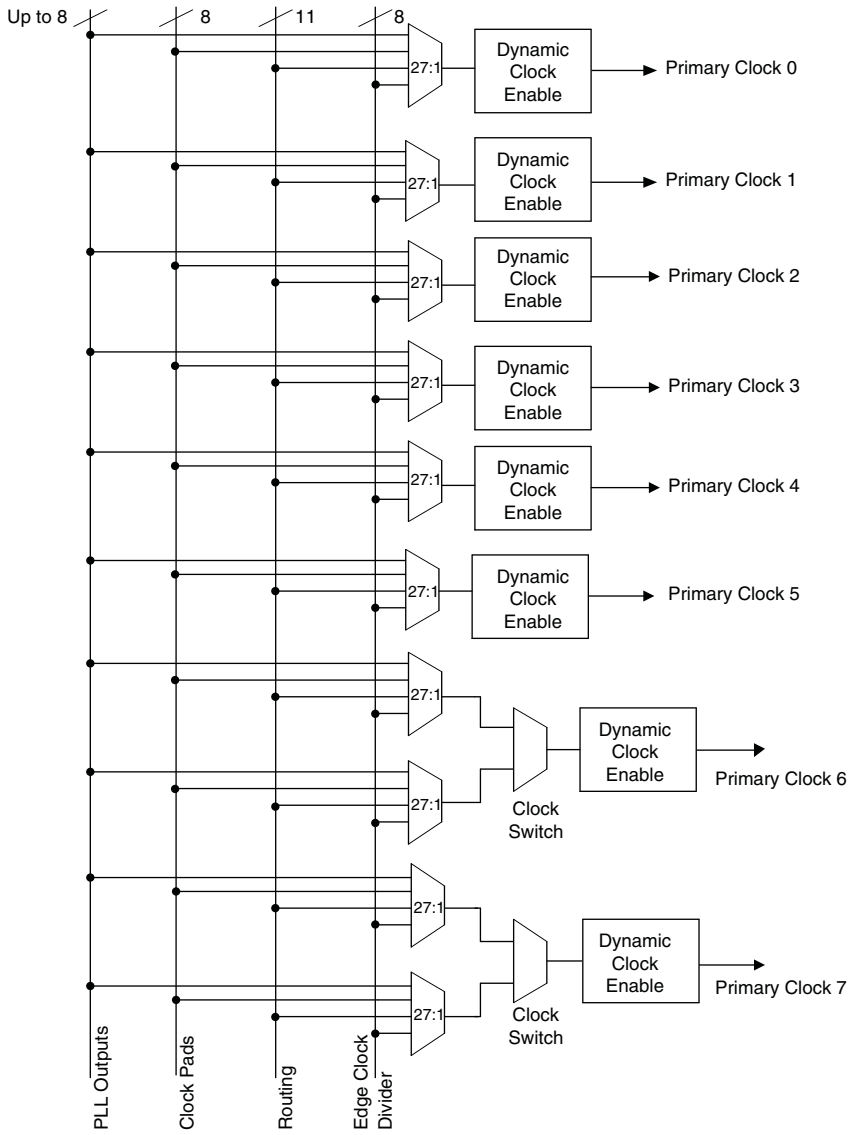
The MachXO2 architecture has three types of clocking resources: edge clocks, primary clocks and secondary high fanout nets. MachXO2-640U, MachXO2-1200/U and higher density devices have two edge clocks each on the top and bottom edges. Lower density devices have no edge clocks. Edge clocks are used to clock I/O registers and have low injection time and skew. Edge clock inputs are from PLL outputs, primary clock pads, edge clock bridge outputs and CIB sources.

The eight primary clock lines in the primary clock network drive throughout the entire device and can provide clocks for all resources within the device including PFUs, EBRs and PICs. In addition to the primary clock signals, MachXO2 devices also have eight secondary high fanout signals which can be used for global control signals, such as clock enables, synchronous or asynchronous clears, presets, output enables, etc. Internal logic can drive the global clock network for internally-generated global clocks and control signals.

The maximum frequency for the primary clock network is shown in the MachXO2 External Switching Characteristics table.

The primary clock signals for the MachXO2-256 and MachXO2-640 are generated from eight 17:1 muxes The available clock sources include eight I/O sources and 9 routing inputs. Primary clock signals for the MachXO2-640U, MachXO2-1200/U and larger devices are generated from eight 27:1 muxes The available clock sources include eight I/O sources, 11 routing inputs, eight clock divider inputs and up to eight sysCLOCK PLL outputs.

Figure 2-5. Primary Clocks for MachXO2 Devices

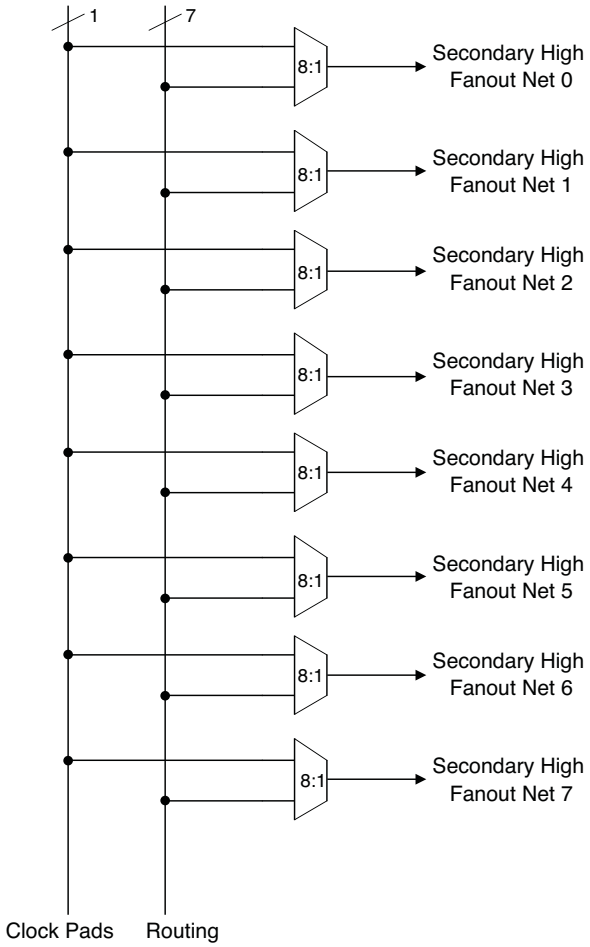


Primary clocks for MachXO2-640U, MachXO2-1200/U and larger devices.

Note: MachXO2-640 and smaller devices do not have inputs from the Edge Clock Divider or PLL and fewer routing inputs. These devices have 17:1 muxes instead of 27:1 muxes.

Eight secondary high fanout nets are generated from eight 8:1 muxes as shown in Figure 2-6. One of the eight inputs to the secondary high fanout net input mux comes from dual function clock pins and the remaining seven come from internal routing. The maximum frequency for the secondary clock network is shown in MachXO2 External Switching Characteristics table.

Figure 2-6. Secondary High Fanout Nets for MachXO2 Devices



sysCLOCK Phase Locked Loops (PLLs)

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. The MachXO2-640U, MachXO2-1200/U and larger devices have one or more sysCLOCK PLL. CLKI is the reference frequency input to the PLL and its source can come from an external I/O pin or from internal routing. CLKFB is the feedback signal to the PLL which can come from internal routing or an external I/O pin. The feedback divider is used to multiply the reference frequency and thus synthesize a higher frequency clock output.

The MachXO2 sysCLOCK PLLs support high resolution (16-bit) fractional-N synthesis. Fractional-N frequency synthesis allows the user to generate an output clock which is a non-integer multiple of the input frequency. For more information about using the PLL with Fractional-N synthesis, please see TN1199, MachXO2 sysCLOCK PLL Design and Usage Guide.

Each output has its own output divider, thus allowing the PLL to generate different frequencies for each output. The output dividers can have a value from 1 to 128. The output dividers may also be cascaded together to generate low frequency clocks. The CLKOP, CLKOS, CLKOS2, and CLKOS3 outputs can all be used to drive the MachXO2 clock distribution network directly or general purpose routing resources can be used.

The LOCK signal is asserted when the PLL determines it has achieved lock and de-asserted if a loss of lock is detected. A block diagram of the PLL is shown in Figure 2-7.

The setup and hold times of the device can be improved by programming a phase shift into the CLKOS, CLKOS2, and CLKOS3 output clocks which will advance or delay the output clock with reference to the CLKOP output clock.

This phase shift can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after a phase adjustment on the output used as the feedback source and not relock until the t_{LOCK} parameter has been satisfied.

The MachXO2 also has a feature that allows the user to select between two different reference clock sources dynamically. This feature is implemented using the PLLREFCS primitive. The timing parameters for the PLL are shown in the sysCLOCK PLL Timing table.

The MachXO2 PLL contains a WISHBONE port feature that allows the PLL settings, including divider values, to be dynamically changed from the user logic. When using this feature the EFB block must also be instantiated in the design to allow access to the WISHBONE ports. Similar to the dynamic phase adjustment, when PLL settings are updated through the WISHBONE port the PLL may lose lock and not relock until the t_{LOCK} parameter has been satisfied. The timing parameters for the PLL are shown in the sysCLOCK PLL Timing table.

For more details on the PLL and the WISHBONE interface, see TN1199, MachXO2 sysCLOCK PLL Design and Usage Guide.

Figure 2-7. PLL Diagram

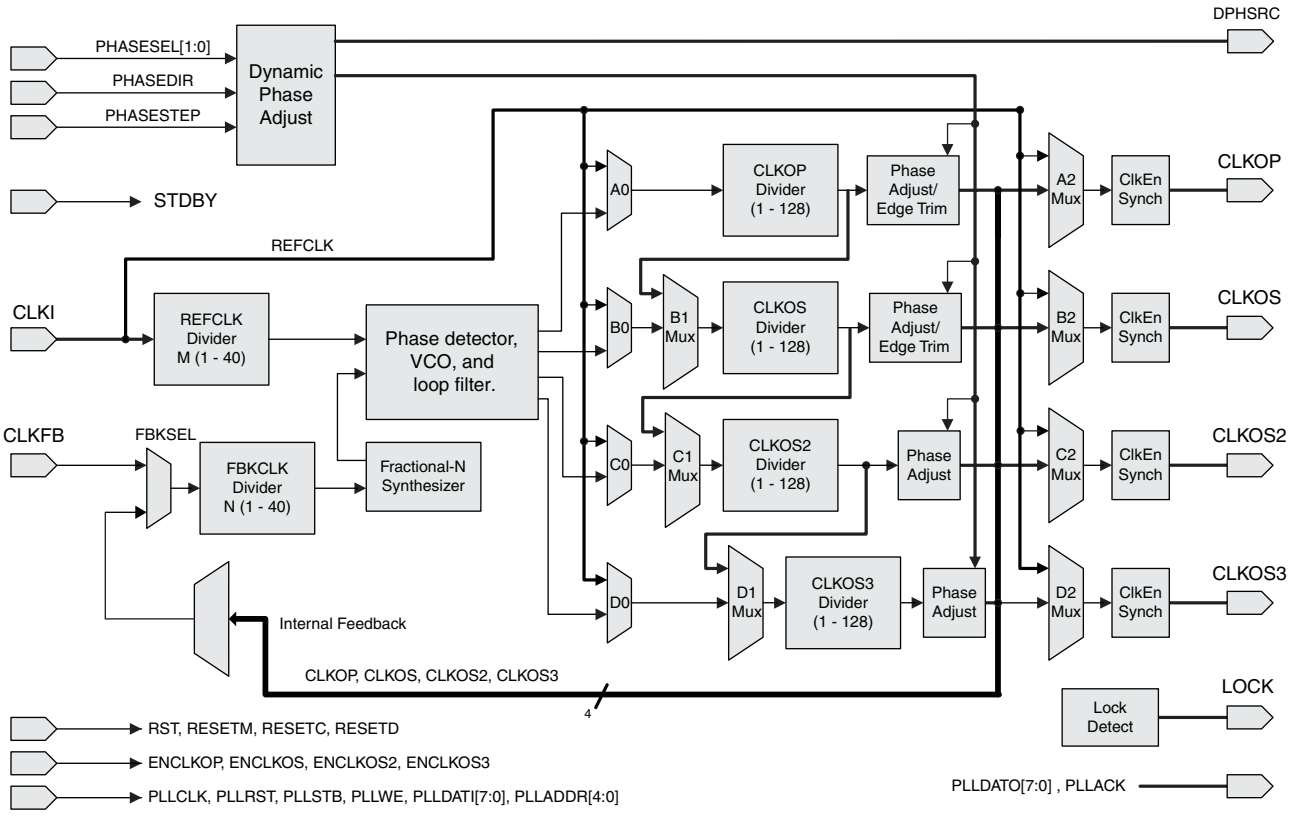


Table 2-4 provides signal descriptions of the PLL block.

Table 2-4. PLL Signal Descriptions

Port Name	I/O	Description
CLKI	I	Input clock to PLL
CLKFB	I	Feedback clock
PHASESEL[1:0]	I	Select which output is affected by Dynamic Phase adjustment ports
PHASEDIR	I	Dynamic Phase adjustment direction
PHASESTEP	I	Dynamic Phase step – toggle shifts VCO phase adjust by one step.

Table 2-4. PLL Signal Descriptions (Continued)

Port Name	I/O	Description
CLKOP	O	Primary PLL output clock (with phase shift adjustment)
CLKOS	O	Secondary PLL output clock (with phase shift adjust)
CLKOS2	O	Secondary PLL output clock2 (with phase shift adjust)
CLKOS3	O	Secondary PLL output clock3 (with phase shift adjust)
LOCK	O	PLL LOCK, asynchronous signal. Active high indicates PLL is locked to input and feedback signals.
DPHSRC	O	Dynamic Phase source – ports or WISHBONE is active
STDBY	I	Standby signal to power down the PLL
RST	I	PLL reset without resetting the M-divider. Active high reset.
RESETM	I	PLL reset - includes resetting the M-divider. Active high reset.
RESETC	I	Reset for CLKOS2 output divider only. Active high reset.
RESETD	I	Reset for CLKOS3 output divider only. Active high reset.
ENCLKOP	I	Enable PLL output CLKOP
ENCLKOS	I	Enable PLL output CLKOS when port is active
ENCLKOS2	I	Enable PLL output CLKOS2 when port is active
ENCLKOS3	I	Enable PLL output CLKOS3 when port is active
PLLCLK	I	PLL data bus clock input signal
PLLRST	I	PLL data bus reset. This resets only the data bus not any register values.
PLLSTB	I	PLL data bus strobe signal
PLLWE	I	PLL data bus write enable signal
PLLADDR [4:0]	I	PLL data bus address
PLLDATI [7:0]	I	PLL data bus data input
PLLDATO [7:0]	O	PLL data bus data output
PLLACK	O	PLL data bus acknowledge signal

sysMEM Embedded Block RAM Memory

The MachXO2-640/U and larger devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-kbit RAM, with dedicated input and output registers. This memory can be used for a wide variety of purposes including data buffering, PROM for the soft processor and FIFO.

sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-5.

Table 2-5. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. EBR initialization data can be loaded from the UFM. To maximize the number of UFM bits, initialize the EBRs used in your design to an all-zero pattern. Initializing to an all-zero pattern does not use up UFM bits. MachXO2 devices have been designed such that multiple EBRs share the same initialization memory space if they are initialized to the same pattern.

By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual, Pseudo-Dual Port and FIFO Modes

Figure 2-8 shows the five basic memory configurations and their input/output names. In all the sysMEM RAM modes, the input data and addresses for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the memory array output.

Figure 2-8. sysMEM Memory Primitives

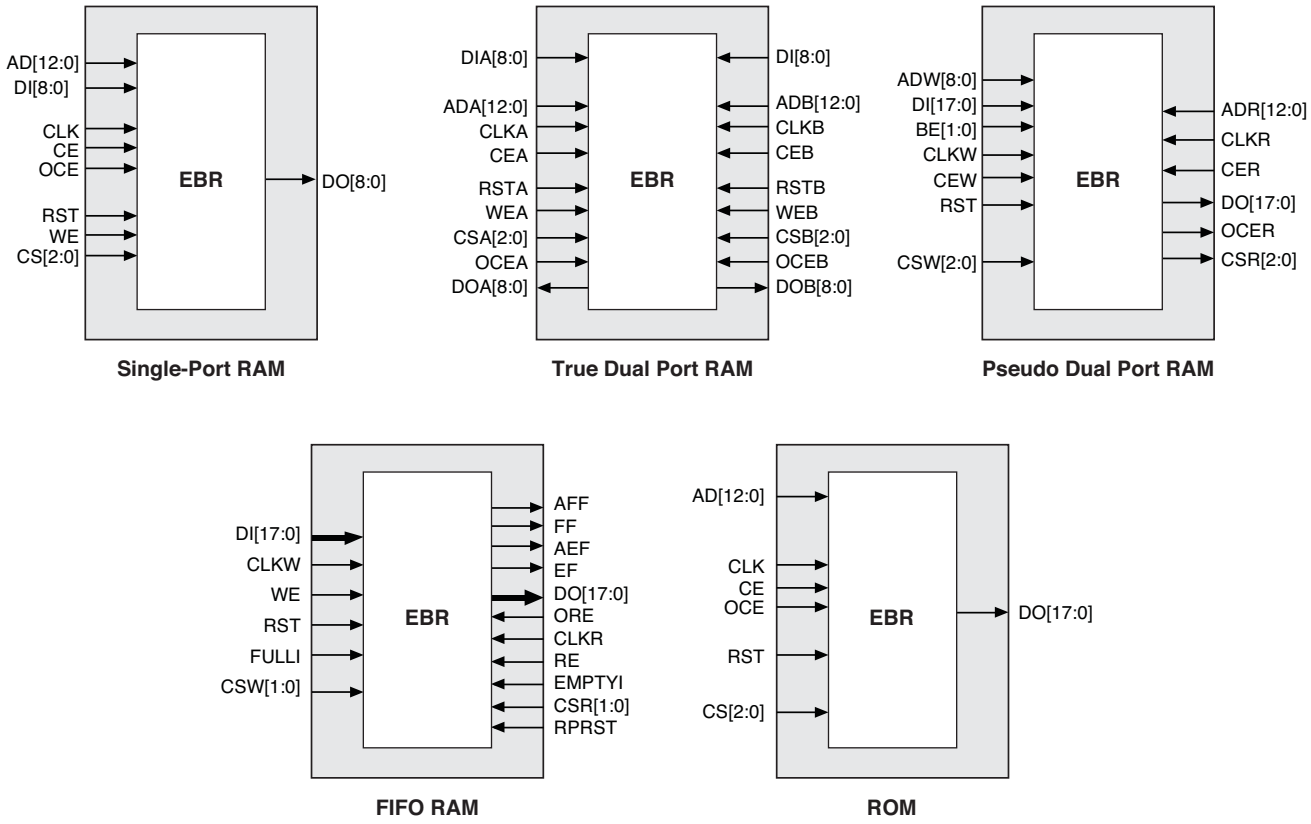


Table 2-6. EBR Signal Descriptions

Port Name	Description	Active State
CLK	Clock	Rising Clock Edge
CE	Clock Enable	Active High
OCE[1]	Output Clock Enable	Active High
RST	Reset	Active High
BE[1]	Byte Enable	Active High
WE	Write Enable	Active High
AD	Address Bus	—
DI	Data In	—
DO	Data Out	—
CS	Chip Select	Active High
AFF	FIFO RAM Almost Full Flag	—
FF	FIFO RAM Full Flag	—
AEF	FIFO RAM Almost Empty Flag	—
EF	FIFO RAM Empty Flag	—
RPRST	FIFO RAM Read Pointer Reset	—

1. Optional signals.
2. For dual port EBR primitives a trailing ‘A’ or ‘B’ in the signal name specifies the EBR port A or port B respectively.
3. For FIFO RAM mode primitive, a trailing ‘R’ or ‘W’ in the signal name specifies the FIFO read port or write port respectively.
4. For FIFO RAM mode primitive FULLI has the same function as CSW(2) and EMPTYI has the same function as CSR(2).
5. In FIFO mode, CLKW is the write port clock, CSW is the write port chip select, CLKR is the read port clock, CSR is the read port chip select, ORE is the output read enable.

The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – Data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

2. **Write Through** – A copy of the input data appears at the output of the same port. This mode is supported for all data widths.

3. **Read-Before-Write** – When new data is being written, the old contents of the address appears at the output.

FIFO Configuration

The FIFO has a write port with data-in, CEW, WE and CLKW signals. There is a separate read port with data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. Table 2-7 shows the range of programming values for these flags.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to max (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

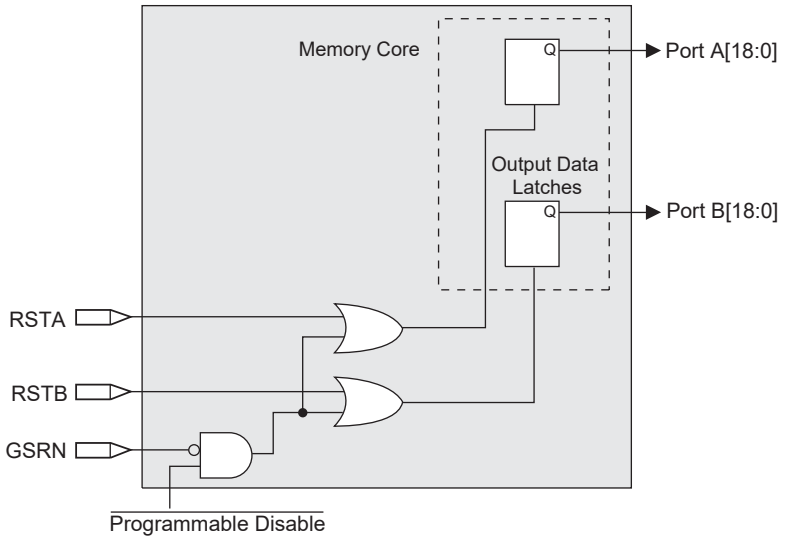
N = Address bit width.

The FIFO state machine supports two types of reset signals: RST and RPRST. The RST signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RPRST signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory core contains data output latches for ports A and B. These are simple latches that can be reset synchronously or asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with port A and port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-9.

Figure 2-9. Memory Core Reset

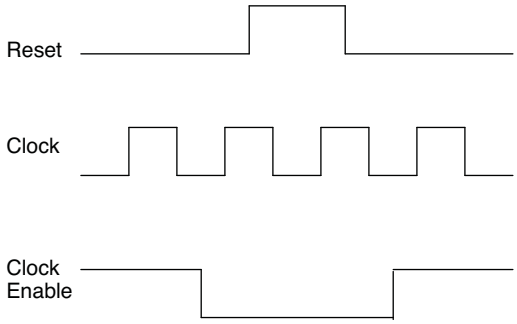


For further information on the sysMEM EBR block, please refer to TN1201, Memory Usage Guide for MachXO2 Devices.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-10. The GSR input to the EBR is always asynchronous.

Figure 2-10. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device wake up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM and FIFO implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-10. The reset timing rules apply to the RPReset input versus the RE input and the RST input versus the WE and RE inputs. Both RST and RPReset are always asynchronous EBR inputs. For more details refer to TN1201, Memory Usage Guide for MachXO2 Devices.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

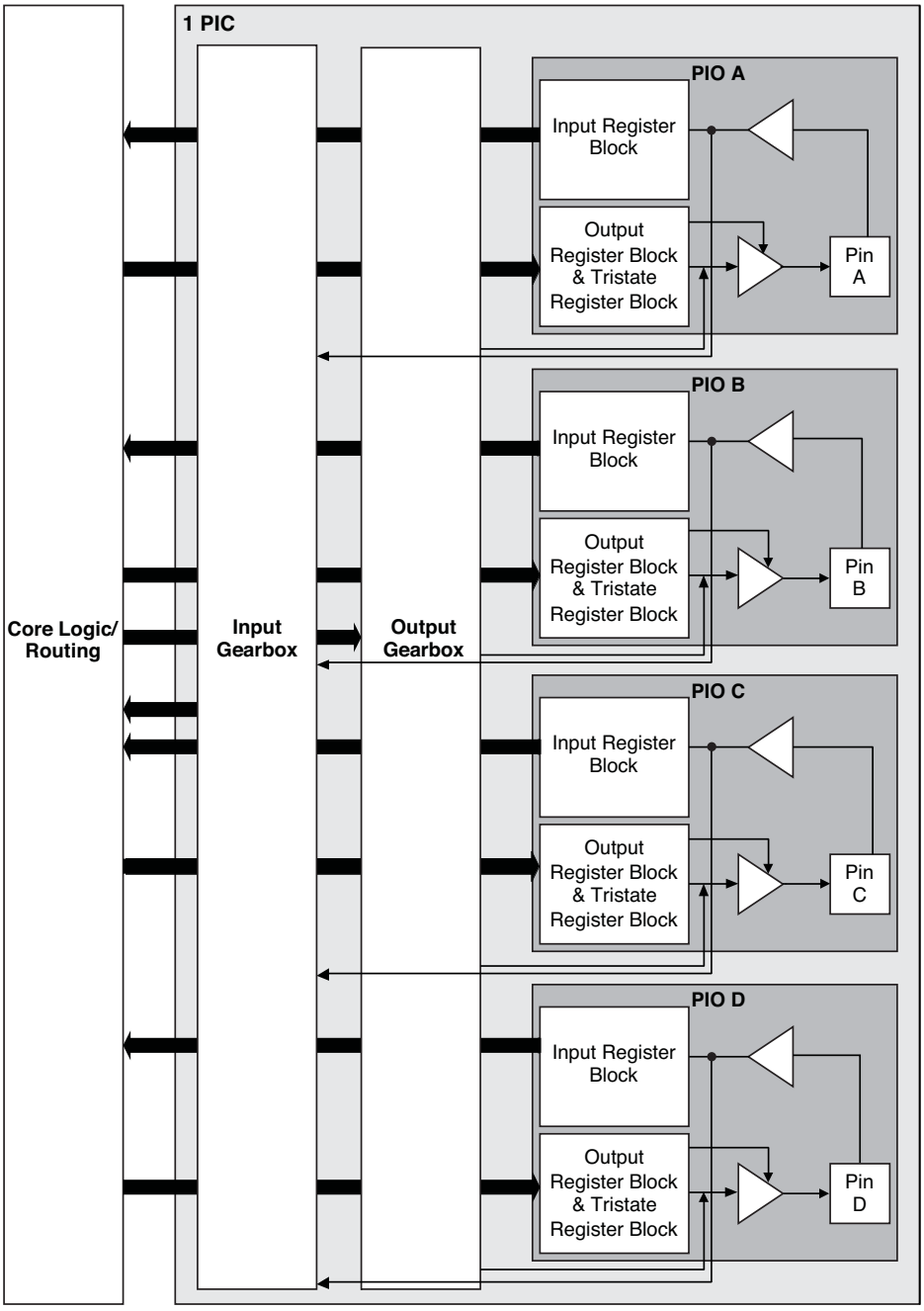
Programmable I/O Cells (PIC)

The programmable logic associated with an I/O is called a PIO. The individual PIO are connected to their respective sysIO buffers and pads. On the MachXO2 devices, the PIO cells are assembled into groups of four PIO cells called a Programmable I/O Cell or PIC. The PICs are placed on all four sides of the device.

On all the MachXO2 devices, two adjacent PIOs can be combined to provide a complementary output driver pair.

The MachXO2-640U, MachXO2-1200/U and higher density devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. Half of the PIO pairs on the top edge of these devices can be configured as true LVDS transmit pairs. The PIO pairs on the bottom edge of these higher density devices have on-chip differential termination and also provide PCI support.

Figure 2-11. Group of Four Programmable I/O Cells



Notes:
1. Input gearbox is available only in PIC on the bottom edge of MachXO2-640U, MachXO2-1200/U and larger devices.
2. Output gearbox is available only in PIC on the top edge of MachXO2-640U, MachXO2-1200/U and larger devices.

PIO

The PIO contains three blocks: an input register block, output register block and tri-state register block. These blocks contain registers for operating in a variety of modes along with the necessary clock and selection logic.

Table 2-8. PIO Signal List

Pin Name	I/O Type	Description
CE	Input	Clock Enable
D	Input	Pin input from sysIO buffer.
INDD	Output	Register bypassed input.
INCK	Output	Clock input
Q0	Output	DDR positive edge input
Q1	Output	Registered input/DDR negative edge input
D0	Input	Output signal from the core (SDR and DDR)
D1	Input	Output signal from the core (DDR)
TD	Input	Tri-state signal from the core
Q	Output	Data output signals to sysIO Buffer
TQ	Output	Tri-state output signals to sysIO Buffer
DQSR90[1]	Input	DQS shift 90-degree read clock
DQSW90[1]	Input	DQS shift 90-degree write clock
DDRCLKPOL[1]	Input	DDR input register polarity control signal from DQS
SCLK	Input	System clock for input and output/tri-state blocks.
RST	Input	Local set reset signal

1. Available in PIO on right edge only.

Input Register Block

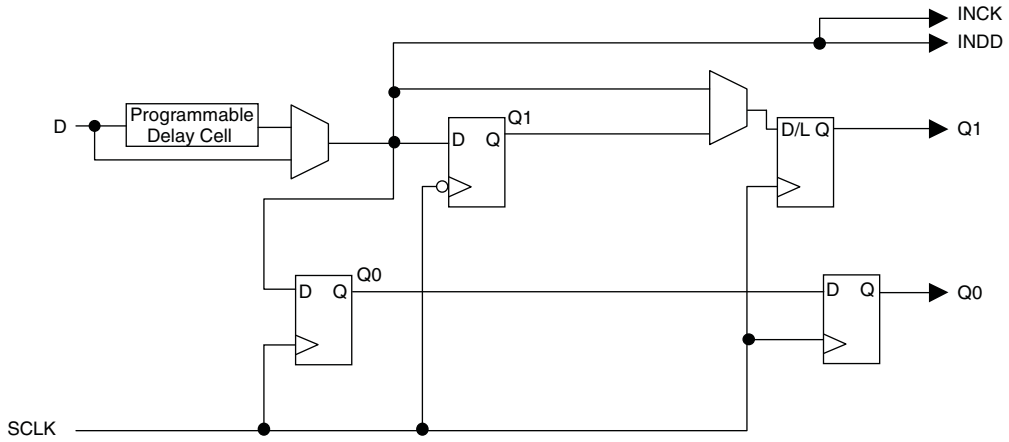
The input register blocks for the PIOs on all edges contain delay elements and registers that can be used to condition high-speed interface signals before they are passed to the device core. In addition to this functionality, the input register blocks for the PIOs on the right edge include built-in logic to interface to DDR memory.

Figure 2-12 shows the input register block for the PIOs located on the left, top and bottom edges. Figure 2-13 shows the input register block for the PIOs on the right edge.

Left, Top, Bottom Edges

Input signals are fed from the sysIO buffer to the input register block (as signal D). If desired, the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), and a clock (INCK). If an input delay is desired, users can select a fixed delay. I/Os on the bottom edge also have a dynamic delay, DEL[4:0]. The delay, if selected, reduces input register hold time requirements when using a global clock. The input block allows two modes of operation. In single data rate (SDR) the data is registered with the system clock (SCLK) by one of the registers in the single data rate sync register block. In Generic DDR mode, two registers are used to sample the data on the positive and negative edges of the system clock (SCLK) signal, creating two data streams.

Figure 2-12. MachXO2 Input Register Block Diagram (PIO on Left, Top and Bottom Edges)



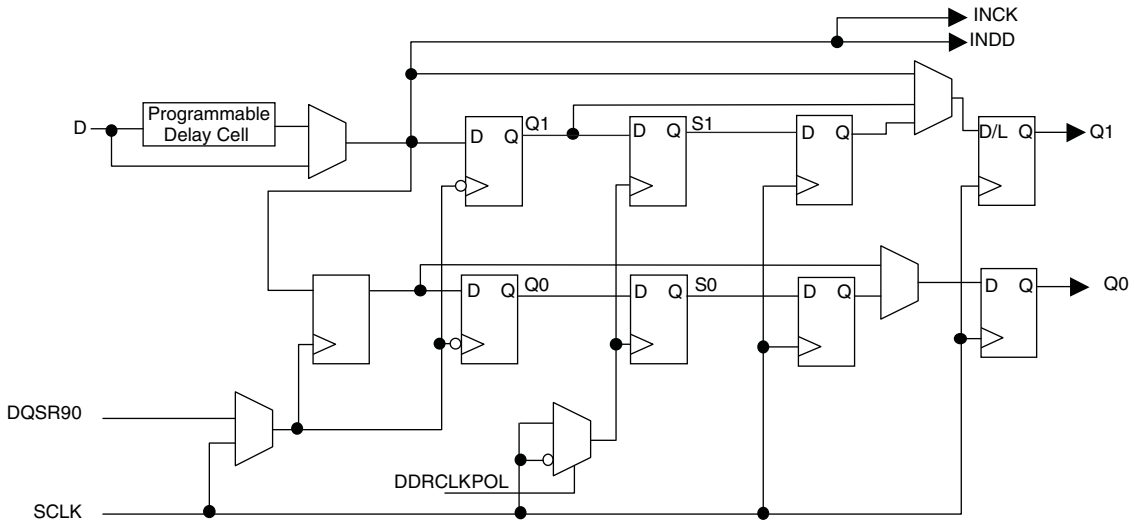
Right Edge

The input register block on the right edge is a superset of the same block on the top, bottom, and left edges. In addition to the modes described above, the input register block on the right edge also supports DDR memory mode.

In DDR memory mode, two registers are used to sample the data on the positive and negative edges of the modified DQS (DQSR90) in the DDR Memory mode creating two data streams. Before entering the core, these two data streams are synchronized to the system clock to generate two data streams.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred to the system clock domain from the DQS domain. The DQSR90 and DDRCLKPOL signals are generated in the DQS read-write block.

Figure 2-13. MachXO2 Input Register Block Diagram (PIO on Right Edge)



Output Register Block

The output register block registers signals from the core of the device before they are passed to the sysIO buffers.

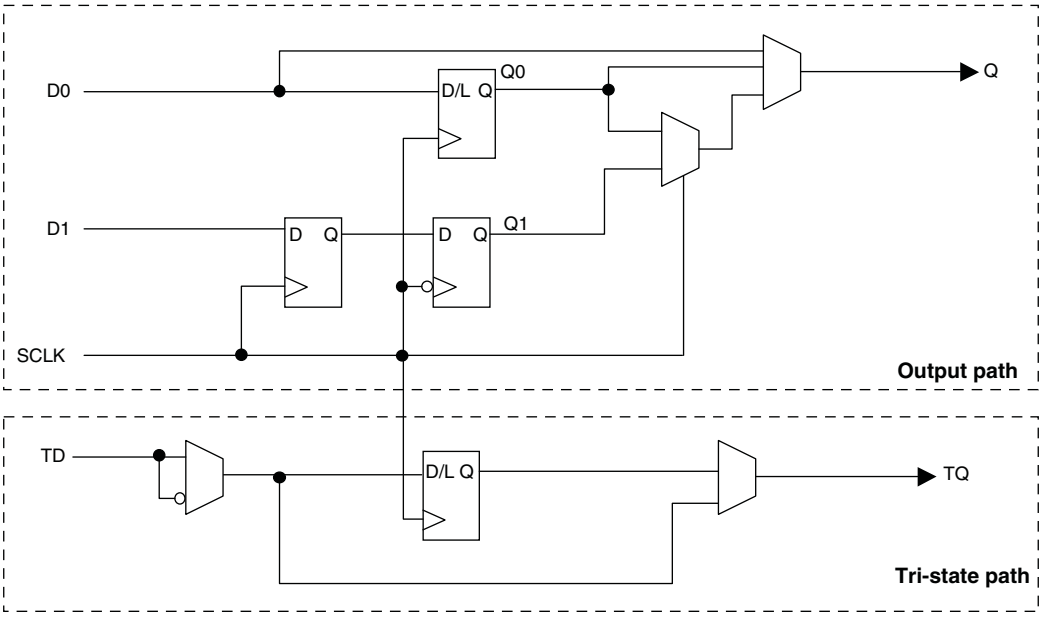
Left, Top, Bottom Edges

In SDR mode, D0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured as a D-type register or latch.

In DDR generic mode, D0 and D1 inputs are fed into registers on the positive edge of the clock. At the next falling edge the registered D1 input is registered into the register Q1. A multiplexer running off the same clock is used to switch the mux between the outputs of registers Q0 and Q1 that will then feed the output.

Figure 2-14 shows the output register block on the left, top and bottom edges.

Figure 2-14. MachXO2 Output Register Block Diagram (PIO on the Left, Top and Bottom Edges)



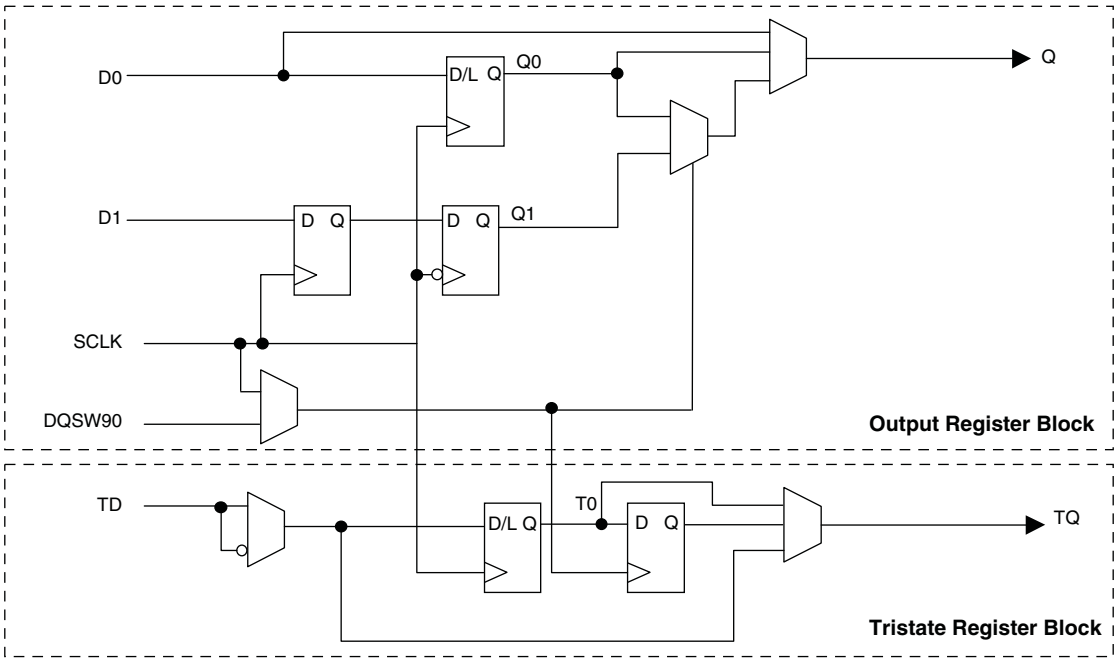
Right Edge

The output register block on the right edge is a superset of the output register on left, top and bottom edges of the device. In addition to supporting SDR and Generic DDR modes, the output register blocks for PIOs on the right edge include additional logic to support DDR-memory interfaces. Operation of this block is similar to that of the output register block on other edges.

In DDR memory mode, D0 and D1 inputs are fed into registers on the positive edge of the clock. At the next falling edge the registered D1 input is registered into the register Q1. A multiplexer running off the DQSW90 signal is used to switch the mux between the outputs of registers Q0 and Q1 that will then feed the output.

Figure 2-15 shows the output register block on the right edge.

Figure 2-15. MachXO2 Output Register Block Diagram (PIO on the Right Edges)



Tri-state Register Block

The tri-state register block registers tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation. In SDR, TD input feeds one of the flip-flops that then feeds the output.

The tri-state register blocks on the right edge contain an additional register for DDR memory operation. In DDR memory mode, the register TS input is fed into another register that is clocked using the DQSW90 signal. The output of this register is used as a tri-state control.

Input Gearbox

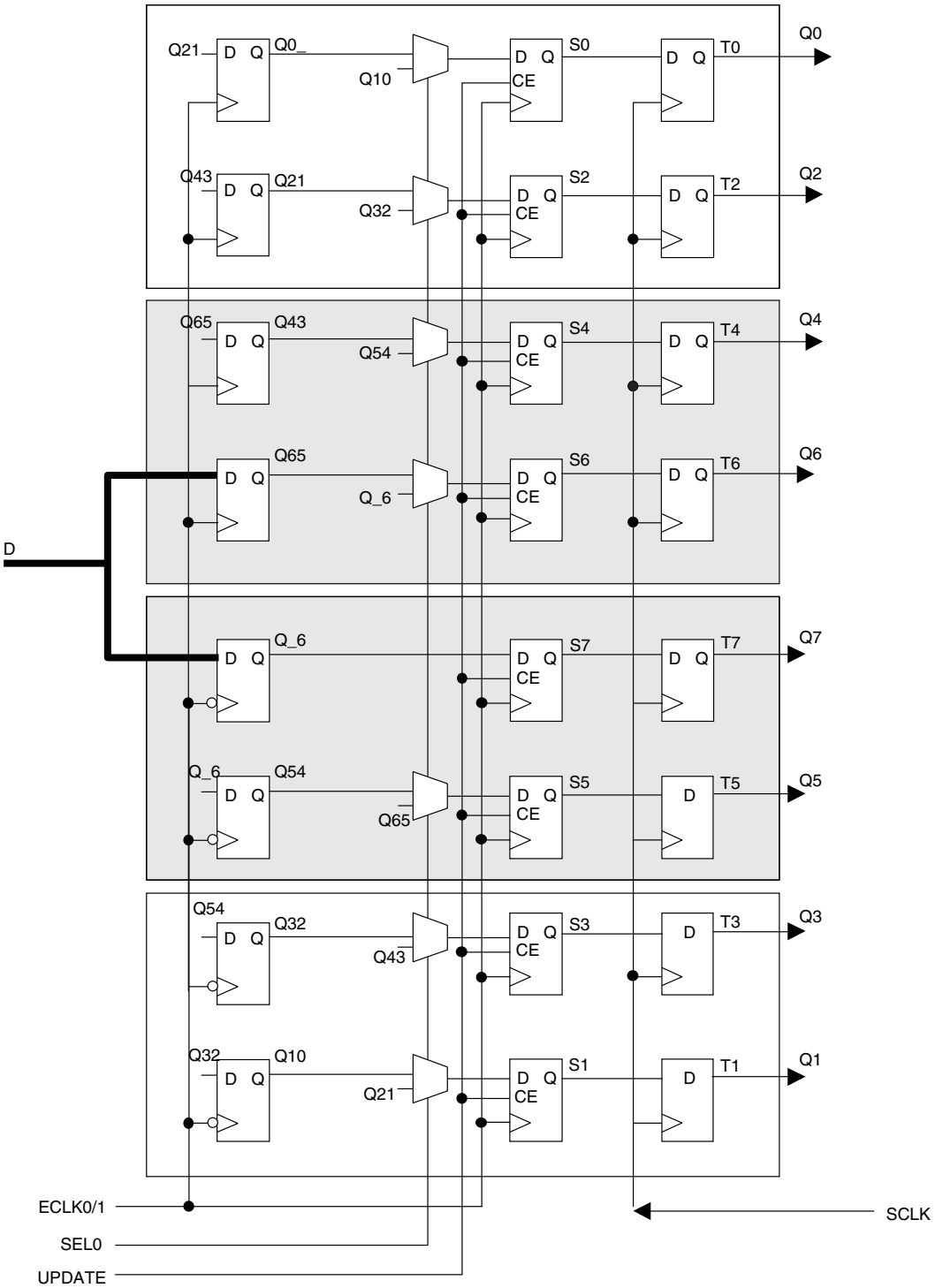
Each PIC on the bottom edge has a built-in 1:8 input gearbox. Each of these input gearboxes may be programmed as a 1:7 de-serializer or as one IDDRX4 (1:8) gearbox or as two IDDRX2 (1:4) gearboxes. Table 2-9 shows the gearbox signals.

Table 2-9. Input Gearbox Signal List

Name	I/O Type	Description
D	Input	High-speed data input after programmable delay in PIO A input register block
ALIGNWD	Input	Data alignment signal from device core
SCLK	Input	Slow-speed system clock
ECLK[1:0]	Input	High-speed edge clock
RST	Input	Reset
Q[7:0]	Output	Low-speed data to device core: Video RX(1:7): Q[6:0] GDDRX4(1:8): Q[7:0] GDDRX2(1:4)(IOL-A): Q4, Q5, Q6, Q7 GDDRX2(1:4)(IOL-C): Q0, Q1, Q2, Q3

These gearboxes have three stage pipeline registers. The first stage registers sample the high-speed input data by the high-speed edge clock on its rising and falling edges. The second stage registers perform data alignment based on the control signals UPDATE and SEL0 from the control block. The third stage pipeline registers pass the data to the device core synchronized to the low-speed system clock. Figure 2-16 shows a block diagram of the input gearbox.

Figure 2-16. Input Gearbox



More information on the input gearbox is available in TN1203, Implementing High-Speed Interfaces with MachXO2 Devices.

Output Gearbox

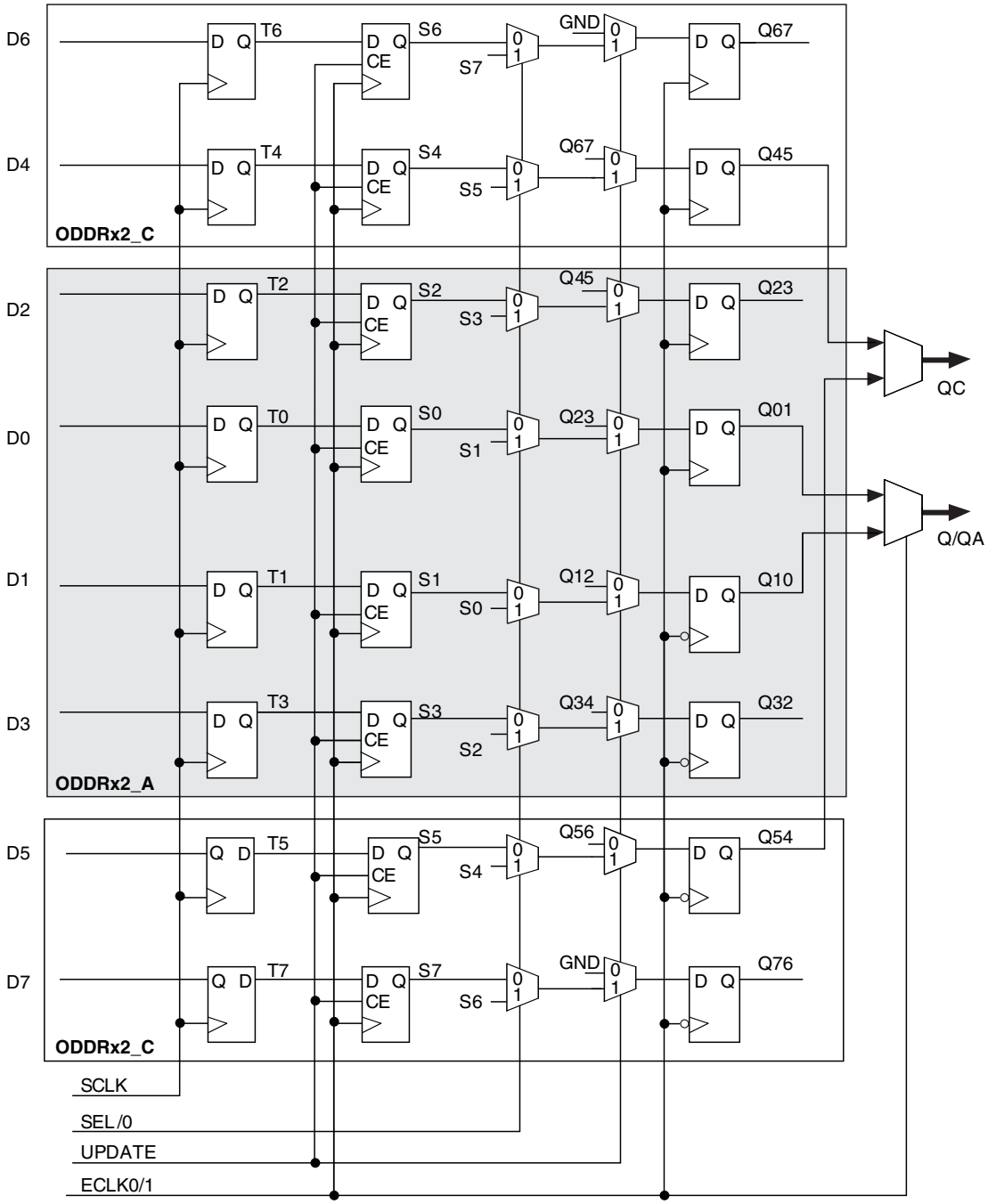
Each PIC on the top edge has a built-in 8:1 output gearbox. Each of these output gearboxes may be programmed as a 7:1 serializer or as one ODDRX4 (8:1) gearbox or as two ODDRX2 (4:1) gearboxes. Table 2-10 shows the gearbox signals.

Table 2-10. Output Gearbox Signal List

Name	I/O Type	Description
Q	Output	High-speed data output
D[7:0]	Input	Low-speed data from device core
Video TX(7:1): D[6:0]		
GDDRX4(8:1): D[7:0]		
GDDRX2(4:1)(IOL-A): D[3:0]		
GDDRX2(4:1)(IOL-C): D[7:4]		
SCLK	Input	Slow-speed system clock
ECLK [1:0]	Input	High-speed edge clock
RST	Input	Reset

The gearboxes have three stage pipeline registers. The first stage registers sample the low-speed input data on the low-speed system clock. The second stage registers transfer data from the low-speed clock registers to the high-speed clock registers. The third stage pipeline registers controlled by high-speed edge clock shift and mux the high-speed data out to the sysIO buffer. Figure 2-17 shows the output gearbox block diagram.

Figure 2-17. Output Gearbox



More information on the output gearbox is available in TN1203, Implementing High-Speed Interfaces with MachXO2 Devices.

DDR Memory Support

Certain PICs on the right edge of MachXO2-640U, MachXO2-1200/U and larger devices, have additional circuitry to allow the implementation of DDR memory interfaces. There are two groups of 14 or 12 PIOs each on the right edge with additional circuitry to implement DDR memory interfaces. This capability allows the implementation of up to 16-bit wide memory interfaces. One PIO from each group contains a control element, the DQS Read/Write Block, to facilitate the generation of clock and control signals (DQSR90, DQSW90, DDRCLKPOL and DATAVALID). These clock and control signals are distributed to the other PIO in the group through dedicated low skew routing.

DQS Read Write Block

Source synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment. However, in DDR memories the clock (referred to as DQS) is not free-running so this approach cannot be used. The DQS Read Write block provides the required clock alignment for DDR memory interfaces. DQSR90 and DQSW90 signals are generated by the DQS Read Write block from the DQS input.

In a typical DDR memory interface design, the phase relationship between the incoming delayed DQS strobe and the internal system clock (during the read cycle) is unknown. The MachXO2 family contains dedicated circuits to transfer data between these domains. To prevent set-up and hold violations, at the domain transfer between DQS (delayed) and the system clock, a clock polarity selector is used. This circuit changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of each read cycle for the correct clock polarity. Prior to the read operation in DDR memories, DQS is in tri-state (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit in the DQS Read Write block detects the first DQS rising edge after the preamble state and generates the DDRCLKPOL signal. This signal is used to control the polarity of the clock to the synchronizing registers.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration signals (6-bit bus) from a DLL on the right edge of the device. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in groups referred to as banks. The sysIO buffers allow users to implement a wide variety of standards that are found in today's systems including LVCMOS, TTL, PCI, SSTL, HSTL, LVDS, BLVDS, MLVDS and LVPECL.

Each bank is capable of supporting multiple I/O standards. In the MachXO2 devices, single-ended output buffers, ratioed input buffers (LVTTL, LVCMOS and PCI), differential (LVDS) and referenced input buffers (SSTL and HSTL) are powered using I/O supply voltage (V_{CCIO}). Each sysIO bank has its own V_{CCIO}. In addition, each bank has a voltage reference, V_{REF}, which allows the use of referenced input buffers independent of the bank V_{CCIO}.

MachXO2-256 and MachXO2-640 devices contain single-ended ratioed input buffers and single-ended output buffers with complementary outputs on all the I/O banks. Note that the single-ended input buffers on these devices do not contain PCI clamps. In addition to the single-ended I/O buffers these two devices also have differential and referenced input buffers on all I/Os. The I/Os are arranged in pairs, the two pads in the pair are described as "T" and "C", where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

MachXO2-640U, MachXO2-1200/U, MachXO2-2000/U, MachXO2-4000 and MachXO2-7000 devices contain three types of sysIO buffer pairs.

1. **Left and Right sysIO Buffer Pairs**
   The sysIO buffer pairs in the left and right banks of the device consist of two single-ended output drivers and two single-ended input buffers (for ratioed inputs such as LVCMOS and LVTTL). The I/O pairs on the left and right of the devices also have differential and referenced input buffers.

2. **Bottom sysIO Buffer Pairs**
   The sysIO buffer pairs in the bottom bank of the device consist of two single-ended output drivers and two single-ended input buffers (for ratioed inputs such as LVCMOS and LVTTL). The I/O pairs on the bottom also have differential and referenced input buffers. Only the I/Os on the bottom banks have programmable PCI clamps and differential input termination. The PCI clamp is enabled after V_{CC} and V_{CCIO} are at valid operating levels and the device has been configured.

3. **Top sysIO Buffer Pairs**
   The sysIO buffer pairs in the top bank of the device consist of two single-ended output drivers and two single-ended input buffers (for ratioed inputs such as LVCMOS and LVTTL). The I/O pairs on the top also have differential and referenced I/O buffers. Half of the sysIO buffer pairs on the top edge have true differential outputs. The sysIO buffer pair comprising of the A and B PIOs in every PIC on the top edge have a differential output driver. The referenced input buffer can also be configured as a differential input buffer.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCIO0} have reached V_{PORUP} level defined in the Power-On-Reset Voltage table in the DC and Switching Characteristics section of this data sheet. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-down to GND (some pins such as PROGRAMN and the JTAG pins have weak pull-up to V_{CCIO} as the default functionality). The I/O pins will maintain the blank configuration until V_{CC} and V_{CCIO} (for I/O banks containing configuration I/Os) have reached V_{PORUP} levels at which time the I/Os will take on the user-configured settings only after a proper download/configuration.

Supported Standards

The MachXO2 sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL, and PCI. The buffer supports the LVTTL, PCI, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3 V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS, MLVDS and LVPECL output emulation is supported on all devices. The MachXO2-640U, MachXO2-1200/U and higher devices support on-chip LVDS output buffers on approximately 50% of the I/Os on the top bank. Differential receivers for LVDS, BLVDS, MLVDS and LVPECL are supported on all banks of MachXO2 devices. PCI support is provided in the bottom bank of theMachXO2-640U, MachXO2-1200/U and higher density devices. Table 2-11 summarizes the I/O characteristics of the MachXO2 PLDs.

Tables 2-11 and 2-12 show the I/O standards (together with their supply and reference voltages) supported by the MachXO2 devices. For further information on utilizing the sysIO buffer to support a variety of standards please see TN1202, MachXO2 sysIO Usage Guide.

Table 2-11. I/O Support Device by Device

	MachXO2-256, MachXO2-640	MachXO2-640U, MachXO2-1200	MachXO2-1200U MachXO2-2000/U, MachXO2-4000, MachXO2-7000
Number of I/O Banks	4	4	6
Type of Input Buffers	Single-ended (all I/O banks) Differential Receivers (all I/O banks)	Single-ended (all I/O banks) Differential Receivers (all I/O banks) Differential input termination (bottom side)	Single-ended (all I/O banks) Differential Receivers (all I/O banks) Differential input termination (bottom side)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O banks)	Single-ended buffers with complementary outputs (all I/O banks) Differential buffers with true LVDS outputs (50% on top side)	Single-ended buffers with complementary outputs (all I/O banks) Differential buffers with true LVDS outputs (50% on top side)
Differential Output Emulation Capability	All I/O banks	All I/O banks	All I/O banks
PCI Clamp Support	No	Clamp on bottom side only	Clamp on bottom side only

Table 2-12. Supported Input Standards

	VCCIO (Typ.)				
Input Standard	**3.3 V**	**2.5 V**	**1.8 V**	**1.5**	**1.2 V**
Single-Ended Interfaces					
LVTTL	✓	✓[2]	✓[2]	✓[2]	
LVCMOS33	✓	✓[2]	✓[2]	✓[2]	
LVCMOS25	✓[2]	✓	✓[2]	✓[2]	
LVCMOS18	✓[2]	✓[2]	✓	✓[2]	
LVCMOS15	✓[2]	✓[2]	✓[2]	✓	✓[2]
LVCMOS12	✓[2]	✓[2]	✓[2]	✓[2]	✓
PCI[1]	✓				
SSTL18 (Class I, Class II)	✓	✓	✓		
SSTL25 (Class I, Class II)	✓	✓			
HSTL18 (Class I, Class II)	✓	✓	✓		
Differential Interfaces					
LVDS	✓	✓			
BLVDS, MVDS, LVPECL, RSDS	✓	✓			
MIPI[3]	✓	✓			
Differential SSTL18 Class I, II	✓	✓	✓		
Differential SSTL25 Class I, II	✓	✓			
Differential HSTL18 Class I, II	✓	✓	✓		

1. Bottom banks of MachXO2-640U, MachXO2-1200/U and higher density devices only.
2. Reduced functionality. Refer to TN1202, MachXO2 sysIO Usage Guide for more detail.
3. These interfaces can be emulated with external resistors in all devices.

Table 2-13. Supported Output Standards

Output Standard	V_{CCIO} (Typ.)
Single-Ended Interfaces	
LVTTL	3.3
LVCMOS33	3.3
LVCMOS25	2.5
LVCMOS18	1.8
LVCMOS15	1.5
LVCMOS12	1.2
LVCMOS33, Open Drain	—
LVCMOS25, Open Drain	—
LVCMOS18, Open Drain	—
LVCMOS15, Open Drain	—
LVCMOS12, Open Drain	—
PCI33	3.3
SSTL25 (Class I)	2.5
SSTL18 (Class I)	1.8
HSTL18(Class I)	1.8
Differential Interfaces	
LVDS[1, 2]	2.5, 3.3
BLVDS, MLVDS, RSDS [2]	2.5
LVPECL[2]	3.3
MIPI[2]	2.5
Differential SSTL18	1.8
Differential SSTL25	2.5
Differential HSTL18	1.8

1. MachXO2-640U, MachXO2-1200/U and larger devices have dedicated LVDS buffers.
2. These interfaces can be emulated with external resistors in all devices.

sysIO Buffer Banks

The numbers of banks vary between the devices of this family. MachXO2-1200U, MachXO2-2000/U and higher density devices have six I/O banks (one bank on the top, right and bottom side and three banks on the left side). The MachXO2-1200 and lower density devices have four banks (one bank per side). Figures 2-18 and 2-19 show the sysIO banks and their associated supplies for all devices.

Figure 2-18. MachXO2-1200U, MachXO2-2000/U, MachXO2-4000 and MachXO2-7000 Banks

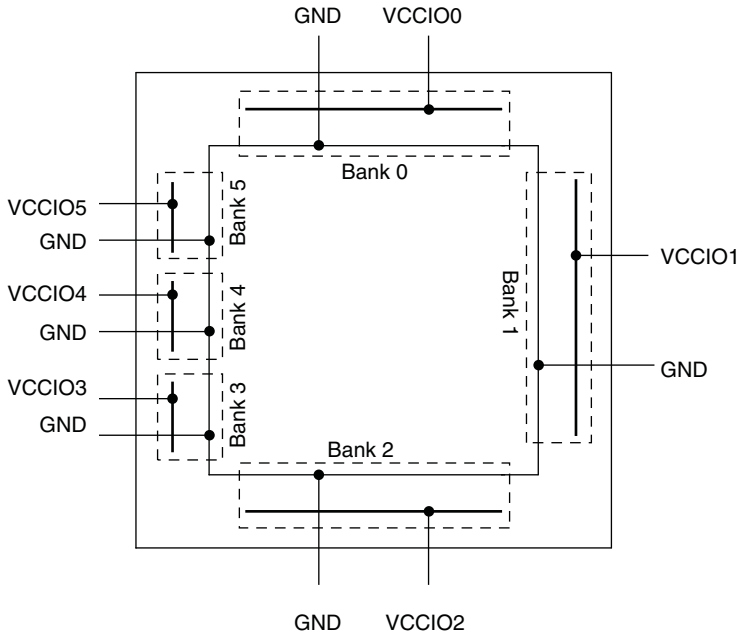
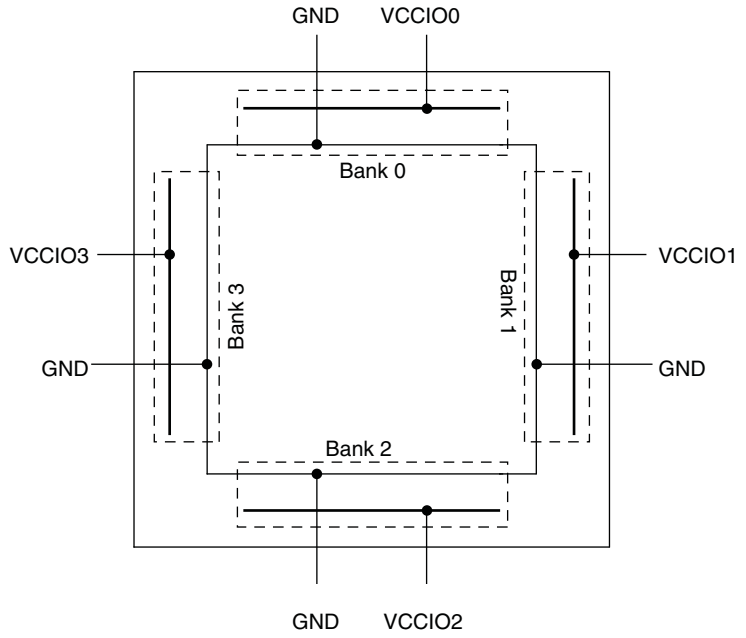


Figure 2-19. MachXO2-256, MachXO2-640/U and MachXO2-1200 Banks



Hot Socketing

The MachXO2 devices have been carefully designed to ensure predictable behavior during power-up and power-down. Leakage into I/O pins is controlled to within specified limits. This allows for easy integration with the rest of the system. These capabilities make the MachXO2 ideal for many multiple power supply and hot-swap applications.

On-chip Oscillator

Every MachXO2 device has an internal CMOS oscillator. The oscillator output can be routed as a clock to the clock tree or as a reference clock to the sysCLOCK PLL using general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit and a user input to enable/disable the oscillator. The oscillator frequency ranges from 2.08 MHz to 133 MHz. The software default value of the Master Clock (MCLK) is nominally 2.08 MHz. When a different MCLK is selected during the design process, the following sequence takes place:

1. Device powers up with a nominal MCLK frequency of 2.08 MHz.
2. During configuration, users select a different master clock frequency.
3. The MCLK frequency changes to the selected frequency once the clock configuration bits are received.
4. If the user does not select a master clock frequency, then the configuration bitstream defaults to the MCLK frequency of 2.08 MHz.

Table 2-14 lists all the available MCLK frequencies.

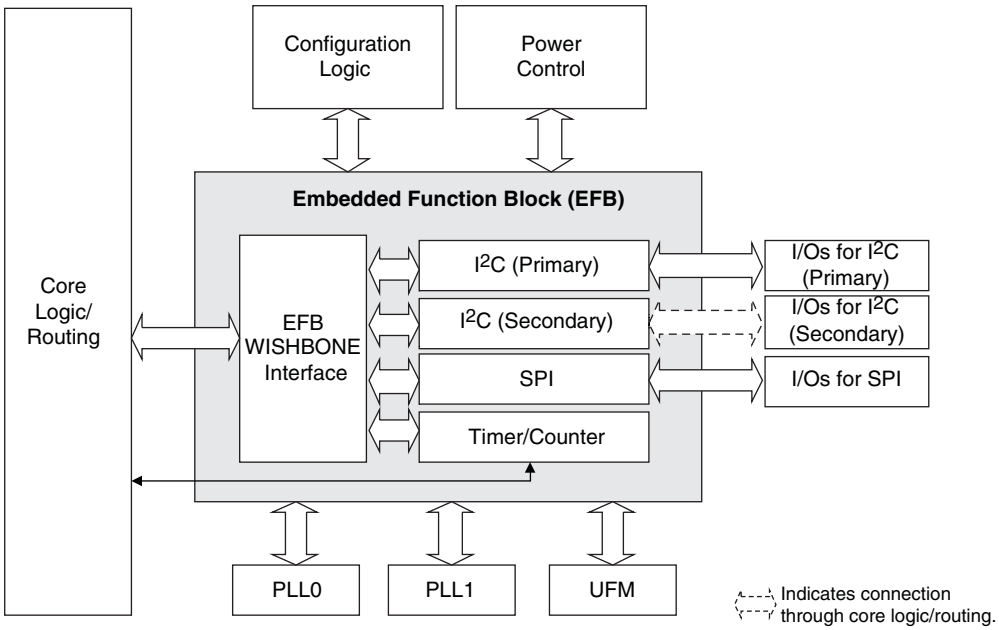
Table 2-14. Available MCLK Frequencies

MCLK (MHz, Nominal)	MCLK (MHz, Nominal)	MCLK (MHz, Nominal)
2.08 (default)	9.17	33.25
2.46	10.23	38
3.17	13.3	44.33
4.29	14.78	53.2
5.54	20.46	66.5
7	26.6	88.67
8.31	29.56	133

Embedded Hardened IP Functions and User Flash Memory

All MachXO2 devices provide embedded hardened functions such as SPI, I^2C and Timer/Counter. MachXO2-640/U and higher density devices also provide User Flash Memory (UFM). These embedded blocks interface through the WISHBONE interface with routing as shown in Figure 2-20.

Figure 2-20. Embedded Function Block Interface



Hardened I²C IP Core

Every MachXO2 device contains two I²C IP cores. These are the primary and secondary I²C IP cores. Either of the two cores can be configured either as an I²C master or as an I²C slave. The only difference between the two IP cores is that the primary core has pre-assigned I/O pins whereas users can assign I/O pins for the secondary core.

When the IP core is configured as a master it will be able to control other devices on the I²C bus through the interface. When the core is configured as the slave, the device will be able to provide I/O expansion to an I²C Master. The I²C cores support the following functionality:

- Master and Slave operation
- 7-bit and 10-bit addressing
- Multi-master arbitration support
- Up to 400 kHz data transfer speed
- General call support
- Interface to custom logic through 8-bit WISHBONE interface

Figure 2-21. I²C Core Block Diagram

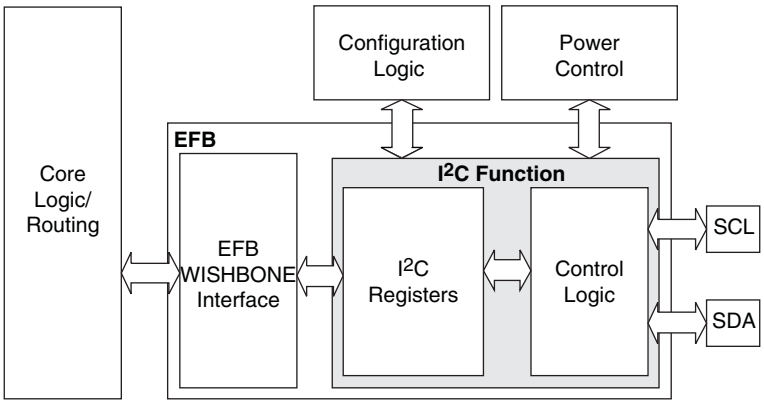


Table 2-15 describes the signals interfacing with the I²C cores.

Table 2-15. I²C Core Signal Description

Signal Name	I/O	Description
i2c_scl	Bi-directional	Bi-directional clock line of the I²C core. The signal is an output if the I²C core is in master mode. The signal is an input if the I²C core is in slave mode. MUST be routed directly to the pre-assigned I/O of the chip. Refer to the Pinout Information section of this document for detailed pad and pin locations of I²C ports in each MachXO2 device.
i2c_sda	Bi-directional	Bi-directional data line of the I²C core. The signal is an output when data is transmitted from the I²C core. The signal is an input when data is received into the I²C core. MUST be routed directly to the pre-assigned I/O of the chip. Refer to the Pinout Information section of this document for detailed pad and pin locations of I²C ports in each MachXO2 device.
i2c_irqo	Output	Interrupt request output signal of the I²C core. The intended usage of this signal is for it to be connected to the WISHBONE master controller (i.e. a microcontroller or state machine) and request an interrupt when a specific condition is met. These conditions are described with the I²C register definitions.
cfg_wake	Output	Wake-up signal – To be connected only to the power module of the MachXO2 device. The signal is enabled only if the “Wakeup Enable” feature has been set within the EFB GUI, I²C Tab.
cfg_stdby	Output	Stand-by signal – To be connected only to the power module of the MachXO2 device. The signal is enabled only if the “Wakeup Enable” feature has been set within the EFB GUI, I²C Tab.

Hardened SPI IP Core

Every MachXO2 device has a hard SPI IP core that can be configured as a SPI master or slave. When the IP core is configured as a master it will be able to control other SPI enabled chips connected to the SPI bus. When the core is configured as the slave, the device will be able to interface to an external SPI master. The SPI IP core on MachXO2 devices supports the following functions:

- Configurable Master and Slave modes
- Full-Duplex data transfer
- Mode fault error flag with CPU interrupt capability
- Double-buffered data register
- Serial clock with programmable polarity and phase
- LSB First or MSB First Data Transfer
- Interface to custom logic through 8-bit WISHBONE interface

There are some limitations on the use of the hardened user SPI. These are defined in the following technical notes:

- TN1087, Minimizing System Interruption During Configuration Using TransFR Technology (Appendix B)
- TN1205, Using User Flash Memory and Hardened Control Functions in MachXO2 Devices

Figure 2-22. SPI Core Block Diagram

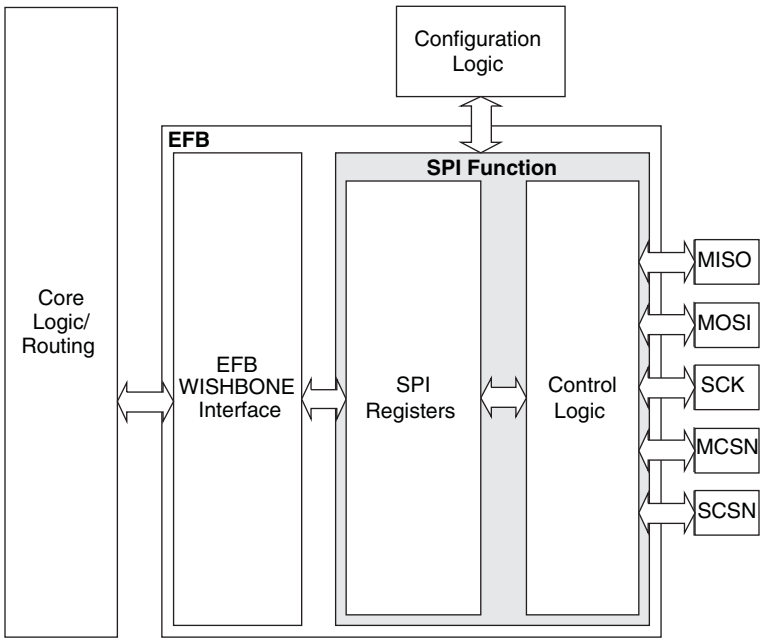


Table 2-16 describes the signals interfacing with the SPI cores.

Table 2-16. SPI Core Signal Description

Signal Name	I/O	Master/Slave	Description
spi_csn[0]	O	Master	SPI master chip-select output
spi_csn[1..7]	O	Master	Additional SPI chip-select outputs (total up to eight slaves)
spi_scsn	I	Slave	SPI slave chip-select input
spi_irq	O	Master/Slave	Interrupt request
spi_clk	I/O	Master/Slave	SPI clock. Output in master mode. Input in slave mode.
spi_miso	I/O	Master/Slave	SPI data. Input in master mode. Output in slave mode.
spi_mosi	I/O	Master/Slave	SPI data. Output in master mode. Input in slave mode.
ufm_sn	I	Slave	Configuration Slave Chip Select (active low), dedicated for selecting the User Flash Memory (UFM).
cfg_stdby	O	Master/Slave	Stand-by signal – To be connected only to the power module of the MachXO2 device. The signal is enabled only if the “Wakeup Enable” feature has been set within the EFB GUI, SPI Tab.
cfg_wake	O	Master/Slave	Wake-up signal – To be connected only to the power module of the MachXO2 device. The signal is enabled only if the “Wakeup Enable” feature has been set within the EFB GUI, SPI Tab.

Hardened Timer/Counter

MachXO2 devices provide a hard Timer/Counter IP core. This Timer/Counter is a general purpose, bi-directional, 16-bit timer/counter module with independent output compare units and PWM support. The Timer/Counter supports the following functions:

- Supports the following modes of operation:
  — Watchdog timer
  — Clear timer on compare match
  — Fast PWM
  — Phase and Frequency Correct PWM
- Programmable clock input source
- Programmable input clock prescaler
- One static interrupt output to routing
- One wake-up interrupt to on-chip standby mode controller.
- Three independent interrupt sources: overflow, output compare match, and input capture
- Auto reload
- Time-stamping support on the input capture unit
- Waveform generation on the output
- Glitch-free PWM waveform generation with variable PWM period
- Internal WISHBONE bus access to the control and status registers
- Stand-alone mode with preloaded control registers and direct reset input

Figure 2-23. Timer/Counter Block Diagram

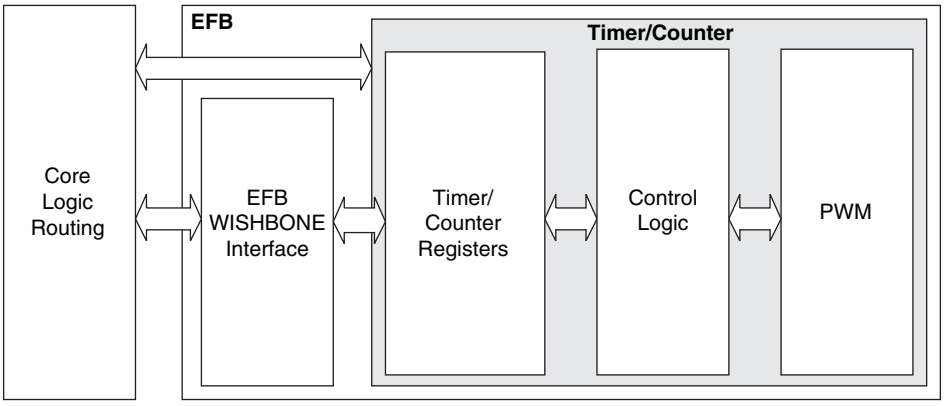


Table 2-17. Timer/Counter Signal Description

Port	I/O	Description
tc_clki	I	Timer/Counter input clock signal
tc_rstn	I	Register tc_rstn_ena is preloaded by configuration to always keep this pin enabled
tc_ic	I	Input capture trigger event, applicable for non-pwm modes with WISHBONE interface. If enabled, a rising edge of this signal will be detected and synchronized to capture tc_cnt value into tc_icr for time-stamping.
tc_int	O	Without WISHBONE – Can be used as overflow flag With WISHBONE – Controlled by three IRQ registers
tc_oc	O	Timer counter output signal

For more details on these embedded functions, please refer to TN1205, Using User Flash Memory and Hardened Control Functions in MachXO2 Devices.

User Flash Memory (UFM)

MachXO2-640/U and higher density devices provide a User Flash Memory block, which can be used for a variety of applications including storing a portion of the configuration image, initializing EBRs, to store PROM data or, as a general purpose user Flash memory. The UFM block connects to the device core through the embedded function block WISHBONE interface. Users can also access the UFM block through the JTAG, I^2C and SPI interfaces of the device. The UFM block offers the following features:

- Non-volatile storage up to 256 kbits
- 100K write cycles
- Write access is performed page-wise; each page has 128 bits (16 bytes)
- Auto-increment addressing
- WISHBONE interface

For more information on the UFM, please refer to TN1205, Using User Flash Memory and Hardened Control Functions in MachXO2 Devices.

Standby Mode and Power Saving Options

MachXO2 devices are available in three options for maximum flexibility: ZE, HC and HE devices. The ZE devices have ultra low static and dynamic power consumption. These devices use a 1.2 V core voltage that further reduces power consumption. The HC and HE devices are designed to provide high performance. The HC devices have a built-in voltage regulator to allow for 2.5 V V_{CC} and 3.3 V V_{CC} while the HE devices operate at 1.2 V V_{CC}.

MachXO2 devices have been designed with features that allow users to meet the static and dynamic power requirements of their applications by controlling various device subsystems such as the bandgap, power-on-reset circuitry, I/O bank controllers, power guard, on-chip oscillator, PLLs, etc. In order to maximize power savings, MachXO2 devices support an ultra low power Stand-by mode. While most of these features are available in all three device types, these features are mainly intended for use with MachXO2 ZE devices to manage power consumption.

In the stand-by mode the MachXO2 devices are powered on and configured. Internal logic, I/Os and memories are switched on and remain operational, as the user logic waits for an external input. The device enters this mode when the standby input of the standby controller is toggled or when an appropriate I^2C or JTAG instruction is issued by an external master. Various subsystems in the device such as the band gap, power-on-reset circuitry etc can be configured such that they are automatically turned “off” or go into a low power consumption state to save power when the device enters this state. Note that the MachXO2 devices are powered on when in standby mode and all power supplies should remain in the Recommended Operating Conditions.

Table 2-18. MachXO2 Power Saving Features Description

Device Subsystem	Feature Description
Bandgap	The bandgap can be turned off in standby mode. When the Bandgap is turned off, analog circuitry such as the POR, PLLs, on-chip oscillator, and referenced and differential I/O buffers are also turned off. Bandgap can only be turned off for 1.2 V devices.
Power-On-Reset (POR)	The POR can be turned off in standby mode. This monitors VCC levels. In the event of unsafe V_{CC} drops, this circuit reconfigures the device. When the POR circuitry is turned off, limited power detector circuitry is still active. This option is only recommended for applications in which the power supply rails are reliable.
On-Chip Oscillator	The on-chip oscillator has two power saving features. It may be switched off if it is not needed in your design. It can also be turned off in Standby mode.
PLL	Similar to the on-chip oscillator, the PLL also has two power saving features. It can be statically switched off if it is not needed in a design. It can also be turned off in Standby mode. The PLL will wait until all output clocks from the PLL are driven low before powering off.
I/O Bank Controller	Referenced and differential I/O buffers (used to implement standards such as HSTL, SSTL and LVDS) consume more than ratioed single-ended I/Os such as LVCMOS and LVTTL. The I/O bank controller allows the user to turn these I/Os off dynamically on a per bank selection.
Dynamic Clock Enable for Primary Clock Nets	Each primary clock net can be dynamically disabled to save power.
Power Guard	Power Guard is a feature implemented in input buffers. This feature allows users to switch off the input buffer when it is not needed. This feature can be used in both clock and data paths. Its biggest impact is that in the standby mode it can be used to switch off clock inputs that are distributed using general routing resources.

For more details on the standby mode refer to TN1198, Power Estimation and Management for MachXO2 Devices.

Power On Reset

MachXO2 devices have power-on reset circuitry to monitor V_{CCINT} and V_{CCIO} voltage levels during power-up and operation. At power-up, the POR circuitry monitors V_{CCINT} and V_{CCIO0} (controls configuration) voltage levels. It then triggers download from the on-chip configuration Flash memory after reaching the V_{PORUP} level specified in the Power-On-Reset Voltage table in the DC and Switching Characteristics section of this data sheet. For devices without voltage regulators (ZE and HE devices), V_{CCINT} is the same as the V_{CC} supply voltage. For devices with voltage regulators (HC devices), V_{CCINT} is regulated from the V_{CC} supply voltage. From this voltage reference, the time taken for configuration and entry into user mode is specified as Flash Download Time ($t_{REFRESH}$) in the DC and Switching Characteristics section of this data sheet. Before and during configuration, the I/Os are held in tri-state. I/Os are released to user functionality once the device has finished configuration. Note that for HC devices, a separate POR circuit monitors external V_{CC} voltage in addition to the POR circuit that monitors the internal post-regulated power supply voltage level.

Once the device enters into user mode, the POR circuitry can optionally continue to monitor V_{CCINT} levels. If V_{CCINT} drops below $V_{PORDNBG}$ level (with the bandgap circuitry switched on) or below $V_{PORDNSRAM}$ level (with the bandgap circuitry switched off to conserve power) device functionality cannot be guaranteed. In such a situation the POR issues a reset and begins monitoring the V_{CCINT} and V_{CCIO} voltage levels. $V_{PORDNBG}$ and $V_{PORDNSRAM}$ are both specified in the Power-On-Reset Voltage table in the DC and Switching Characteristics section of this data sheet.

Note that once a ZE or HE device enters user mode, users can switch off the bandgap to conserve power. When the bandgap circuitry is switched off, the POR circuitry also shuts down. The device is designed such that a minimal, low power POR circuit is still operational (this corresponds to the $V_{PORDNSRAM}$ reset point described in the paragraph above). However this circuit is not as accurate as the one that operates when the bandgap is switched on. The low power POR circuit emulates an SRAM cell and is biased to trip before the vast majority of SRAM cells flip. If users are concerned about the V_{CC} supply dropping below V_{CC} (min) they should not shut down the bandgap or POR circuit.

Configuration and Testing

This section describes the configuration and testing features of the MachXO2 family.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO2 devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with V_{CCIO} Bank 0 and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, see AN8066, Boundary Scan Testability with Lattice sysIO Capability and TN1087, Minimizing System Interruption During Configuration Using TransFR Technology.

Device Configuration

All MachXO2 devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration and the sysCONFIG port which supports serial configuration through I^2C or SPI. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In-System Configuration specification. There are various ways to configure a MachXO2 device:

1. Internal Flash Download
2. JTAG
3. Standard Serial Peripheral Interface (Master SPI mode) – interface to boot PROM memory
4. System microprocessor to drive a serial slave SPI port (SSPI mode)
5. Standard I^2C Interface to system microprocessor

Upon power-up, the configuration SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port. Optionally the device can run a CRC check upon entering the user mode. This will ensure that the device was configured correctly.

The sysCONFIG port has 10 dual-function pins which can be used as general purpose I/Os if they are not required for configuration. See TN1204, MachXO2 Programming and Configuration Usage Guide for more information about using the dual-use pins as general purpose I/Os.

Lattice design software uses proprietary compression technology to compress bit-streams for use in MachXO2 devices. Use of this technology allows Lattice to provide a lower cost solution. In the unlikely event that this technology is unable to compress bitstreams to fit into the amount of on-chip Flash memory, there are a variety of techniques that can be utilized to allow the bitstream to fit in the on-chip Flash memory. For more details, refer to TN1204, MachXO2 Programming and Configuration Usage Guide.

The Test Access Port (TAP) has five dual purpose pins (TDI, TDO, TMS, TCK and JTAGENB). These pins are dual function pins - TDI, TDO, TMS and TCK can be used as general purpose I/O if desired. For more details, refer to TN1204, MachXO2 Programming and Configuration Usage Guide.

TransFR (Transparent Field Reconfiguration)
TransFR is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a simple push-button solution. For more details refer to TN1087, Minimizing System Interruption During Configuration Using TransFR Technology for details.

When implementing background programming of the on-chip Flash, care must be taken for the operation of the PLL. For devices that have two PLLs (XO2-2000U, -4000 and -7000), the system must put the RPLL (Right-side PLL) in reset state during the background Flash programming. More detailed description can be found in TN1204, MachXO2 Programming and Configuration Usage Guide.

Security and One-Time Programmable Mode (OTP)
For applications where security is important, the lack of an external bitstream provides a solution that is inherently more secure than SRAM-based FPGAs. This is further enhanced by device locking. MachXO2 devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile Flash memory spaces. The device can be in one of two modes:

1. Unlocked – Readback of the SRAM configuration and non-volatile Flash memory spaces is allowed.

2. Permanently Locked – The device is permanently locked.

Once set, the only way to clear the security bits is to erase the device. To further complement the security of the device, a One Time Programmable (OTP) mode is available. Once the device is set in this mode it is not possible to erase or re-program the Flash and SRAM OTP portions of the device. For more details, refer to TN1204, MachXO2 Programming and Configuration Usage Guide.

Dual Boot
MachXO2 devices can optionally boot from two patterns, a primary bitstream and a golden bitstream. If the primary bitstream is found to be corrupt while being downloaded into the SRAM, the device shall then automatically re-boot from the golden bitstream. Note that the primary bitstream must reside in the on-chip Flash. The golden image MUST reside in an external SPI Flash. For more details, refer to TN1204, MachXO2 Programming and Configuration Usage Guide.

Soft Error Detection
The SED feature is a CRC check of the SRAM cells after the device is configured. This check ensures that the SRAM cells were configured successfully. This feature is enabled by a configuration bit option. The Soft Error Detection can also be initiated in user mode via an input to the fabric. The clock for the Soft Error Detection circuit is generated using a dedicated divider. The undivided clock from the on-chip oscillator is the input to this divider. For low power applications users can switch off the Soft Error Detection circuit. For more details, refer to TN1206, MachXO2 Soft Error Detection Usage Guide.

TraceID

Each MachXO2 device contains a unique (per device), TraceID that can be used for tracking purposes or for IP security applications. The TraceID is 64 bits long. Eight out of 64 bits are user-programmable, the remaining 56 bits are factory-programmed. The TraceID is accessible through the EFB WISHBONE interface and can also be accessed through the SPI, I^2C, or JTAG interfaces.

Density Shifting

The MachXO2 family has been designed to enable density migration within the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density devices to higher density devices. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case. When migrating from lower to higher density or higher to lower density, ensure to review all the power supplies and NC pins of the chosen devices. For more details refer to the MachXO2 migration files.

MachXO2 Family Data Sheet DC and Switching Characteristics

March 2017 Data Sheet DS1035

Absolute Maximum Ratings[1, 2, 3]

	MachXO2 ZE/HE (1.2 V)	MachXO2 HC (2.5 V / 3.3 V)
Supply Voltage V_{CC}	–0.5 V to 1.32 V	–0.5 V to 3.75 V
Output Supply Voltage V_{CCIO}	–0.5 V to 3.75 V	–0.5 V to 3.75 V
I/O Tri-state Voltage Applied[4, 5]	–0.5 V to 3.75 V	–0.5 V to 3.75 V
Dedicated Input Voltage Applied[4]	–0.5 V to 3.75 V	–0.5 V to 3.75 V
Storage Temperature (Ambient)	–55 °C to 125 °C	–55 °C to 125 °C
Junction Temperature (T_J)	–40 °C to 125 °C	–40 °C to 125 °C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of –2 V to (V_{IHMAX} + 2) volts is permitted for a duration of <20 ns.
5. The dual function I^2C pins SCL and SDA are limited to –0.25 V to 3.75 V or to –0.3 V with a duration of <20 ns.

Recommended Operating Conditions[1]

Symbol	Parameter	Min.	Max.	Units
V_{CC}[1]	Core Supply Voltage for 1.2 V Devices	1.14	1.26	V
	Core Supply Voltage for 2.5 V / 3.3 V Devices	2.375	3.6	V
V_{CCIO}[1, 2, 3]	I/O Driver Supply Voltage	1.14	3.6	V
t_{JCOM}	Junction Temperature Commercial Operation	0	85	°C
t_{JIND}	Junction Temperature Industrial Operation	–40	100	°C

1. Like power supplies must be tied together. For example, if V_{CCIO} and V_{CC} are both the same voltage, they must also be the same supply.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CCIO} pins of unused I/O banks should be connected to the V_{CC} power supply on boards.

Power Supply Ramp Rates[1]

Symbol	Parameter	Min.	Typ.	Max.	Units
t_{RAMP}	Power supply ramp rates for all power supplies.	0.01	—	100	V/ms

1. Assumes monotonic ramp rates.

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Power-On-Reset Voltage Levels[1, 2, 3, 4, 5]

Symbol	Parameter	Min.	Typ.	Max.	Units
V_{PORUP}	Power-On-Reset ramp up trip point (band gap based circuit monitoring V_{CCINT} and V_{CCIO0})	0.9	—	1.06	V
$V_{PORUPEXT}$	Power-On-Reset ramp up trip point (band gap based circuit monitoring external V_{CC} power supply)	1.5	—	2.1	V
$V_{PORDNBG}$	Power-On-Reset ramp down trip point (band gap based circuit monitoring V_{CCINT})	0.75	—	0.93	V
$V_{PORDNBGEXT}$	Power-On-Reset ramp down trip point (band gap based circuit monitoring V_{CC})	0.98	—	1.33	V
$V_{PORDNSRAM}$	Power-On-Reset ramp down trip point (SRAM based circuit monitoring V_{CCINT})	—	0.6	—	V
$V_{PORDNSRAMEXT}$	Power-On-Reset ramp down trip point (SRAM based circuit monitoring V_{CC})	—	0.96	—	V

1. These POR trip points are only provided for guidance. Device operation is only characterized for power supply voltages specified under recommended operating conditions.
2. For devices without voltage regulators V_{CCINT} is the same as the V_{CC} supply voltage. For devices with voltage regulators, V_{CCINT} is regulated from the V_{CC} supply voltage.
3. Note that V_{PORUP} (min.) and $V_{PORDNBG}$ (max.) are in different process corners. For any given process corner $V_{PORDNBG}$ (max.) is always 12.0 mV below V_{PORUP} (min.).
4. $V_{PORUPEXT}$ is for HC devices only. In these devices a separate POR circuit monitors the external V_{CC} power supply.
5. V_{CCIO0} does not have a Power-On-Reset ramp down trip point. V_{CCIO0} must remain within the Recommended Operating Conditions to ensure proper operation.

Programming/Erase Specifications

Symbol	Parameter	Min.	Max.[1]	Units
$N_{PROGCYC}$	Flash Programming cycles per $t_{RETENTION}$	—	10,000	Cycles
	Flash functional programming cycles	—	100,000	
$t_{RETENTION}$	Data retention at 100 °C junction temperature	10	—	Years
	Data retention at 85 °C junction temperature	20	—	

1. Maximum Flash memory reads are limited to 7.5E13 cycles over the lifetime of the product.

Hot Socketing Specifications[1, 2, 3]

Symbol	Parameter	Condition	Max.	Units
I_{DK}	Input or I/O leakage Current	$0 < V_{IN} < V_{IH}$ (MAX)	+/–1000	µA

1. Insensitive to sequence of V_{CC} and V_{CCIO}. However, assumes monotonic rise/fall rates for V_{CC} and V_{CCIO}.
2. $0 < V_{CC} < V_{CC}$ (MAX), $0 < V_{CCIO} < V_{CCIO}$ (MAX).
3. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}.

ESD Performance

Please refer to the MachXO2 Product Family Qualification Summary for complete qualification data, including ESD performance.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 4]	Input or I/O Leakage	Clamp OFF and $V_{CCIO} < V_{IN} < V_{IH}$ (MAX)	—	—	+175	µA
		Clamp OFF and $V_{IN} = V_{CCIO}$	–10	—	10	µA
		Clamp OFF and V_{CCIO} –0.97 V < V_{IN} < V_{CCIO}	–175	—	—	µA
		Clamp OFF and 0 V < V_{IN} < V_{CCIO} –0.97 V	—	—	10	µA
		Clamp OFF and V_{IN} = GND	—	—	10	µA
		Clamp ON and 0 V < V_{IN} < V_{CCIO}	—	—	10	µA
I_{PU}	I/O Active Pull-up Current	0 < V_{IN} < 0.7 V_{CCIO}	–30	—	-309	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) < V_{IN} < V_{CCIO}	30	—	305	µA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	–30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	0 ≤ V_{IN} ≤ V_{CCIO}	—	—	305	µA
I_{BHHO}	Bus Hold High Overdrive current	0 ≤ V_{IN} ≤ V_{CCIO}	—	—	–309	µA
V_{BHT}[3]	Bus Hold Trip Points		V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3 V, 2.5 V, 1.8 V, 1.5 V, 1.2 V, V_{CC} = Typ., V_{IO} = 0 to V_{IH} (MAX)	3	5	9	pF
C2	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3 V, 2.5 V, 1.8 V, 1.5 V, 1.2 V, V_{CC} = Typ., V_{IO} = 0 to V_{IH} (MAX)	3	5.5	7	pF
V_{HYST}	Hysteresis for Schmitt Trigger Inputs[5]	V_{CCIO} = 3.3 V, Hysteresis = Large	—	450	—	mV
		V_{CCIO} = 2.5 V, Hysteresis = Large	—	250	—	mV
		V_{CCIO} = 1.8 V, Hysteresis = Large	—	125	—	mV
		V_{CCIO} = 1.5 V, Hysteresis = Large	—	100	—	mV
		V_{CCIO} = 3.3 V, Hysteresis = Small	—	250	—	mV
		V_{CCIO} = 2.5 V, Hysteresis = Small	—	150	—	mV
		V_{CCIO} = 1.8 V, Hysteresis = Small	—	60	—	mV
		V_{CCIO} = 1.5 V, Hysteresis = Small	—	40	—	mV

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25 °C, f = 1.0 MHz.
3. Please refer to V_{IL} and V_{IH} in the sysIO Single-Ended DC Electrical Characteristics table of this document.
4. When V_{IH} is higher than V_{CCIO}, a transient current typically of 30 ns in duration or less with a peak current of 6 mA can occur on the high-to-low transition. For true LVDS output pins in MachXO2-640U, MachXO2-1200/U and larger devices, V_{IH} must be less than or equal to V_{CCIO}.
5. With bus keeper circuit turned on. For more details, refer to TN1202, MachXO2 sysIO Usage Guide.

Static Supply Current – ZE Devices[1, 2, 3, 6]

Symbol	Parameter	Device	Typ.[4]	Units
I_{CC}	Core Power Supply	LCMXO2-256ZE	18	µA
		LCMXO2-640ZE	28	µA
		LCMXO2-1200ZE	56	µA
		LCMXO2-2000ZE	80	µA
		LCMXO2-4000ZE	124	µA
		LCMXO2-7000ZE	189	µA
I_{CCIO}	Bank Power Supply[5] V_{CCIO} = 2.5 V	All devices	1	µA

1. For further information on supply current, please refer to TN1198, Power Estimation and Management for MachXO2 Devices.
2. Assumes blank pattern with the following characteristics: all outputs are tri-stated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND, on-chip oscillator is off, on-chip PLL is off. To estimate the impact of turning each of these items on, please refer to the following table or for more detail with your specific design use the Power Calculator tool.
3. Frequency = 0 MHz.
4. T_J = 25 °C, power supplies at nominal voltage.
5. Does not include pull-up/pull-down.
6. To determine the MachXO2 peak start-up current data, use the Power Calculator tool.

Static Power Consumption Contribution of Different Components – ZE Devices

The table below can be used for approximating static power consumption. For a more accurate power analysis for your design please use the Power Calculator tool.

Symbol	Parameter	Typ.	Units
I_{DCBG}	Bandgap DC power contribution	101	µA
I_{DCPOR}	POR DC power contribution	38	µA
$I_{DCIOBANKCONTROLLER}$	DC power contribution per I/O bank controller	143	µA

Static Supply Current – HC/HE Devices[1, 2, 3, 6]

Symbol	Parameter	Device	Typ.[4]	Units
I_{CC}	Core Power Supply	LCMXO2-256HC	1.15	mA
		LCMXO2-640HC	1.84	mA
		LCMXO2-640UHC	3.48	mA
		LCMXO2-1200HC	3.49	mA
		LCMXO2-1200UHC	4.80	mA
		LCMXO2-2000HC	4.80	mA
		LCMXO2-2000UHC	8.44	mA
		LCMXO2-4000HC	8.45	mA
		LCMXO2-7000HC	12.87	mA
		LCMXO2-2000HE	1.39	mA
		LCMXO2-4000HE	2.55	mA
		LCMXO2-7000HE	4.06	mA
I_{CCIO}	Bank Power Supply[5] V_{CCIO} = 2.5 V	All devices	0	mA

1. For further information on supply current, please refer to TN1198, Power Estimation and Management for MachXO2 Devices.
2. Assumes blank pattern with the following characteristics: all outputs are tri-stated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND, on-chip oscillator is off, on-chip PLL is off.
3. Frequency = 0 MHz.
4. T_J = 25 °C, power supplies at nominal voltage.
5. Does not include pull-up/pull-down.
6. To determine the MachXO2 peak start-up current data, use the Power Calculator tool.

Programming and Erase Flash Supply Current – HC/HE Devices[1, 2, 3, 4]

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO2-256HC	14.6	mA
		LCMXO2-640HC	16.1	mA
		LCMXO2-640UHC	18.8	mA
		LCMXO2-1200HC	18.8	mA
		LCMXO2-1200UHC	22.1	mA
		LCMXO2-2000HC	22.1	mA
		LCMXO2-2000UHC	26.8	mA
		LCMXO2-4000HC	26.8	mA
		LCMXO2-7000HC	33.2	mA
		LCMXO2-2000HE	18.3	mA
		LCMXO2-2000UHE	20.4	mA
		LCMXO2-4000HE	20.4	mA
		LCMXO2-7000HE	23.9	mA
I_{CCIO}	Bank Power Supply[6]	All devices	0	mA

1. For further information on supply current, please refer to TN1198, Power Estimation and Management for MachXO2 Devices.
2. Assumes all inputs are held at V_{CCIO} or GND and all outputs are tri-stated.
3. Typical user pattern.
4. JTAG programming is at 25 MHz.
5. T_J = 25 °C, power supplies at nominal voltage.
6. Per bank. V_{CCIO} = 2.5 V. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current – ZE Devices[1, 2, 3, 4]

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO2-256ZE	13	mA
		LCMXO2-640ZE	14	mA
		LCMXO2-1200ZE	15	mA
		LCMXO2-2000ZE	17	mA
		LCMXO2-4000ZE	18	mA
		LCMXO2-7000ZE	20	mA
I_{CCIO}	Bank Power Supply[6]	All devices	0	mA

1. For further information on supply current, please refer to TN1198, Power Estimation and Management for MachXO2 Devices.
2. Assumes all inputs are held at V_{CCIO} or GND and all outputs are tri-stated.
3. Typical user pattern.
4. JTAG programming is at 25 MHz.
5. TJ = 25 °C, power supplies at nominal voltage.
6. Per bank. V_{CCIO} = 2.5 V. Does not include pull-up/pull-down.

sysIO Recommended Operating Conditions

Standard	V_{CCIO} (V)			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.6	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.6	—	—	—
PCI[3]	3.135	3.3	3.6	—	—	—
SSTL25	2.375	2.5	2.625	1.15	1.25	1.35
SSTL18	1.71	1.8	1.89	0.833	0.9	0.969
HSTL18	1.71	1.8	1.89	0.816	0.9	1.08
LVCMOS25R33	3.135	3.3	3.6	1.1	1.25	1.4
LVCMOS18R33	3.135	3.3	3.6	0.75	0.9	1.05
LVCMOS18R25	2.375	2.5	2.625	0.75	0.9	1.05
LVCMOS15R33	3.135	3.3	3.6	0.6	0.75	0.9
LVCMOS15R25	2.375	2.5	2.625	0.6	0.75	0.9
LVCMOS12R33[4]	3.135	3.3	3.6	0.45	0.6	0.75
LVCMOS12R25[4]	2.375	2.5	2.625	0.45	0.6	0.75
LVCMOS10R33[4]	3.135	3.3	3.6	0.35	0.5	0.65
LVCMOS10R25[4]	2.375	2.5	2.625	0.35	0.5	0.65
LVDS25[1, 2]	2.375	2.5	2.625	—	—	—
LVDS33[1, 2]	3.135	3.3	3.6	—	—	—
LVPECL[1]	3.135	3.3	3.6	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—
RSDS[1]	2.375	2.5	2.625	—	—	—
SSTL18D	1.71	1.8	1.89	—	—	—
SSTL25D	2.375	2.5	2.625	—	—	—
HSTL18D	1.71	1.8	1.89	—	—	—

1. Inputs on-chip. Outputs are implemented with the addition of external resistors.
2. MachXO2-640U, MachXO2-1200/U and larger devices have dedicated LVDS buffers.
3. Input on the bottom bank of the MachXO2-640U, MachXO2-1200/U and larger devices only.
4. Supported only for inputs and BIDIs for all ZE devices, and –6 speed grade for HE and HC devices.

sysIO Single-Ended DC Electrical Characteristics[1, 2]

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} Max.[4] (mA)	I_{OH} Max.[4] (mA)
	Min. (V)[3]	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3 LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} – 0.4	4	–4
							8	–8
							12	–12
							16	–16
							24	–24
					0.2	V_{CCIO} – 0.2	0.1	–0.1
LVCMOS 2.5	–0.3	0.7	1.7	3.6	0.4	V_{CCIO} – 0.4	4	–4
							8	–8
							12	–12
							16	–16
					0.2	V_{CCIO} – 0.2	0.1	–0.1
LVCMOS 1.8	–0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} – 0.4	4	–4
							8	–8
							12	–12
					0.2	V_{CCIO} – 0.2	0.1	–0.1
LVCMOS 1.5	–0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} – 0.4	4	–4
							8	–8
					0.2	V_{CCIO} – 0.2	0.1	–0.1
LVCMOS 1.2	–0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} – 0.4	4	–2
							8	–6
					0.2	V_{CCIO} – 0.2	0.1	–0.1
PCI	–0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	–0.5
SSTL25 Class I	–0.3	V_{REF} – 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	8	8
SSTL25 Class II	–0.3	V_{REF} – 0.18	V_{REF} + 0.18	3.6	NA	NA	NA	NA
SSTL18 Class I	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	3.6	0.40	V_{CCIO} - 0.40	8	8
SSTL18 Class II	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	3.6	NA	NA	NA	NA
HSTL18 Class I	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.40	V_{CCIO} - 0.40	8	8
HSTL18 Class II	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	NA	NA	NA	NA
LVCMOS25R33	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	NA	NA	NA	NA
LVCMOS18R33	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	NA	NA	NA	NA
LVCMOS18R25	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	NA	NA	NA	NA
LVCMOS15R33	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	NA	NA	NA	NA
LVCMOS15R25	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	NA	NA	NA	NA
LVCMOS12R33	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.40	NA Open Drain	24, 16, 12, 8, 4	NA Open Drain
LVCMOS12R25	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.40	NA Open Drain	16, 12, 8, 4	NA Open Drain
LVCMOS10R33	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.40	NA Open Drain	24, 16, 12, 8, 4	NA Open Drain

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} Max.[4] (mA)	I_{OH} Max.[4] (mA)
	Min. (V)[3]	Max. (V)	Min. (V)	Max. (V)				
LVCMOS10R25	–0.3	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.40	NA Open Drain	16, 12, 8, 4	NA Open Drain

1. MachXO2 devices allow LVCMOS inputs to be placed in I/O banks where V_{CCIO} is different from what is specified in the applicable JEDEC specification. This is referred to as a ratioed input buffer. In a majority of cases this operation follows or exceeds the applicable JEDEC specification. The cases where MachXO2 devices do not meet the relevant JEDEC specification are documented in the table below.
2. MachXO2 devices allow for LVCMOS referenced I/Os which follow applicable JEDEC specifications. For more details about mixed mode operation please refer to please refer to TN1202, MachXO2 sysIO Usage Guide.
3. The dual function I^2C pins SCL and SDA are limited to a V_{IL} min of –0.25 V or to –0.3 V with a duration of <10 ns.
4. For electromigration, the average DC current sourced or sinked by I/O pads between two consecutive VCCIO or GND pad connections, or between the last VCCIO or GND in an I/O bank and the end of an I/O bank, as shown in the Logic Signal Connections table (also shown as I/O grouping) shall not exceed a maximum of n * 8 mA. “n” is the number of I/O pads between the two consecutive bank VCCIO or GND connections or between the last VCCIO and GND in a bank and the end of a bank. IO Grouping can be found in the Data Sheet Pin Tables, which can also be generated from the Lattice Diamond software.

Input Standard	V_{CCIO} (V)	V_{IL} Max. (V)
LVCMOS 33	1.5	0.685
LVCMOS 25	1.5	0.687
LVCMOS 18	1.5	0.655

sysIO Differential Electrical Characteristics

The LVDS differential output buffers are available on the top side of MachXO2-640U, MachXO2-1200/U and higher density devices in the MachXO2 PLD family.

LVDS

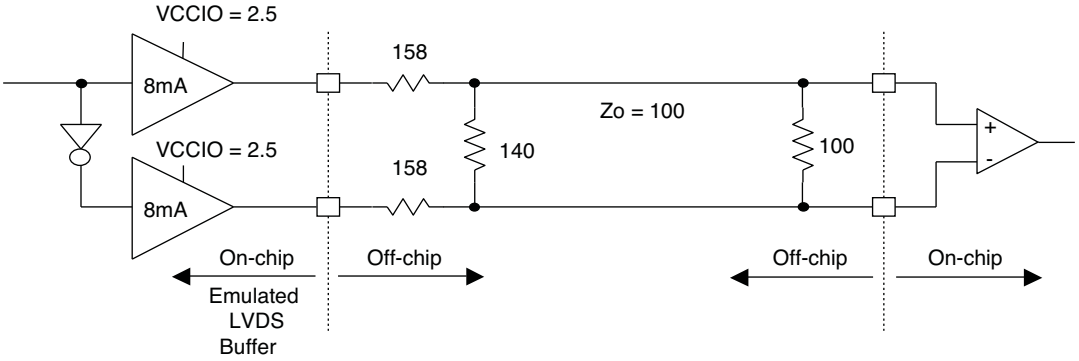
Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage	V_{CCIO} = 3.3 V	0	—	2.605	V
		V_{CCIO} = 2.5 V	0	—	2.05	V
V_{THD}	Differential Input Threshold		±100	—		mV
V_{CM}	Input Common Mode Voltage	V_{CCIO} = 3.3 V	0.05	—	2.6	V
		V_{CCIO} = 2.5 V	0.05	—	2.0	V
I_{IN}	Input current	Power on	—	—	±10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.375	—	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.90	1.025	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} + V_{OM})/2, R_T = 100 Ohm	1.125	1.20	1.395	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0 V driver outputs shorted	—	—	24	mA

LVDS Emulation

MachXO2 devices can support LVDS outputs via emulation (LVDS25E). The output is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

Figure 3-1. LVDS Using External Resistors (LVDS25E)



Note: All resistors are ±1%.

Table 3-1. LVDS25E DC Conditions

Over Recommended Operating Conditions

Parameter	Description	Typ.	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	158	Ohms
R_P	Driver parallel resistor	140	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100.5	Ohms
I_{DC}	DC output current	6.03	mA

BLVDS

The MachXO2 family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs. The input standard is supported by the LVDS differential input buffer. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example

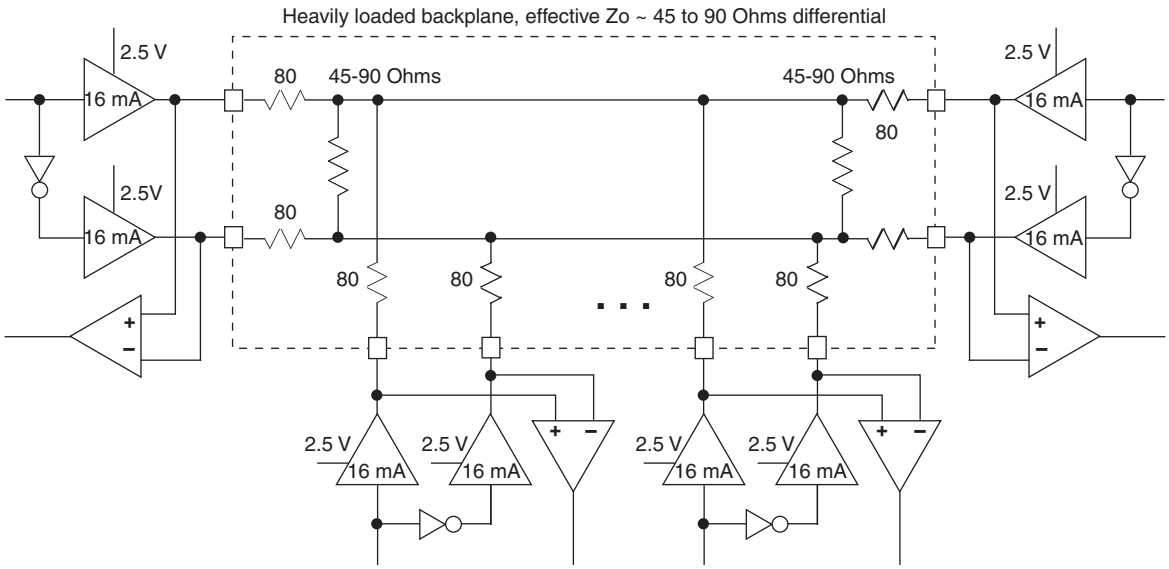


Table 3-2. BLVDS DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal		Units
		Zo = 45	Zo = 90	
Z_{OUT}	Output impedance	20	20	Ohms
R_S	Driver series resistance	80	80	Ohms
R_{TLEFT}	Left end termination	45	90	Ohms
R_{TRIGHT}	Right end termination	45	90	Ohms
V_{OH}	Output high voltage	1.376	1.480	V
V_{OL}	Output low voltage	1.124	1.020	V
V_{OD}	Output differential voltage	0.253	0.459	V
V_{CM}	Output common mode voltage	1.250	1.250	V
I_{DC}	DC output current	11.236	10.204	mA

1. For input buffer, see LVDS table.

LVPECL

The MachXO2 family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Differential LVPECL is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

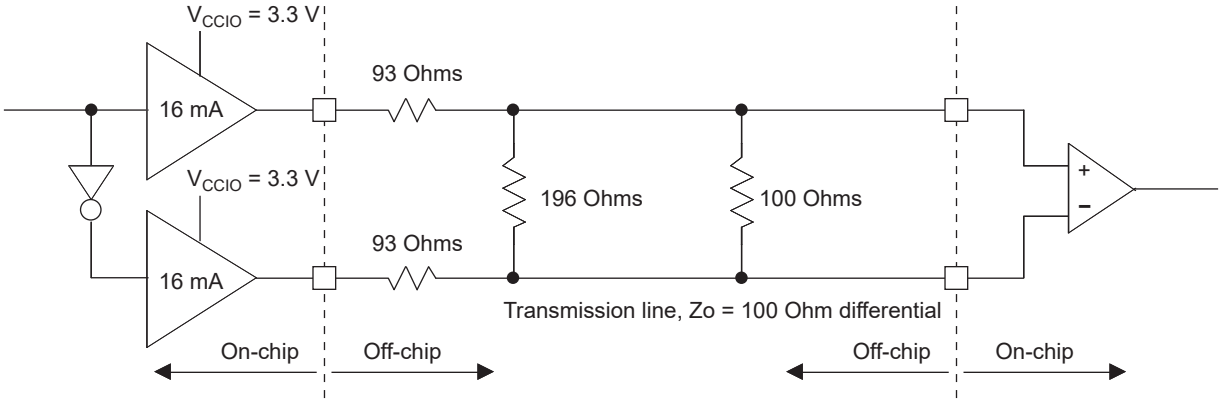


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	93	Ohms
R_P	Driver parallel resistor	196	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	2.05	V
V_{OL}	Output low voltage	1.25	V
V_{OD}	Output differential voltage	0.80	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	100.5	Ohms
I_{DC}	DC output current	12.11	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO2 family supports the differential RSDS standard. The output standard is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

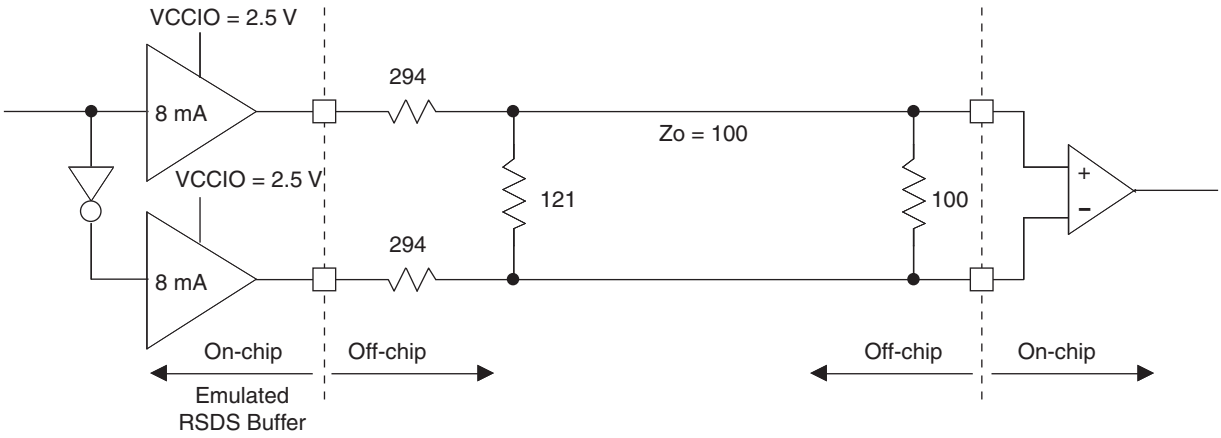


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	294	Ohms
R_P	Driver parallel resistor	121	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	Ohms
I_{DC}	DC output current	3.66	mA

Typical Building Block Function Performance – HC/HE Devices[1]

Pin-to-Pin Performance (LVCMOS25 12 mA Drive)

Function	-6 Timing	Units
Basic Functions		
16-bit decoder	8.9	ns
4:1 MUX	7.5	ns
16:1 MUX	8.3	ns

Register-to-Register Performance

Function	-6 Timing	Units
Basic Functions		
16:1 MUX	412	MHz
16-bit adder	297	MHz
16-bit counter	324	MHz
64-bit counter	161	MHz
Embedded Memory Functions		
1024x9 True-Dual Port RAM (Write Through or Normal, EBR output registers)	183	MHz
Distributed Memory Functions		
16x4 Pseudo-Dual Port RAM (one PFU)	500	MHz

1. The above timing numbers are generated using the Diamond design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device. Commercial timing numbers are shown at 85 °C and 1.14 V. Other operating conditions, including industrial, can be extracted from the Diamond software.

Typical Building Block Function Performance – ZE Devices[1]

Pin-to-Pin Performance (LVCMOS25 12 mA Drive)

Function	–3 Timing	Units
Basic Functions		
16-bit decoder	13.9	ns
4:1 MUX	10.9	ns
16:1 MUX	12.0	ns

Register-to-Register Performance

Function	–3 Timing	Units
Basic Functions		
16:1 MUX	191	MHz
16-bit adder	134	MHz
16-bit counter	148	MHz
64-bit counter	77	MHz
Embedded Memory Functions		
1024x9 True-Dual Port RAM (Write Through or Normal, EBR output registers)	90	MHz
Distributed Memory Functions		
16x4 Pseudo-Dual Port RAM (one PFU)	214	MHz

1. The above timing numbers are generated using the Diamond design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Derating Logic Timing

Logic timing provided in the following sections of the data sheet and the Lattice design tools are worst case numbers in the operating range. Actual delays may be much faster. Lattice design tools can provide logic timing numbers at a particular temperature and voltage.

Maximum sysIO Buffer Performance

I/O Standard	Max. Speed	Units
LVDS25	400	MHz
LVDS25E	150	MHz
RSDS25	150	MHz
RSDS25E	150	MHz
BLVDS25	150	MHz
BLVDS25E	150	MHz
MLVDS25	150	MHz
MLVDS25E	150	MHz
LVPECL33	150	MHz
LVPECL33E	150	MHz
SSTL25_I	150	MHz
SSTL25_II	150	MHz
SSTL25D_I	150	MHz
SSTL25D_II	150	MHz
SSTL18_I	150	MHz
SSTL18_II	150	MHz
SSTL18D_I	150	MHz
SSTL18D_II	150	MHz
HSTL18_I	150	MHz
HSTL18_II	150	MHz
HSTL18D_I	150	MHz
HSTL18D_II	150	MHz
PCI33	134	MHz
LVTTL33	150	MHz
LVTTL33D	150	MHz
LVCMOS33	150	MHz
LVCMOS33D	150	MHz
LVCMOS25	150	MHz
LVCMOS25D	150	MHz
LVCMOS25R33	150	MHz
LVCMOS18	150	MHz
LVCMOS18D	150	MHz
LVCMOS18R33	150	MHz
LVCMOS18R25	150	MHz
LVCMOS15	150	MHz
LVCMOS15D	150	MHz
LVCMOS15R33	150	MHz
LVCMOS15R25	150	MHz
LVCMOS12	91	MHz
LVCMOS12D	91	MHz

MachXO2 External Switching Characteristics – HC/HE Devices[1, 2, 3, 4, 5, 6, 7]

Over Recommended Operating Conditions

Parameter	Description	Device	–6		–5		–4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Clocks									
Primary Clocks									
f_{MAX_PRI}[8]	Frequency for Primary Clock Tree	All MachXO2 devices	—	388	—	323	—	269	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All MachXO2 devices	0.5	—	0.6	—	0.7	—	ns
t_{SKEW_PRI}	Primary Clock Skew Within a Device	MachXO2-256HC-HE	—	912	—	939	—	975	ps
		MachXO2-640HC-HE	—	844	—	871	—	908	ps
		MachXO2-1200HC-HE	—	868	—	902	—	951	ps
		MachXO2-2000HC-HE	—	867	—	897	—	941	ps
		MachXO2-4000HC-HE	—	865	—	892	—	931	ps
		MachXO2-7000HC-HE	—	902	—	942	—	989	ps
Edge Clock									
f_{MAX_EDGE}[8]	Frequency for Edge Clock	MachXO2-1200 and larger devices	—	400	—	333	—	278	MHz
Pin-LUT-Pin Propagation Delay									
t_{PD}	Best case propagation delay through one LUT-4	All MachXO2 devices	—	6.72	—	6.96	—	7.24	ns
General I/O Pin Parameters (Using Primary Clock without PLL)									
t_{CO}	Clock to Output – PIO Output Register	MachXO2-256HC-HE	—	7.13	—	7.30	—	7.57	ns
		MachXO2-640HC-HE	—	7.15	—	7.30	—	7.57	ns
		MachXO2-1200HC-HE	—	7.44	—	7.64	—	7.94	ns
		MachXO2-2000HC-HE	—	7.46	—	7.66	—	7.96	ns
		MachXO2-4000HC-HE	—	7.51	—	7.71	—	8.01	ns
		MachXO2-7000HC-HE	—	7.54	—	7.75	—	8.06	ns
t_{SU}	Clock to Data Setup – PIO Input Register	MachXO2-256HC-HE	–0.06	—	–0.06	—	–0.06	—	ns
		MachXO2-640HC-HE	–0.06	—	–0.06	—	–0.06	—	ns
		MachXO2-1200HC-HE	–0.17	—	–0.17	—	–0.17	—	ns
		MachXO2-2000HC-HE	–0.20	—	–0.20	—	–0.20	—	ns
		MachXO2-4000HC-HE	–0.23	—	–0.23	—	–0.23	—	ns
		MachXO2-7000HC-HE	–0.23	—	–0.23	—	–0.23	—	ns
t_{H}	Clock to Data Hold – PIO Input Register	MachXO2-256HC-HE	1.75	—	1.95	—	2.16	—	ns
		MachXO2-640HC-HE	1.75	—	1.95	—	2.16	—	ns
		MachXO2-1200HC-HE	1.88	—	2.12	—	2.36	—	ns
		MachXO2-2000HC-HE	1.89	—	2.13	—	2.37	—	ns
		MachXO2-4000HC-HE	1.94	—	2.18	—	2.43	—	ns
		MachXO2-7000HC-HE	1.98	—	2.23	—	2.49	—	ns

Parameter	Description	Device	–6		–5		–4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{SU_DEL}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-256HC-HE	1.42	—	1.59	—	1.96	—	ns
		MachXO2-640HC-HE	1.41	—	1.58	—	1.96	—	ns
		MachXO2-1200HC-HE	1.63	—	1.79	—	2.17	—	ns
		MachXO2-2000HC-HE	1.61	—	1.76	—	2.13	—	ns
		MachXO2-4000HC-HE	1.66	—	1.81	—	2.19	—	ns
		MachXO2-7000HC-HE	1.53	—	1.67	—	2.03	—	ns
t_{H_DEL}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-256HC-HE	–0.24	—	–0.24	—	–0.24	—	ns
		MachXO2-640HC-HE	–0.23	—	–0.23	—	–0.23	—	ns
		MachXO2-1200HC-HE	–0.24	—	–0.24	—	–0.24	—	ns
		MachXO2-2000HC-HE	–0.23	—	–0.23	—	–0.23	—	ns
		MachXO2-4000HC-HE	–0.25	—	–0.25	—	–0.25	—	ns
		MachXO2-7000HC-HE	–0.21	—	–0.21	—	–0.21	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All MachXO2 devices	—	388	—	323	—	269	MHz
General I/O Pin Parameters (Using Edge Clock without PLL)									
t_{COE}	Clock to Output – PIO Output Register	MachXO2-1200HC-HE	—	7.53	—	7.76	—	8.10	ns
		MachXO2-2000HC-HE	—	7.53	—	7.76	—	8.10	ns
		MachXO2-4000HC-HE	—	7.45	—	7.68	—	8.00	ns
		MachXO2-7000HC-HE	—	7.53	—	7.76	—	8.10	ns
t_{SUE}	Clock to Data Setup – PIO Input Register	MachXO2-1200HC-HE	–0.19	—	–0.19	—	–0.19	—	ns
		MachXO2-2000HC-HE	–0.19	—	–0.19	—	–0.19	—	ns
		MachXO2-4000HC-HE	–0.16	—	–0.16	—	–0.16	—	ns
		MachXO2-7000HC-HE	–0.19	—	–0.19	—	–0.19	—	ns
t_{HE}	Clock to Data Hold – PIO Input Register	MachXO2-1200HC-HE	1.97	—	2.24	—	2.52	—	ns
		MachXO2-2000HC-HE	1.97	—	2.24	—	2.52	—	ns
		MachXO2-4000HC-HE	1.89	—	2.16	—	2.43	—	ns
		MachXO2-7000HC-HE	1.97	—	2.24	—	2.52	—	ns
t_{SU_DELE}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-1200HC-HE	1.56	—	1.69	—	2.05	—	ns
		MachXO2-2000HC-HE	1.56	—	1.69	—	2.05	—	ns
		MachXO2-4000HC-HE	1.74	—	1.88	—	2.25	—	ns
		MachXO2-7000HC-HE	1.66	—	1.81	—	2.17	—	ns
t_{H_DELE}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-1200HC-HE	–0.23	—	–0.23	—	–0.23	—	ns
		MachXO2-2000HC-HE	–0.23	—	–0.23	—	–0.23	—	ns
		MachXO2-4000HC-HE	–0.34	—	–0.34	—	–0.34	—	ns
		MachXO2-7000HC-HE	–0.29	—	–0.29	—	–0.29	—	ns
General I/O Pin Parameters (Using Primary Clock with PLL)									
t_{COPLL}	Clock to Output – PIO Output Register	MachXO2-1200HC-HE	—	5.97	—	6.00	—	6.13	ns
		MachXO2-2000HC-HE	—	5.98	—	6.01	—	6.14	ns
		MachXO2-4000HC-HE	—	5.99	—	6.02	—	6.16	ns
		MachXO2-7000HC-HE	—	6.02	—	6.06	—	6.20	ns
t_{SUPLL}	Clock to Data Setup – PIO Input Register	MachXO2-1200HC-HE	0.36	—	0.36	—	0.65	—	ns
		MachXO2-2000HC-HE	0.36	—	0.36	—	0.63	—	ns
		MachXO2-4000HC-HE	0.35	—	0.35	—	0.62	—	ns
		MachXO2-7000HC-HE	0.34	—	0.34	—	0.59	—	ns

Parameter	Description	Device	–6		–5		–4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{HPLL}	Clock to Data Hold – PIO Input Register	MachXO2-1200HC-HE	0.41	—	0.48	—	0.55	—	ns
		MachXO2-2000HC-HE	0.42	—	0.49	—	0.56	—	ns
		MachXO2-4000HC-HE	0.43	—	0.50	—	0.58	—	ns
		MachXO2-7000HC-HE	0.46	—	0.54	—	0.62	—	ns
t_{SU_DELPLL}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-1200HC-HE	2.88	—	3.19	—	3.72	—	ns
		MachXO2-2000HC-HE	2.87	—	3.18	—	3.70	—	ns
		MachXO2-4000HC-HE	2.96	—	3.28	—	3.81	—	ns
		MachXO2-7000HC-HE	3.05	—	3.35	—	3.87	—	ns
t_{H_DELPLL}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-1200HC-HE	–0.83	—	–0.83	—	–0.83	—	ns
		MachXO2-2000HC-HE	–0.83	—	–0.83	—	–0.83	—	ns
		MachXO2-4000HC-HE	–0.87	—	–0.87	—	–0.87	—	ns
		MachXO2-7000HC-HE	–0.91	—	–0.91	—	–0.91	—	ns
Generic DDRX1 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX1_RX.SCLK.Aligned[9, 12]									
t_{DVA}	Input Data Valid After CLK	All MachXO2 devices, all sides	—	0.317	—	0.344	—	0.368	UI
t_{DVE}	Input Data Hold After CLK		0.742	—	0.702	—	0.668	—	UI
f_{DATA}	DDRX1 Input Data Speed		—	300	—	250	—	208	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency		—	150	—	125	—	104	MHz
Generic DDRX1 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX1_RX.SCLK.Centered[9, 12]									
t_{SU}	Input Data Setup Before CLK	All MachXO2 devices, all sides	0.566	—	0.560	—	0.538	—	ns
t_{HO}	Input Data Hold After CLK		0.778	—	0.879	—	1.090	—	ns
f_{DATA}	DDRX1 Input Data Speed		—	300	—	250	—	208	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency		—	150	—	125	—	104	MHz
Generic DDRX2 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX2_RX.ECLK.Aligned[9, 12]									
t_{DVA}	Input Data Valid After CLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only[11]	—	0.316	—	0.342	—	0.364	UI
t_{DVE}	Input Data Hold After CLK		0.710	—	0.675	—	0.679	—	UI
f_{DATA}	DDRX2 Serial Input Data Speed		—	664	—	554	—	462	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency		—	332	—	277	—	231	MHz
f_{SCLK}	SCLK Frequency		—	166	—	139	—	116	MHz
Generic DDRX2 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX2_RX.ECLK.Centered[9, 12]									
t_{SU}	Input Data Setup Before CLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only[11]	0.233	—	0.219	—	0.198	—	ns
t_{HO}	Input Data Hold After CLK		0.287	—	0.287	—	0.344	—	ns
f_{DATA}	DDRX2 Serial Input Data Speed		—	664	—	554	—	462	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency		—	332	—	277	—	231	MHz
f_{SCLK}	SCLK Frequency		—	166	—	139	—	116	MHz

Parameter	Description	Device	–6		–5		–4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Generic DDR4 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX4_RX.ECLK.Aligned[9, 12]									
t_{DVA}	Input Data Valid After ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only.[11]	—	0.290	—	0.320	—	0.345	UI
t_{DVE}	Input Data Hold After ECLK		0.739	—	0.699	—	0.703	—	UI
f_{DATA}	DDRX4 Serial Input Data Speed		—	756	—	630	—	524	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency		—	378	—	315	—	262	MHz
f_{SCLK}	SCLK Frequency		—	95	—	79	—	66	MHz
Generic DDR4 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX4_RX.ECLK.Centered[9, 12]									
t_{SU}	Input Data Setup Before ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only.[11]	0.233	—	0.219	—	0.198	—	ns
t_{HO}	Input Data Hold After ECLK		0.287	—	0.287	—	0.344	—	ns
f_{DATA}	DDRX4 Serial Input Data Speed		—	756	—	630	—	524	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency		—	378	—	315	—	262	MHz
f_{SCLK}	SCLK Frequency		—	95	—	79	—	66	MHz
7:1 LVDS Inputs (GDDR71_RX.ECLK.7:1)[9, 12]									
t_{DVA}	Input Data Valid After ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only.[11]	—	0.290	—	0.320	—	0.345	UI
t_{DVE}	Input Data Hold After ECLK		0.739	—	0.699	—	0.703	—	UI
f_{DATA}	DDR71 Serial Input Data Speed		—	756	—	630	—	524	Mbps
f_{DDR71}	DDR71 ECLK Frequency		—	378	—	315	—	262	MHz
f_{CLKIN}	7:1 Input Clock Frequency (SCLK) (minimum limited by PLL)		—	108	—	90	—	75	MHz
Generic DDR Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX1_TX.SCLK.Aligned[9, 12]									
t_{DIA}	Output Data Invalid After CLK Output	All MachXO2 devices, all sides.	—	0.520	—	0.550	—	0.580	ns
t_{DIB}	Output Data Invalid Before CLK Output		—	0.520	—	0.550	—	0.580	ns
f_{DATA}	DDRX1 Output Data Speed		—	300	—	250	—	208	Mbps
f_{DDRX1}	DDRX1 SCLK frequency		—	150	—	125	—	104	MHz
Generic DDR Outputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX1_TX.SCLK.Centered[9, 12]									
t_{DVB}	Output Data Valid Before CLK Output	All MachXO2 devices, all sides.	1.210	—	1.510	—	1.870	—	ns
t_{DVA}	Output Data Valid After CLK Output		1.210	—	1.510	—	1.870	—	ns
f_{DATA}	DDRX1 Output Data Speed		—	300	—	250	—	208	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency (minimum limited by PLL)		—	150	—	125	—	104	MHz
Generic DDRX2 Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX2_TX.ECLK.Aligned[9, 12]									
t_{DIA}	Output Data Invalid After CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only.	—	0.200	—	0.215	—	0.230	ns
t_{DIB}	Output Data Invalid Before CLK Output		—	0.200	—	0.215	—	0.230	ns
f_{DATA}	DDRX2 Serial Output Data Speed		—	664	—	554	—	462	Mbps
f_{DDRX2}	DDRX2 ECLK frequency		—	332	—	277	—	231	MHz
f_{SCLK}	SCLK Frequency		—	166	—	139	—	116	MHz

Parameter	Description	Device	–6		–5		–4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Generic DDRX2 Outputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX2_TX.ECLK.Centered[9, 12]									
t_{DVB}	Output Data Valid Before CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only.	0.535	—	0.670	—	0.830	—	ns
t_{DVA}	Output Data Valid After CLK Output		0.535	—	0.670	—	0.830	—	ns
f_{DATA}	DDRX2 Serial Output Data Speed		—	664	—	554	—	462	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency (minimum limited by PLL)		—	332	—	277	—	231	MHz
f_{SCLK}	SCLK Frequency		—	166	—	139	—	116	MHz
Generic DDRX4 Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX4_TX.ECLK.Aligned[9, 12]									
t_{DIA}	Output Data Invalid After CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only.	—	0.200	—	0.215	—	0.230	ns
t_{DIB}	Output Data Invalid Before CLK Output		—	0.200	—	0.215	—	0.230	ns
f_{DATA}	DDRX4 Serial Output Data Speed		—	756	—	630	—	524	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency		—	378	—	315	—	262	MHz
f_{SCLK}	SCLK Frequency		—	95	—	79	—	66	MHz
Generic DDRX4 Outputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX4_TX.ECLK.Centered[9, 12]									
t_{DVB}	Output Data Valid Before CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only.	0.455	—	0.570	—	0.710	—	ns
t_{DVA}	Output Data Valid After CLK Output		0.455	—	0.570	—	0.710	—	ns
f_{DATA}	DDRX4 Serial Output Data Speed		—	756	—	630	—	524	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency (minimum limited by PLL)		—	378	—	315	—	262	MHz
f_{SCLK}	SCLK Frequency		—	95	—	79	—	66	MHz
7:1 LVDS Outputs – GDDR71_TX.ECLK.7:1[9, 12]									
t_{DIB}	Output Data Invalid Before CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only.	—	0.160	—	0.180	—	0.200	ns
t_{DIA}	Output Data Invalid After CLK Output		—	0.160	—	0.180	—	0.200	ns
f_{DATA}	DDR71 Serial Output Data Speed		—	756	—	630	—	524	Mbps
f_{DDR71}	DDR71 ECLK Frequency		—	378	—	315	—	262	MHz
f_{CLKOUT}	7:1 Output Clock Frequency (SCLK) (minimum limited by PLL)		—	108	—	90	—	75	MHz

Parameter	Description	Device	–6		–5		–4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
LPDDR[9, 12]									
t_{DVADQ}	Input Data Valid After DQS Input	MachXO2-1200/U and larger devices, right side only.[13]	—	0.369	—	0.395	—	0.421	UI
t_{DVEDQ}	Input Data Hold After DQS Input		0.529	—	0.530	—	0.527	—	UI
t_{DQVBS}	Output Data Invalid Before DQS Output		0.25	—	0.25	—	0.25	—	UI
t_{DQVAS}	Output Data Invalid After DQS Output		0.25	—	0.25	—	0.25	—	UI
f_{DATA}	MEM LPDDR Serial Data Speed		—	280	—	250	—	208	Mbps
f_{SCLK}	SCLK Frequency		—	140	—	125	—	104	MHz
f_{LPDDR}	LPDDR Data Transfer Rate		0	280	0	250	0	208	Mbps
DDR[9, 12]									
t_{DVADQ}	Input Data Valid After DQS Input	MachXO2-1200/U and larger devices, right side only.[13]	—	0.350	—	0.387	—	0.414	UI
t_{DVEDQ}	Input Data Hold After DQS Input		0.545	—	0.538	—	0.532	—	UI
t_{DQVBS}	Output Data Invalid Before DQS Output		0.25	—	0.25	—	0.25	—	UI
t_{DQVAS}	Output Data Invalid After DQS Output		0.25	—	0.25	—	0.25	—	UI
f_{DATA}	MEM DDR Serial Data Speed		—	300	—	250	—	208	Mbps
f_{SCLK}	SCLK Frequency		—	150	—	125	—	104	MHz
f_{MEM_DDR}	MEM DDR Data Transfer Rate		N/A	300	N/A	250	N/A	208	Mbps
DDR2[9, 12]									
t_{DVADQ}	Input Data Valid After DQS Input	MachXO2-1200/U and larger devices, right side only.[13]	—	0.360	—	0.378	—	0.406	UI
t_{DVEDQ}	Input Data Hold After DQS Input		0.555	—	0.549	—	0.542	—	UI
t_{DQVBS}	Output Data Invalid Before DQS Output		0.25	—	0.25	—	0.25	—	UI
t_{DQVAS}	Output Data Invalid After DQS Output		0.25	—	0.25	—	0.25	—	UI
f_{DATA}	MEM DDR Serial Data Speed		—	300	—	250	—	208	Mbps
f_{SCLK}	SCLK Frequency		—	150	—	125	—	104	MHz
f_{MEM_DDR2}	MEM DDR2 Data Transfer Rate		N/A	300	N/A	250	N/A	208	Mbps

1. Exact performance may vary with device and design implementation. Commercial timing numbers are shown at 85 °C and 1.14 V. Other operating conditions, including industrial, can be extracted from the Diamond software.
2. General I/O timing numbers based on LVCMOS 2.5, 8 mA, 0pf load, fast slew rate.
3. Generic DDR timing numbers based on LVDS I/O (for input, output, and clock ports).
4. DDR timing numbers based on SSTL25. DDR2 timing numbers based on SSTL18. LPDDR timing numbers based in LVCMOS18.
5. 7:1 LVDS (GDDR71) uses the LVDS I/O standard (for input, output, and clock ports).
6. For Generic DDRX1 mode $t_{SU} = t_{HO} = (t_{DVE} - t_{DVA} - 0.03\ ns)/2$.
7. The t_{SU_DEL} and t_{H_DEL} values use the SCLK_ZERHOLD default step size. Each step is 105 ps (–6), 113 ps (–5), 120 ps (–4).
8. This number for general purpose usage. Duty cycle tolerance is +/– 10%.
9. Duty cycle is +/–5% for system usage.
10. The above timing numbers are generated using the Diamond design tool. Exact performance may vary with the device selected.
11. High-speed DDR and LVDS not supported in SG32 (32 QFN) packages.
12. Advance information for MachXO2 devices in 48 QFN packages.
13. DDR memory interface not supported in QN84 (84 QFN) and SG32 (32 QFN) packages.

MachXO2 External Switching Characteristics – ZE Devices[1, 2, 3, 4, 5, 6, 7]

Over Recommended Operating Conditions

Parameter	Description	Device	–3		–2		–1		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Clocks									
Primary Clocks									
f_{MAX_PRI}[8]	Frequency for Primary Clock Tree	All MachXO2 devices	—	150	—	125	—	104	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All MachXO2 devices	1.00	—	1.20	—	1.40	—	ns
t_{SKEW_PRI}	Primary Clock Skew Within a Device	MachXO2-256ZE	—	1250	—	1272	—	1296	ps
		MachXO2-640ZE	—	1161	—	1183	—	1206	ps
		MachXO2-1200ZE	—	1213	—	1267	—	1322	ps
		MachXO2-2000ZE	—	1204	—	1250	—	1296	ps
		MachXO2-4000ZE	—	1195	—	1233	—	1269	ps
		MachXO2-7000ZE	—	1243	—	1268	—	1296	ps
Edge Clock									
f_{MAX_EDGE}[8]	Frequency for Edge Clock	MachXO2-1200 and larger devices	—	210	—	175	—	146	MHz
Pin-LUT-Pin Propagation Delay									
t_{PD}	Best case propagation delay through one LUT-4	All MachXO2 devices	—	9.35	—	9.78	—	10.21	ns
General I/O Pin Parameters (Using Primary Clock without PLL)									
t_{CO}	Clock to Output – PIO Output Register	MachXO2-256ZE	—	10.46	—	10.86	—	11.25	ns
		MachXO2-640ZE	—	10.52	—	10.92	—	11.32	ns
		MachXO2-1200ZE	—	11.24	—	11.68	—	12.12	ns
		MachXO2-2000ZE	—	11.27	—	11.71	—	12.16	ns
		MachXO2-4000ZE	—	11.28	—	11.78	—	12.28	ns
		MachXO2-7000ZE	—	11.22	—	11.76	—	12.30	ns
t_{SU}	Clock to Data Setup – PIO Input Register	MachXO2-256ZE	–0.21	—	–0.21	—	–0.21	—	ns
		MachXO2-640ZE	–0.22	—	–0.22	—	–0.22	—	ns
		MachXO2-1200ZE	–0.25	—	–0.25	—	–0.25	—	ns
		MachXO2-2000ZE	–0.27	—	–0.27	—	–0.27	—	ns
		MachXO2-4000ZE	–0.31	—	–0.31	—	–0.31	—	ns
		MachXO2-7000ZE	–0.33	—	–0.33	—	–0.33	—	ns
t_{H}	Clock to Data Hold – PIO Input Register	MachXO2-256ZE	3.96	—	4.25	—	4.65	—	ns
		MachXO2-640ZE	4.01	—	4.31	—	4.71	—	ns
		MachXO2-1200ZE	3.95	—	4.29	—	4.73	—	ns
		MachXO2-2000ZE	3.94	—	4.29	—	4.74	—	ns
		MachXO2-4000ZE	3.96	—	4.36	—	4.87	—	ns
		MachXO2-7000ZE	3.93	—	4.37	—	4.91	—	ns

Parameter	Description	Device	–3		–2		–1		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{SU_DEL}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-256ZE	2.62	—	2.91	—	3.14	—	ns
		MachXO2-640ZE	2.56	—	2.85	—	3.08	—	ns
		MachXO2-1200ZE	2.30	—	2.57	—	2.79	—	ns
		MachXO2-2000ZE	2.25	—	2.50	—	2.70	—	ns
		MachXO2-4000ZE	2.39	—	2.60	—	2.76	—	ns
		MachXO2-7000ZE	2.17	—	2.33	—	2.43	—	ns
t_{H_DEL}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-256ZE	–0.44	—	–0.44	—	–0.44	—	ns
		MachXO2-640ZE	–0.43	—	–0.43	—	–0.43	—	ns
		MachXO2-1200ZE	–0.28	—	–0.28	—	–0.28	—	ns
		MachXO2-2000ZE	–0.31	—	–0.31	—	–0.31	—	ns
		MachXO2-4000ZE	–0.34	—	–0.34	—	–0.34	—	ns
		MachXO2-7000ZE	–0.21	—	–0.21	—	–0.21	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All MachXO2 devices	—	150	—	125	—	104	MHz
General I/O Pin Parameters (Using Edge Clock without PLL)									
t_{COE}	Clock to Output – PIO Output Register	MachXO2-1200ZE	—	11.10	—	11.51	—	11.91	ns
		MachXO2-2000ZE	—	11.10	—	11.51	—	11.91	ns
		MachXO2-4000ZE	—	10.89	—	11.28	—	11.67	ns
		MachXO2-7000ZE	—	11.10	—	11.51	—	11.91	ns
t_{SUE}	Clock to Data Setup – PIO Input Register	MachXO2-1200ZE	–0.23	—	–0.23	—	–0.23	—	ns
		MachXO2-2000ZE	–0.23	—	–0.23	—	–0.23	—	ns
		MachXO2-4000ZE	–0.15	—	–0.15	—	–0.15	—	ns
		MachXO2-7000ZE	–0.23	—	–0.23	—	–0.23	—	ns
t_{HE}	Clock to Data Hold – PIO Input Register	MachXO2-1200ZE	3.81	—	4.11	—	4.52	—	ns
		MachXO2-2000ZE	3.81	—	4.11	—	4.52	—	ns
		MachXO2-4000ZE	3.60	—	3.89	—	4.28	—	ns
		MachXO2-7000ZE	3.81	—	4.11	—	4.52	—	ns
t_{SU_DELE}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-1200ZE	2.78	—	3.11	—	3.40	—	ns
		MachXO2-2000ZE	2.78	—	3.11	—	3.40	—	ns
		MachXO2-4000ZE	3.11	—	3.48	—	3.79	—	ns
		MachXO2-7000ZE	2.94	—	3.30	—	3.60	—	ns
t_{H_DELE}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-1200ZE	–0.29	—	-0.29	—	–0.29	—	ns
		MachXO2-2000ZE	–0.29	—	-0.29	—	–0.29	—	ns
		MachXO2-4000ZE	–0.46	—	-0.46	—	–0.46	—	ns
		MachXO2-7000ZE	–0.37	—	-0.37	—	–0.37	—	ns
General I/O Pin Parameters (Using Primary Clock with PLL)									
t_{COPLL}	Clock to Output – PIO Output Register	MachXO2-1200ZE	—	7.95	—	8.07	—	8.19	ns
		MachXO2-2000ZE	—	7.97	—	8.10	—	8.22	ns
		MachXO2-4000ZE	—	7.98	—	8.10	—	8.23	ns
		MachXO2-7000ZE	—	8.02	—	8.14	—	8.26	ns
t_{SUPLL}	Clock to Data Setup – PIO Input Register	MachXO2-1200ZE	0.85	—	0.85	—	0.89	—	ns
		MachXO2-2000ZE	0.84	—	0.84	—	0.86	—	ns
		MachXO2-4000ZE	0.84	—	0.84	—	0.85	—	ns
		MachXO2-7000ZE	0.83	—	0.83	—	0.81	—	ns

Parameter	Description	Device	–3		–2		–1		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{HPLL}	Clock to Data Hold – PIO Input Register	MachXO2-1200ZE	0.66	—	0.68	—	0.80	—	ns
		MachXO2-2000ZE	0.68	—	0.70	—	0.83	—	ns
		MachXO2-4000ZE	0.68	—	0.71	—	0.84	—	ns
		MachXO2-7000ZE	0.73	—	0.74	—	0.87	—	ns
t_{SU_DELPLL}	Clock to Data Setup – PIO Input Register with Data Input Delay	MachXO2-1200ZE	5.14	—	5.69	—	6.20	—	ns
		MachXO2-2000ZE	5.11	—	5.67	—	6.17	—	ns
		MachXO2-4000ZE	5.27	—	5.84	—	6.35	—	ns
		MachXO2-7000ZE	5.15	—	5.71	—	6.23	—	ns
t_{H_DELPLL}	Clock to Data Hold – PIO Input Register with Input Data Delay	MachXO2-1200ZE	–1.36	—	–1.36	—	–1.36	—	ns
		MachXO2-2000ZE	–1.35	—	–1.35	—	–1.35	—	ns
		MachXO2-4000ZE	–1.43	—	–1.43	—	–1.43	—	ns
		MachXO2-7000ZE	–1.41	—	–1.41	—	–1.41	—	ns
Generic DDRX1 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX1_RX.SCLK.Aligned[9, 12]									
t_{DVA}	Input Data Valid After CLK	All MachXO2 devices, all sides	—	0.382	—	0.401	—	0.417	UI
t_{DVE}	Input Data Hold After CLK		0.670	—	0.684	—	0.693	—	UI
f_{DATA}	DDRX1 Input Data Speed		—	140	—	116	—	98	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency		—	70	—	58	—	49	MHz
Generic DDRX1 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX1_RX.SCLK.Centered[9, 12]									
t_{SU}	Input Data Setup Before CLK	All MachXO2 devices, all sides	1.319	—	1.412	—	1.462	—	ns
t_{HO}	Input Data Hold After CLK		0.717	—	1.010	—	1.340	—	ns
f_{DATA}	DDRX1 Input Data Speed		—	140	—	116	—	98	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency		—	70	—	58	—	49	MHz
Generic DDRX2 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX2_RX.ECLK.Aligned[9, 12]									
t_{DVA}	Input Data Valid After CLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only[11]	—	0.361	—	0.346	—	0.334	UI
t_{DVE}	Input Data Hold After CLK		0.602	—	0.625	—	0.648	—	UI
f_{DATA}	DDRX2 Serial Input Data Speed		—	280	—	234	—	194	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency		—	140	—	117	—	97	MHz
f_{SCLK}	SCLK Frequency		—	70	—	59	—	49	MHz
Generic DDRX2 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX2_RX.ECLK.Centered[9, 12]									
t_{SU}	Input Data Setup Before CLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only[11]	0.472	—	0.672	—	0.865	—	ns
t_{HO}	Input Data Hold After CLK		0.363	—	0.501	—	0.743	—	ns
f_{DATA}	DDRX2 Serial Input Data Speed		—	280	—	234	—	194	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency		—	140	—	117	—	97	MHz
f_{SCLK}	SCLK Frequency		—	70	—	59	—	49	MHz
Generic DDR4 Inputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input - GDDRX4_RX.ECLK.Aligned[9, 12]									
t_{DVA}	Input Data Valid After ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only[11]	—	0.307	—	0.316	—	0.326	UI
t_{DVE}	Input Data Hold After ECLK		0.662	—	0.650	—	0.649	—	UI
f_{DATA}	DDRX4 Serial Input Data Speed		—	420	—	352	—	292	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency		—	210	—	176	—	146	MHz
f_{SCLK}	SCLK Frequency		—	53	—	44	—	37	MHz

Parameter	Description	Device	–3		–2		–1		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Generic DDR4 Inputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX4_RX.ECLK.Centered[9, 12]									
t_{SU}	Input Data Setup Before ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only[11]	0.434	—	0.535	—	0.630	—	ns
t_{HO}	Input Data Hold After ECLK		0.385	—	0.395	—	0.463	—	ns
f_{DATA}	DDRX4 Serial Input Data Speed		—	420	—	352	—	292	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency		—	210	—	176	—	146	MHz
f_{SCLK}	SCLK Frequency		—	53	—	44	—	37	MHz
7:1 LVDS Inputs – GDDR71_RX.ECLK.7.1[9, 12]									
t_{DVA}	Input Data Valid After ECLK	MachXO2-640U, MachXO2-1200/U and larger devices, bottom side only[11]	—	0.307	—	0.316	—	0.326	UI
t_{DVE}	Input Data Hold After ECLK		0.662	—	0.650	—	0.649	—	UI
f_{DATA}	DDR71 Serial Input Data Speed		—	420	—	352	—	292	Mbps
f_{DDR71}	DDR71 ECLK Frequency		—	210	—	176	—	146	MHz
f_{CLKIN}	7:1 Input Clock Frequency (SCLK) (minimum limited by PLL)		—	60	—	50	—	42	MHz
Generic DDR Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX1_TX.SCLK.Aligned[9, 12]									
t_{DIA}	Output Data Invalid After CLK Output	All MachXO2 devices, all sides	—	0.850	—	0.910	—	0.970	ns
t_{DIB}	Output Data Invalid Before CLK Output		—	0.850	—	0.910	—	0.970	ns
f_{DATA}	DDRX1 Output Data Speed		—	140	—	116	—	98	Mbps
f_{DDRX1}	DDRX1 SCLK frequency		—	70	—	58	—	49	MHz
Generic DDR Outputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX1_TX.SCLK.Centered[9, 12]									
t_{DVB}	Output Data Valid Before CLK Output	All MachXO2 devices, all sides	2.720	—	3.380	—	4.140	—	ns
t_{DVA}	Output Data Valid After CLK Output		2.720	—	3.380	—	4.140	—	ns
f_{DATA}	DDRX1 Output Data Speed		—	140	—	116	—	98	Mbps
f_{DDRX1}	DDRX1 SCLK Frequency (minimum limited by PLL)		—	70	—	58	—	49	MHz
Generic DDRX2 Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX2_TX.ECLK.Aligned[9, 12]									
t_{DIA}	Output Data Invalid After CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only	—	0.270	—	0.300	—	0.330	ns
t_{DIB}	Output Data Invalid Before CLK Output		—	0.270	—	0.300	—	0.330	ns
f_{DATA}	DDRX2 Serial Output Data Speed		—	280	—	234	—	194	Mbps
f_{DDRX2}	DDRX2 ECLK frequency		—	140	—	117	—	97	MHz
f_{SCLK}	SCLK Frequency		—	70	—	59	—	49	MHz

Parameter	Description	Device	–3		–2		–1		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Generic DDRX2 Outputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX2_TX.ECLK.Centered[9, 12]									
t_{DVB}	Output Data Valid Before CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only	1.445	—	1.760	—	2.140	—	ns
t_{DVA}	Output Data Valid After CLK Output		1.445	—	1.760	—	2.140	—	ns
f_{DATA}	DDRX2 Serial Output Data Speed		—	280	—	234	—	194	Mbps
f_{DDRX2}	DDRX2 ECLK Frequency (minimum limited by PLL)		—	140	—	117	—	97	MHz
f_{SCLK}	SCLK Frequency		—	70	—	59	—	49	MHz
Generic DDRX4 Outputs with Clock and Data Aligned at Pin Using PCLK Pin for Clock Input – GDDRX4_TX.ECLK.Aligned[9, 12]									
t_{DIA}	Output Data Invalid After CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only	—	0.270	—	0.300	—	0.330	ns
t_{DIB}	Output Data Invalid Before CLK Output		—	0.270	—	0.300	—	0.330	ns
f_{DATA}	DDRX4 Serial Output Data Speed		—	420	—	352	—	292	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency		—	210	—	176	—	146	MHz
f_{SCLK}	SCLK Frequency		—	53	—	44	—	37	MHz
Generic DDRX4 Outputs with Clock and Data Centered at Pin Using PCLK Pin for Clock Input – GDDRX4_TX.ECLK.Centered[9, 12]									
t_{DVB}	Output Data Valid Before CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only	0.873	—	1.067	—	1.319	—	ns
t_{DVA}	Output Data Valid After CLK Output		0.873	—	1.067	—	1.319	—	ns
f_{DATA}	DDRX4 Serial Output Data Speed		—	420	—	352	—	292	Mbps
f_{DDRX4}	DDRX4 ECLK Frequency (minimum limited by PLL)		—	210	—	176	—	146	MHz
f_{SCLK}	SCLK Frequency		—	53	—	44	—	37	MHz
7:1 LVDS Outputs – GDDR71_TX.ECLK.7:1[9, 12]									
t_{DIB}	Output Data Invalid Before CLK Output	MachXO2-640U, MachXO2-1200/U and larger devices, top side only.	—	0.240	—	0.270	—	0.300	ns
t_{DIA}	Output Data Invalid After CLK Output		—	0.240	—	0.270	—	0.300	ns
f_{DATA}	DDR71 Serial Output Data Speed		—	420	—	352	—	292	Mbps
f_{DDR71}	DDR71 ECLK Frequency		—	210	—	176	—	146	MHz
f_{CLKOUT}	7:1 Output Clock Frequency (SCLK) (minimum limited by PLL)		—	60	—	50	—	42	MHz

Parameter	Description	Device	–3		–2		–1		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
LPDDR[9, 12]									
t_{DVADQ}	Input Data Valid After DQS Input	MachXO2-1200/U and larger devices, right side only.[13]	—	0.349	—	0.381	—	0.396	UI
t_{DVEDQ}	Input Data Hold After DQS Input		0.665	—	0.630	—	0.613	—	UI
t_{DQVBS}	Output Data Invalid Before DQS Output		0.25	—	0.25	—	0.25	—	UI
t_{DQVAS}	Output Data Invalid After DQS Output		0.25	—	0.25	—	0.25	—	UI
f_{DATA}	MEM LPDDR Serial Data Speed		—	120	—	110	—	96	Mbps
f_{SCLK}	SCLK Frequency		—	60	—	55	—	48	MHz
f_{LPDDR}	LPDDR Data Transfer Rate		0	120	0	110	0	96	Mbps
DDR[9, 12]									
t_{DVADQ}	Input Data Valid After DQS Input	MachXO2-1200/U and larger devices, right side only.[13]	—	0.347	—	0.374	—	0.393	UI
t_{DVEDQ}	Input Data Hold After DQS Input		0.665	—	0.637	—	0.616	—	UI
t_{DQVBS}	Output Data Invalid Before DQS Output		0.25	—	0.25	—	0.25	—	UI
t_{DQVAS}	Output Data Invalid After DQS Output		0.25	—	0.25	—	0.25	—	UI
f_{DATA}	MEM DDR Serial Data Speed		—	140	—	116	—	98	Mbps
f_{SCLK}	SCLK Frequency		—	70	—	58	—	49	MHz
f_{MEM_DDR}	MEM DDR Data Transfer Rate		N/A	140	N/A	116	N/A	98	Mbps
DDR2[9, 12]									
t_{DVADQ}	Input Data Valid After DQS Input	MachXO2-1200/U and larger devices, right side only.[13]	—	0.372	—	0.394	—	0.410	UI
t_{DVEDQ}	Input Data Hold After DQS Input		0.690	—	0.658	—	0.618	—	UI
t_{DQVBS}	Output Data Invalid Before DQS Output		0.25	—	0.25	—	0.25	—	UI
t_{DQVAS}	Output Data Invalid After DQS Output		0.25	—	0.25	—	0.25	—	UI
f_{DATA}	MEM DDR Serial Data Speed		—	140	—	116	—	98	Mbps
f_{SCLK}	SCLK Frequency		—	70	—	58	—	49	MHz
f_{MEM_DDR2}	MEM DDR2 Data Transfer Rate		N/A	140	N/A	116	N/A	98	Mbps

1. Exact performance may vary with device and design implementation. Commercial timing numbers are shown at 85 °C and 1.14 V. Other operating conditions, including industrial, can be extracted from the Diamond software.
2. General I/O timing numbers based on LVCMOS 2.5, 8 mA, 0 pf load, fast slew rate.
3. Generic DDR timing numbers based on LVDS I/O (for input, output, and clock ports).
4. DDR timing numbers based on SSTL25. DDR2 timing numbers based on SSTL18. LPDDR timing numbers based in LVCMOS18.
5. 7:1 LVDS (GDDR71) uses the LVDS I/O standard (for input, output, and clock ports).
6. For Generic DDRX1 mode $t_{SU} = t_{HO} = (t_{DVE} - t_{DVA} - 0.03\ ns)/2$.
7. The t_{SU_DEL} and t_{H_DEL} values use the SCLK_ZERHOLD default step size. Each step is 167 ps (–3), 182 ps (–2), 195 ps (–1).
8. This number for general purpose usage. Duty cycle tolerance is +/–10%.
9. Duty cycle is +/– 5% for system usage.
10. The above timing numbers are generated using the Diamond design tool. Exact performance may vary with the device selected.
11. High-speed DDR and LVDS not supported in SG32 (32-Pin QFN) packages.
12. Advance information for MachXO2 devices in 48 QFN packages.
13. DDR memory interface not supported in QN84 (84 QFN) and SG32 (32 QFN) packages.

Figure 3-5. Receiver RX.CLK.Aligned and MEM DDR Input Waveforms

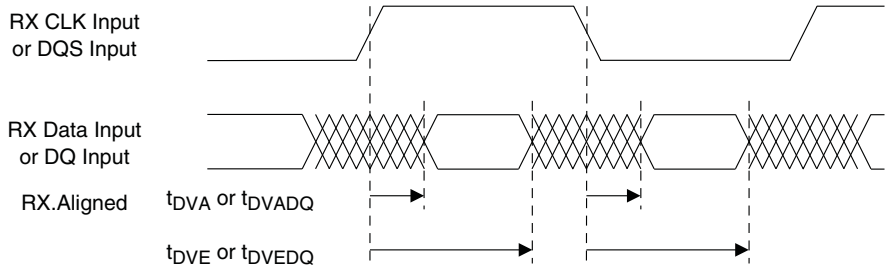


Figure 3-6. Receiver RX.CLK.Centered Waveforms

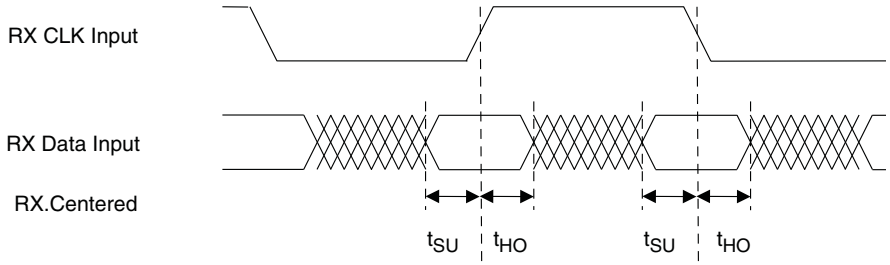


Figure 3-7. Transmitter TX.CLK.Aligned Waveforms

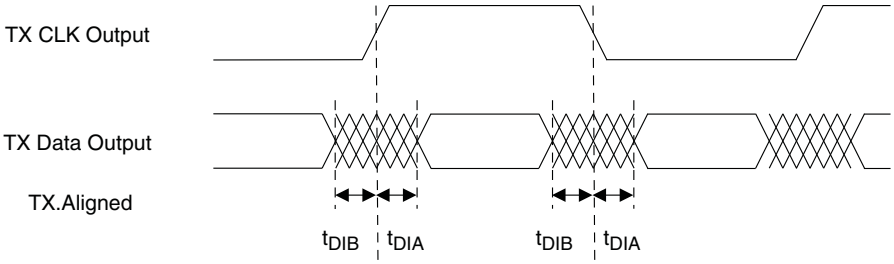


Figure 3-8. Transmitter TX.CLK.Centered and MEM DDR Output Waveforms

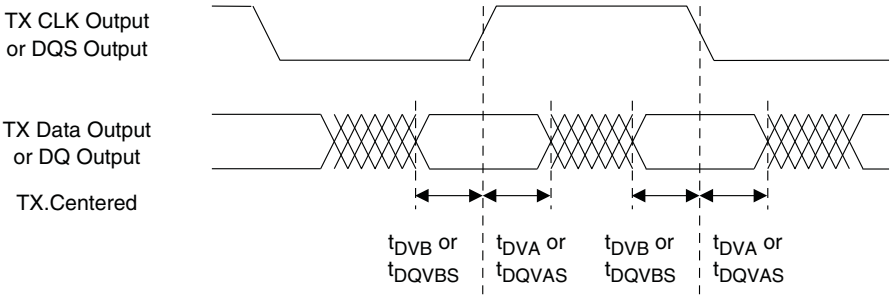


Figure 3-9. GDDR71 Video Timing Waveforms

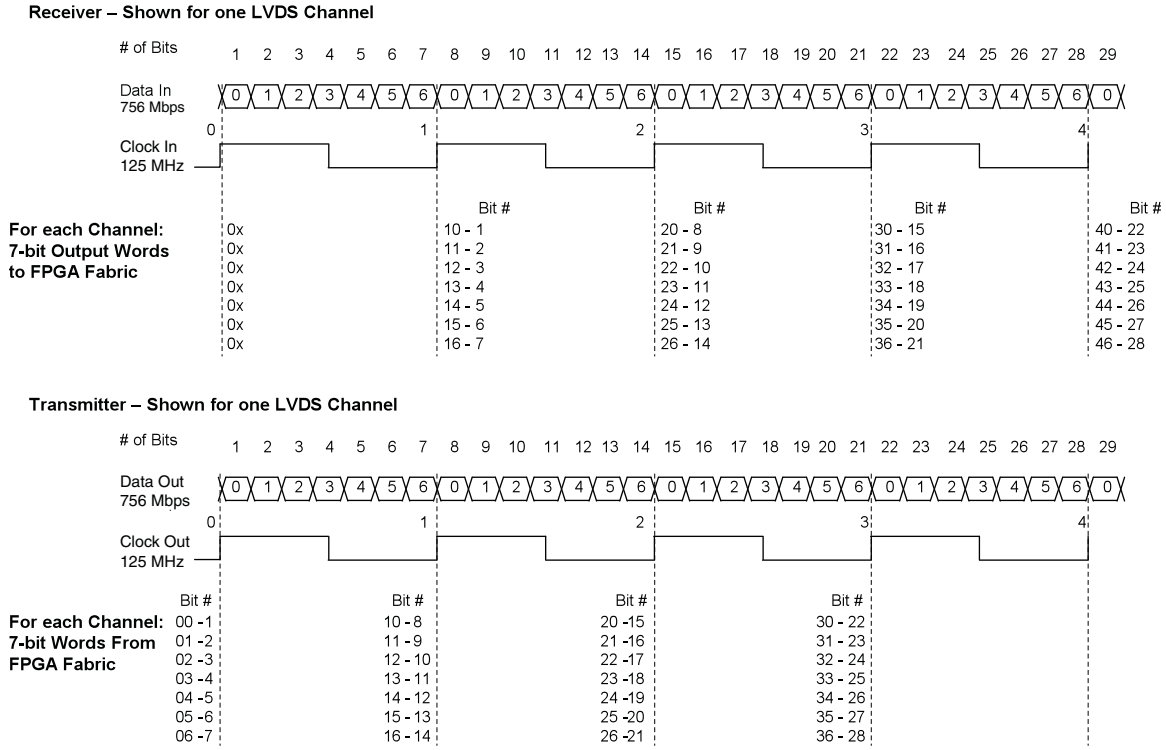


Figure 3-10. Receiver GDDR71_RX. Waveforms

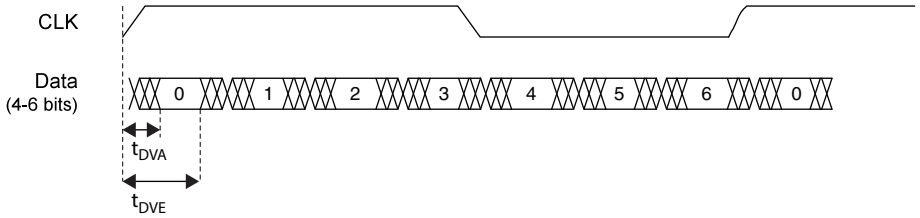
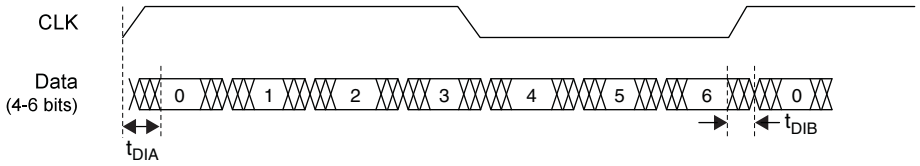


Figure 3-11. Transmitter GDDR71_TX. Waveforms



sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		7	400	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS, CLKOS2)		1.5625	400	MHz
f_{OUT2}	Output Frequency (CLKOS3 cascaded from CLKOS2)		0.0122	400	MHz
f_{VCO}	PLL VCO Frequency		200	800	MHz
f_{PFD}	Phase Detector Input Frequency		7	400	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle	Without duty trim selected[3]	45	55	%
t_{DT_TRIM}[7]	Edge Duty Trim Accuracy		–75	75	%
t_{PH}[4]	Output Phase Accuracy		–6	6	%
t_{OPJIT}[1, 8]	Output Clock Period Jitter	f_{OUT} > 100 MHz	—	150	ps p-p
		f_{OUT} < 100 MHz	—	0.007	UIPP
	Output Clock Cycle-to-cycle Jitter	f_{OUT} > 100 MHz	—	180	ps p-p
		f_{OUT} < 100 MHz	—	0.009	UIPP
	Output Clock Phase Jitter	f_{PFD} > 100 MHz	—	160	ps p-p
		f_{PFD} < 100 MHz	—	0.011	UIPP
	Output Clock Period Jitter (Fractional-N)	f_{OUT} > 100 MHz	—	230	ps p-p
		f_{OUT} < 100 MHz	—	0.12	UIPP
	Output Clock Cycle-to-cycle Jitter (Fractional-N)	f_{OUT} > 100 MHz	—	230	ps p-p
		f_{OUT} < 100 MHz	—	0.12	UIPP
t_{SPO}	Static Phase Offset	Divider ratio = integer	–120	120	ps
t_W	Output Clock Pulse Width	At 90% or 10%[3]	0.9	—	ns
t_{LOCK}[2, 5]	PLL Lock-in Time		—	15	ms
t_{UNLOCK}	PLL Unlock Time		—	50	ns
t_{IPJIT}[6]	Input Clock Period Jitter	$f_{PFD} \geq 20$ MHz	—	1,000	ps p-p
		f_{PFD} < 20 MHz	—	0.02	UIPP
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{STABLE}[5]	STANDBY High to PLL Stable		—	15	ms
t_{RST}	RST/RESETM Pulse Width		1	—	ns
t_{RSTREC}	RST Recovery Time		1	—	ns
t_{RST_DIV}	RESETC/D Pulse Width		10	—	ns
t_{RSTREC_DIV}	RESETC/D Recovery Time		1	—	ns
$t_{ROTATE-SETUP}$	PHASESTEP Setup Time		10	—	ns

sysCLOCK PLL Timing (Continued)

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
t_{ROTATE_WD}	PHASESTEP Pulse Width		4	—	VCO Cycles

1. Period jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock. Cycle-to-cycle jitter is taken over 1000 cycles. Phase jitter is taken over 2000 cycles. All values per JESD65B.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. CLKOS as compared to CLKOP output for one phase step at the maximum VCO frequency. See TN1199, MachXO2 sysCLOCK PLL Design and Usage Guide for more details.
5. At minimum $f_{PFD.}$ As the f_{PFD} increases the time will decrease to approximately 60% the value listed.
6. Maximum allowed jitter on an input clock. PLL unlock may occur if the input jitter exceeds this specification. Jitter on the input clock may be transferred to the output clocks, resulting in jitter measurements outside the output specifications listed in this table.
7. Edge Duty Trim Accuracy is a percentage of the setting value. Settings available are 70 ps, 140 ps, and 280 ps in addition to the default value of none.
8. Jitter values measured with the internal oscillator operating. The jitter values will increase with loading of the PLD fabric and in the presence of SSO noise.

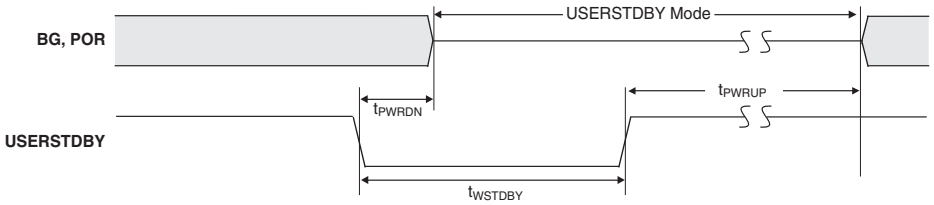
MachXO2 Oscillator Output Frequency

Symbol	Parameter	Min.	Typ.	Max	Units
f_{MAX}	Oscillator Output Frequency (Commercial Grade Devices, 0 to 85°C)	125.685	133	140.315	MHz
	Oscillator Output Frequency (Industrial Grade Devices, –40 °C to 100 °C)	124.355	133	141.645	MHz
t_{DT}	Output Clock Duty Cycle	43	50	57	%
t_{OPJIT}[1]	Output Clock Period Jitter	0.01	0.012	0.02	UIPP
$t_{STABLEOSC}$	STDBY Low to Oscillator Stable	0.01	0.05	0.1	µs

1. Output Clock Period Jitter specified at 133 MHz. The values for lower frequencies will be smaller UIPP. The typical value for 133 MHz is 95 ps and for 2.08 MHz the typical value is 1.54 ns.

MachXO2 Standby Mode Timing – HC/HE Devices

Symbol	Parameter	Device	Min.	Typ.	Max	Units
t_{PWRDN}	USERSTDBY High to Stop	All	—	—	9	ns
t_{PWRUP}	USERSTDBY Low to Power Up	LCMXO2-256		—		µs
		LCMXO2-640		—		µs
		LCMXO2-640U		—		µs
		LCMXO2-1200	20	—	50	µs
		LCMXO2-1200U		—		µs
		LCMXO2-2000		—		µs
		LCMXO2-2000U		—		µs
		LCMXO2-4000		—		µs
		LCMXO2-7000		—		µs
t_{WSTDBY}	USERSTDBY Pulse Width	All	18	—	—	ns



MachXO2 Standby Mode Timing – ZE Devices

Symbol	Parameter	Device	Min.	Typ.	Max	Units
t_{PWRDN}	USERSTDBY High to Stop	All	—	—	13	ns
t_{PWRUP}	USERSTDBY Low to Power Up	LCMXO2-256		—		µs
		LCMXO2-640		—		µs
		LCMXO2-1200	20	—	50	µs
		LCMXO2-2000		—		µs
		LCMXO2-4000		—		µs
		LCMXO2-7000		—		µs
t_{WSTDBY}	USERSTDBY Pulse Width	All	19	—	—	ns
$t_{BNDGAPSTBL}$	USERSTDBY High to Bandgap Stable	All	—	—	15	ns

Flash Download Time[1, 2]

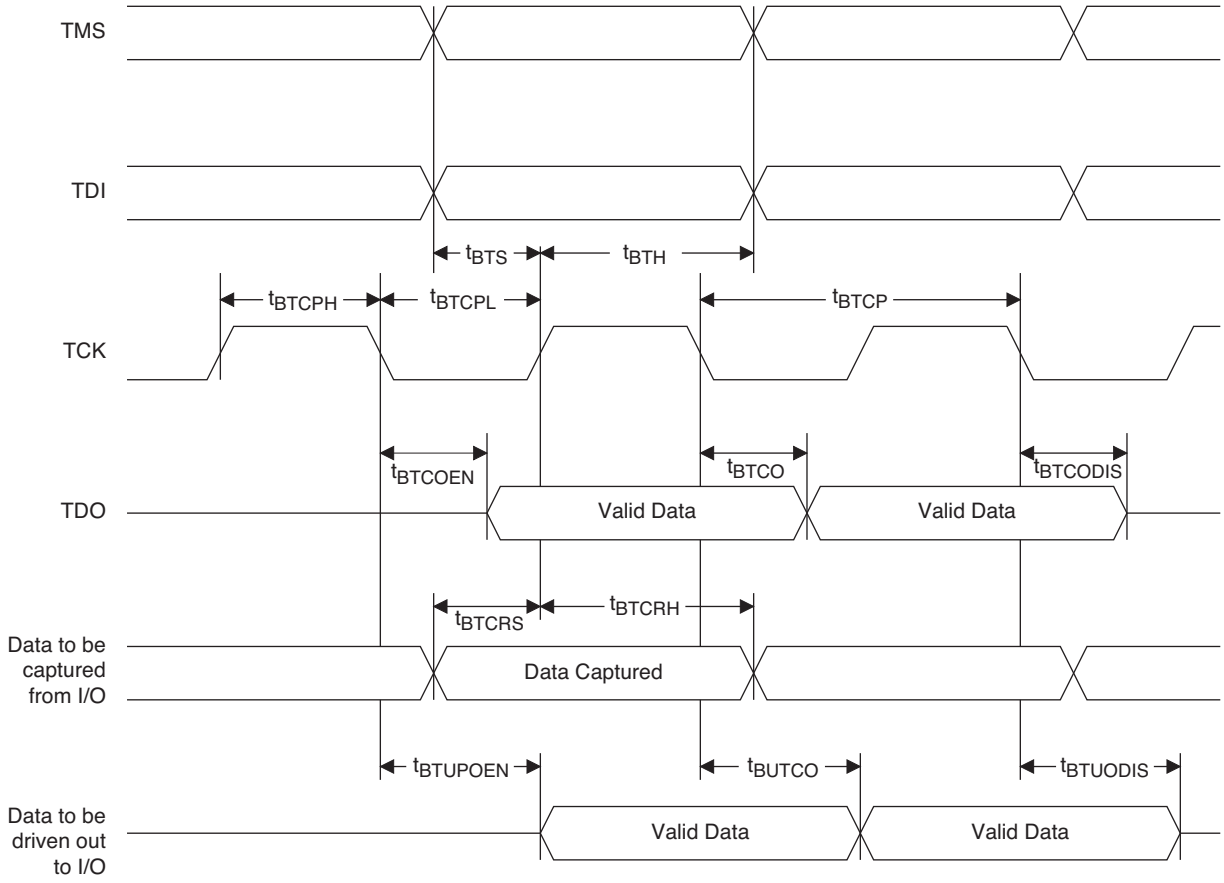
Symbol	Parameter	Device	Typ.	Units
$t_{REFRESH}$	POR to Device I/O Active	LCMXO2-256	0.6	ms
		LCMXO2-640	1.0	ms
		LCMXO2-640U	1.9	ms
		LCMXO2-1200	1.9	ms
		LCMXO2-1200U	1.4	ms
		LCMXO2-2000	1.4	ms
		LCMXO2-2000U	2.4	ms
		LCMXO2-4000	2.4	ms
		LCMXO2-7000	3.8	ms

1. Assumes sysMEM EBR initialized to an all zero pattern if they are used.
2. The Flash download time is measured starting from the maximum voltage of POR trip point.

JTAG Port Timing Specifications

Symbol	Parameter	Min.	Max.	Units
f_{MAX}	TCK clock frequency	—	25	MHz
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	10	—	ns
t_{BTH}	TCK [BSCAN] hold time	8	—	ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	20	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

Figure 3-12. JTAG Port Timing Waveforms



sysCONFIG Port Timing Specifications

Symbol	Parameter		Min.	Max.	Units
All Configuration Modes					
t_{PRGM}	PROGRAMN low pulse accept		55	—	ns
t_{PRGMJ}	PROGRAMN low pulse rejection		—	25	ns
t_{INITL}	INITN low time	LCMXO2-256	—	30	µs
		LCMXO2-640	—	35	µs
		LCMXO2-640U/ LCMXO2-1200	—	55	µs
		LCMXO2-1200U/ LCMXO2-2000	—	70	µs
		LCMXO2-2000U/ LCMXO2-4000	—	105	µs
		LCMXO2-7000	—	130	µs
$t_{DPPINIT}$	PROGRAMN low to INITN low		—	150	ns
$t_{DPPDONE}$	PROGRAMN low to DONE low		—	150	ns
t_{IODISS}	PROGRAMN low to I/O disable		—	120	ns
Slave SPI					
f_{MAX}	CCLK clock frequency		—	66	MHz
t_{CCLKH}	CCLK clock pulse width high		7.5	—	ns
t_{CCLKL}	CCLK clock pulse width low		7.5	—	ns
t_{STSU}	CCLK setup time		2	—	ns
t_{STH}	CCLK hold time		0	—	ns
t_{STCO}	CCLK falling edge to valid output		—	10	ns
t_{STOZ}	CCLK falling edge to valid disable		—	10	ns
t_{STOV}	CCLK falling edge to valid enable		—	10	ns
t_{SCS}	Chip select high time		25	—	ns
t_{SCSS}	Chip select setup time		3	—	ns
t_{SCSH}	Chip select hold time		3	—	ns
Master SPI					
f_{MAX}	MCLK clock frequency		—	133	MHz
t_{MCLKH}	MCLK clock pulse width high		3.75	—	ns
t_{MCLKL}	MCLK clock pulse width low		3.75	—	ns
t_{STSU}	MCLK setup time		5	—	ns
t_{STH}	MCLK hold time		1	—	ns
t_{CSSPI}	INITN high to chip select low		100	200	ns
t_{MCLK}	INITN high to first MCLK edge		0.75	1	µs

I^2C Port Timing Specifications[1, 2]

Symbol	Parameter	Min.	Max.	Units
f_{MAX}	Maximum SCL clock frequency	—	400	kHz

1. MachXO2 supports the following modes:
   • Standard-mode (Sm), with a bit rate up to 100 kbit/s (user and configuration mode)
   • Fast-mode (Fm), with a bit rate up to 400 kbit/s (user and configuration mode)
2. Refer to the I^2C specification for timing requirements.

SPI Port Timing Specifications[1]

Symbol	Parameter	Min.	Max.	Units
f_{MAX}	Maximum SCK clock frequency	—	45	MHz

1. Applies to user mode only. For configuration mode timing specifications, refer to sysCONFIG Port Timing Specifications table in this data sheet.

Switching Test Conditions

Figure 3-13 shows the output test load used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-5.

Figure 3-13. Output Test Load, LVTTL and LVCMOS Standards

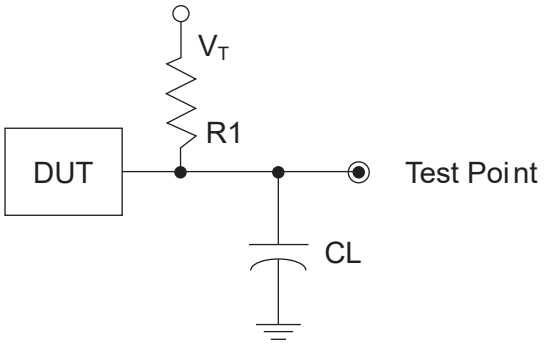


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R1	CL	Timing Ref.	VT
LVTTL and LVCMOS settings (L -> H, H -> L)	∞	0pF	LVTTL, LVCMOS 3.3 = 1.5 V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVTTL and LVCMOS 3.3 (Z -> H)	188	0pF	1.5 V	V_{OL}
LVTTL and LVCMOS 3.3 (Z -> L)			1.5 V	V_{OH}
Other LVCMOS (Z -> H)			$V_{CCIO}/2$	V_{OL}
Other LVCMOS (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVTTL + LVCMOS (H -> Z)			V_{OH} – 0.15 V	V_{OL}
LVTTL + LVCMOS (L -> Z)			V_{OL} – 0.15 V	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number]_[A/B/C/D]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B/C/D] indicates the PIO within the group to which the pad is connected. Some of these user-programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic. During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up, pull-down or buskeeper resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-down resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-down resistor enabled. Some pins, such as PROGRAMN and JTAG pins, default to tri-stated I/Os with pull-up resistors enabled when the device is erased.
NC	—	No connect.
GND	—	GND – Ground. Dedicated pins. It is recommended that all GNDs are tied together. For QFN 48 package, the exposed die pad is the device ground.
VCC	—	V_{CC} – The power supply pins for core logic. Dedicated pins. It is recommended that all VCCs are tied to the same supply.
VCCIOx	—	VCCIO – The power supply pins for I/O Bank x. Dedicated pins. It is recommended that all VCCIOs located in the same bank are tied to the same supply.
PLL and Clock Functions (Used as user-programmable I/O pins when not used for PLL or clock pins)		
[LOC]_GPLL[T, C]_IN	—	Reference Clock (PLL) input pads: [LOC] indicates location. Valid designations are L (Left PLL) and R (Right PLL). T = true and C = complement.
[LOC]_GPLL[T, C]_FB	—	Optional Feedback (PLL) input pads: [LOC] indicates location. Valid designations are L (Left PLL) and R (Right PLL). T = true and C = complement.
PCLK [n]_[2:0]	—	Primary Clock pads. One to three clock pads per side.
Test and Programming (Dual function pins used for test access port and during sysCONFIG™)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin – Test Data output pin used to shift data out of the device using 1149.1.
JTAGENB	I	Optionally controls behavior of TDI, TDO, TMS, TCK. If the device is configured to use the JTAG pins (TDI, TDO, TMS, TCK) as general purpose I/O, then: If JTAGENB is low: TDI, TDO, TMS and TCK can function a general purpose I/O. If JTAGENB is high: TDI, TDO, TMS and TCK function as JTAG pins. For more details, refer to TN1204, MachXO2 Programming and Configuration Usage Guide.
Configuration (Dual function pins used during sysCONFIG)		
PROGRAMN	I	Initiates configuration sequence when asserted low. During configuration, or when reserved as PROGRAMN in user mode, this pin always has an active pull-up.

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Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
INITN	I/O	Open Drain pin. Indicates the FPGA is ready to be configured. During configuration, or when reserved as INITn in user mode, this pin has an active pull-up.
DONE	I/O	Open Drain pin. Indicates that the configuration sequence is complete, and the start-up sequence is in progress. During configuration, or when reserved as DONE in user mode, this pin has an active pull-up.
MCLK/CCLK	I/O	Input Configuration Clock for configuring an FPGA in Slave SPI mode. Output Configuration Clock for configuring an FPGA in SPI and SPIm configuration modes.
SN	I	Slave SPI active low chip select input.
CSSPIN	I/O	Master SPI active low chip select output.
SI/SPISI	I/O	Slave SPI serial data input and master SPI serial data output.
SO/SPISO	I/O	Slave SPI serial data output and master SPI serial data input.
SCL	I/O	Slave I^2C clock input and master I^2C clock output.
SDA	I/O	Slave I^2C data input and master I^2C data output.

Pinout Information Summary

	MachXO2-256					MachXO2-640			MachXO2-640U
	32 QFN[1]	48 QFN[3]	64 ucBGA	100 TQFP	132 csBGA	48 QFN[3]	100 TQFP	132 csBGA	144 TQFP
General Purpose I/O per Bank									
Bank 0	8	10	9	13	13	10	18	19	27
Bank 1	2	10	12	14	14	10	20	20	26
Bank 2	9	10	11	14	14	10	20	20	28
Bank 3	2	10	12	14	14	10	20	20	26
Bank 4	0	0	0	0	0	0	0	0	0
Bank 5	0	0	0	0	0	0	0	0	0
Total General Purpose Single Ended I/O	21	40	44	55	55	40	78	79	107
Differential I/O per Bank									
Bank 0	4	5	5	7	7	5	9	10	14
Bank 1	1	5	6	7	7	5	10	10	13
Bank 2	4	5	5	7	7	5	10	10	14
Bank 3	1	5	6	7	7	5	10	10	13
Bank 4	0	0	0	0	0	0	0	0	0
Bank 5	0	0	0	0	0	0	0	0	0
Total General Purpose Differential I/O	10	20	22	28	28	20	39	40	54
Dual Function I/O	22	25	27	29	29	25	29	29	33
High-speed Differential I/O									
Bank 0	0	0	0	0	0	0	0	0	7
Gearboxes									
Number of 7:1 or 8:1 Output Gearbox Available (Bank 0)	0	0	0	0	0	0	0	0	7
Number of 7:1 or 8:1 Input Gearbox Available (Bank 2)	0	0	0	0	0	0	0	0	7
DQS Groups									
Bank 1	0	0	0	0	0	0	0	0	2
VCCIO Pins									
Bank 0	2	2	2	2	2	2	2	2	3
Bank 1	1	1	2	2	2	1	2	2	3
Bank 2	2	2	2	2	2	2	2	2	3
Bank 3	1	1	2	2	2	1	2	2	3
Bank 4	0	0	0	0	0	0	0	0	0
Bank 5	0	0	0	0	0	0	0	0	0
VCC	2	2	2	2	2	2	2	2	4
GND[2]	2	1	8	8	8	1	8	10	12
NC	0	0	1	26	58	0	3	32	8
Reserved for Configuration	1	1	1	1	1	1	1	1	1
Total Count of Bonded Pins	32	49	64	100	132	49	100	132	144

1. Lattice recommends soldering the central thermal pad onto the top PCB ground for improved thermal resistance.
2. For 48 QFN package, exposed die pad is the device ground.
3. 48-pin QFN information is 'Advanced'.

	MachXO2-1200					MachXO2-1200U
	100 TQFP	132 csBGA	144 TQFP	25 WLCSP	32 QFN[1]	256 ftBGA
General Purpose I/O per Bank						
Bank 0	18	25	27	11	9	50
Bank 1	21	26	26	0	2	52
Bank 2	20	28	28	7	9	52
Bank 3	20	25	26	0	2	16
Bank 4	0	0	0	0	0	16
Bank 5	0	0	0	0	0	20
Total General Purpose Single Ended I/O	79	104	107	18	22	206
Differential I/O per Bank						
Bank 0	9	13	14	5	4	25
Bank 1	10	13	13	0	1	26
Bank 2	10	14	14	2	4	26
Bank 3	10	12	13	0	1	8
Bank 4	0	0	0	0	0	8
Bank 5	0	0	0	0	0	10
Total General Purpose Differential I/O	39	52	54	7	10	103
Dual Function I/O	31	33	33	18	22	33
High-speed Differential I/O						
Bank 0	4	7	7	0	0	14
Gearboxes						
Number of 7:1 or 8:1 Output Gearbox Available (Bank 0)	4	7	7	0	0	14
Number of 7:1 or 8:1 Input Gearbox Available (Bank 2)	5	7	7	0	2	14
DQS Groups						
Bank 1	1	2	2	0	0	2
VCCIO Pins						
Bank 0	2	3	3	1	2	4
Bank 1	2	3	3	0	1	4
Bank 2	2	3	3	1	2	4
Bank 3	3	3	3	0	1	1
Bank 4	0	0	0	0	0	2
Bank 5	0	0	0	0	0	1
VCC	2	4	4	2	2	8
GND	8	10	12	2	2	24
NC	1	1	8	0	0	1
Reserved for Configuration	1	1	1	1	1	1
Total Count of Bonded Pins	100	132	144	25	32	256

1. Lattice recommends soldering the central thermal pad onto the top PCB ground for improved thermal resistance.

	MachXO2-2000						MachXO2-2000U
	49 WLCSP	100 TQFP	132 csBGA	144 TQFP	256 caBGA	256 ftBGA	484 ftBGA
General Purpose I/O per Bank							
Bank 0	19	18	25	27	50	50	70
Bank 1	0	21	26	28	52	52	68
Bank 2	13	20	28	28	52	52	72
Bank 3	0	6	7	8	16	16	24
Bank 4	0	6	8	10	16	16	16
Bank 5	6	8	10	10	20	20	28
Total General Purpose Single-Ended I/O	38	79	104	111	206	206	278
Differential I/O per Bank							
Bank 0	7	9	13	14	25	25	35
Bank 1	0	10	13	14	26	26	34
Bank 2	6	10	14	14	26	26	36
Bank 3	0	3	3	4	8	8	12
Bank 4	0	3	4	5	8	8	8
Bank 5	3	4	5	5	10	10	14
Total General Purpose Differential I/O	16	39	52	56	103	103	139
Dual Function I/O	24	31	33	33	33	33	37
High-speed Differential I/O							
Bank 0	5	4	8	9	14	14	18
Gearboxes							
Number of 7:1 or 8:1 Output Gearbox Available (Bank 0)	5	4	8	9	14	14	18
Number of 7:1 or 8:1 Input Gearbox Available (Bank 2)	6	10	14	14	14	14	18
DQS Groups							
Bank 1	0	1	2	2	2	2	2
VCCIO Pins							
Bank 0	2	2	3	3	4	4	10
Bank 1	0	2	3	3	4	4	10
Bank 2	1	2	3	3	4	4	10
Bank 3	0	1	1	1	1	1	3
Bank 4	0	1	1	1	2	2	4
Bank 5	1	1	1	1	1	1	3
VCC	2	2	4	4	8	8	12
GND	4	8	10	12	24	24	48
NC	0	1	1	4	1	1	105
Reserved for Configuration	1	1	1	1	v	1	1
Total Count of Bonded Pins	39	100	132	144	256	256	484

	MachXO2-4000							
	84 QFN	132 csBGA	144 TQFP	184 csBGA	256 caBGA	256 ftBGA	332 caBGA	484 fpBGA
General Purpose I/O per Bank								
Bank 0	27	25	27	37	50	50	68	70
Bank 1	10	26	29	37	52	52	68	68
Bank 2	22	28	29	39	52	52	70	72
Bank 3	0	7	9	10	16	16	24	24
Bank 4	9	8	10	12	16	16	16	16
Bank 5	0	10	10	15	20	20	28	28
Total General Purpose Single Ended I/O	68	104	114	150	206	206	274	278
Differential I/O per Bank								
Bank 0	13	13	14	18	25	25	34	35
Bank 1	4	13	14	18	26	26	34	34
Bank 2	11	14	14	19	26	26	35	36
Bank 3	0	3	4	4	8	8	12	12
Bank 4	4	4	5	6	8	8	8	8
Bank 5	0	5	5	7	10	10	14	14
Total General Purpose Differential I/O	32	52	56	72	103	103	137	139
Dual Function I/O	28	37	37	37	37	37	37	37
High-speed Differential I/O								
Bank 0	8	8	9	8	18	18	18	18
Gearboxes								
Number of 7:1 or 8:1 Output Gearbox Available (Bank 0)	8	8	9	9	18	18	18	18
Number of 7:1 or 8:1 Input Gearbox Available (Bank 2)	11	14	14	12	18	18	18	18
DQS Groups								
Bank 1	1	2	2	2	2	2	2	2
VCCIO Pins								
Bank 0	3	3	3	3	4	4	4	10
Bank 1	1	3	3	3	4	4	4	10
Bank 2	2	3	3	3	4	4	4	10
Bank 3	1	1	1	1	1	1	2	3
Bank 4	1	1	1	1	2	2	1	4
Bank 5	1	1	1	1	1	1	2	3
VCC	4	4	4	4	8	8	8	12
GND	4	10	12	16	24	24	27	48
NC	1	1	1	1	1	1	5	105
Reserved for configuration	1	1	1	1	1	1	1	1
Total Count of Bonded Pins	84	132	144	184	256	256	332	484

	MachXO2-7000					
	144 TQFP	**256 caBGA**	**256 ftBGA**	**332 caBGA**	**400 caBGA**	**484 fpBGA**
General Purpose I/O per Bank						
Bank 0	27	50	50	68	83	82
Bank 1	29	52	52	70	84	84
Bank 2	29	52	52	70	84	84
Bank 3	9	16	16	24	28	28
Bank 4	10	16	16	16	24	24
Bank 5	10	20	20	30	32	32
Total General Purpose Single Ended I/O	114	206	206	278	335	334
Differential I/O per Bank						
Bank 0	14	25	25	34	42	41
Bank 1	14	26	26	35	42	42
Bank 2	14	26	26	35	42	42
Bank 3	4	8	8	12	14	14
Bank 4	5	8	8	8	12	12
Bank 5	5	10	10	15	16	16
Total General Purpose Differential I/O	56	103	103	139	168	167
Dual Function I/O	37	37	37	37	37	37
High-speed Differential I/O						
Bank 0	9	20	20	21	21	21
Gearboxes						
Number of 7:1 or 8:1 Output Gearbox Available (Bank 0)	9	20	20	21	21	21
Number of 7:1 or 8:1 Input Gearbox Available (Bank 2)	14	20	20	21	21	21
DQS Groups						
Bank 1	2	2	2	2	2	2
VCCIO Pins						
Bank 0	3	4	4	4	5	10
Bank 1	3	4	4	4	5	10
Bank 2	3	4	4	4	5	10
Bank 3	1	1	1	2	2	3
Bank 4	1	2	2	1	2	4
Bank 5	1	1	1	2	2	3
VCC	4	8	8	8	10	12
GND	12	24	24	27	33	48
NC	1	1	1	1	0	49
Reserved for Configuration	1	1	1	1	1	1
Total Count of Bonded Pins	144	256	256	332	400	484

For Further Information

For further information regarding logic signal connections for various packages please refer to the MachXO2 Device Pinout Files.

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Users must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- Thermal Management document
- TN1198, Power Estimation and Management for MachXO2 Devices
- The Power Calculator tool is included with the Lattice design tools, or as a standalone download from www.latticesemi.com/software

MachXO2 Family Data Sheet Ordering Information

MachXO2 Part Number Description

LCMXO2 – XXXX X X X – X XXXXXX X XX XX

Device Family
MachXO2 PLD

Logic Capacity
256 = 256 LUTs
640 = 640 LUTs
1200 = 1280 LUTs
2000 = 2112 LUTs
4000 = 4320 LUTs
7000 = 6864 LUTs

I/O Count
Blank = Standard Device
U = Ultra High I/O Device

Power/Performance
Z = Low Power
H = High Performance

Supply Voltage
C = 2.5 V / 3.3 V
E = 1.2 V

Speed
1 = Slowest
2
3 = Fastest
} Low Power

4 = Slowest
5
6 = Fastest
} High Performance

Device Status
Blank = Production Device
ES = Engineering Sample
R1 = Production Release 1 Device
1K = WLCSP Package, 1,000 parts per reel

Shipping Method
Blank = Trays
TR = Tape and Reel

Grade
C = Commercial
I = Industrial

Package
UWG25 = 25-Ball Halogen-Free WLCSP (0.4 mm Pitch)
SG32 = 32-Pin Halogen-Free QFN (0.5 mm Pitch)
SG48 = 48-Pin Halogen-Free QFN (0.5 mm Pitch)
UWG49 = 49-ball Halogen-Free WLCSP (0.4 mm Pitch)
UMG64 = 64-Ball Halogen-Free ucBGA (0.4 mm Pitch)
QN84 = 84-Pin Halogen-Free QFN (0.5 mm Pitch)
TG100 = 100-Pin Halogen-Free TQFP
TG144 = 144-Pin Halogen-Free TQFP
MG132 = 132-Ball Halogen-Free csBGA (0.5 mm Pitch)
MG184 = 184-Ball Halogen-Free csBGA (0.5 mm Pitch)
BG256 = 256-Ball Halogen-Free caBGA (0.8 mm Pitch)
FTG256 = 256-Ball Halogen-Free ftBGA (1.0 mm Pitch)
BG332 = 332-Ball Halogen-Free caBGA (0.8 mm Pitch)
FG484 = 484-Ball Halogen-Free fpBGA (1.0 mm Pitch)

* 48-pin QFN information is 'Advanced'.

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Ordering Information

MachXO2 devices have top-side markings, for commercial and industrial grades, as shown below:





Notes:

1. Markings are abbreviated for small packages.

2. See PCN 05A-12 for information regarding a change to the top-side mark logo.

Ultra Low Power Commercial Grade Devices, Halogen Free (RoHS) Packaging

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-256ZE-1SG32C	256	1.2 V	–1	Halogen-Free QFN	32	COM
LCMXO2-256ZE-2SG32C	256	1.2 V	–2	Halogen-Free QFN	32	COM
LCMXO2-256ZE-3SG32C	256	1.2 V	–3	Halogen-Free QFN	32	COM
LCMXO2-256ZE-1UMG64C	256	1.2 V	–1	Halogen-Free ucBGA	64	COM
LCMXO2-256ZE-2UMG64C	256	1.2 V	–2	Halogen-Free ucBGA	64	COM
LCMXO2-256ZE-3UMG64C	256	1.2 V	–3	Halogen-Free ucBGA	64	COM
LCMXO2-256ZE-1TG100C	256	1.2 V	–1	Halogen-Free TQFP	100	COM
LCMXO2-256ZE-2TG100C	256	1.2 V	–2	Halogen-Free TQFP	100	COM
LCMXO2-256ZE-3TG100C	256	1.2 V	–3	Halogen-Free TQFP	100	COM
LCMXO2-256ZE-1MG132C	256	1.2 V	–1	Halogen-Free csBGA	132	COM
LCMXO2-256ZE-2MG132C	256	1.2 V	–2	Halogen-Free csBGA	132	COM
LCMXO2-256ZE-3MG132C	256	1.2 V	–3	Halogen-Free csBGA	132	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-640ZE-1TG100C	640	1.2 V	–1	Halogen-Free TQFP	100	COM
LCMXO2-640ZE-2TG100C	640	1.2 V	–2	Halogen-Free TQFP	100	COM
LCMXO2-640ZE-3TG100C	640	1.2 V	–3	Halogen-Free TQFP	100	COM
LCMXO2-640ZE-1MG132C	640	1.2 V	–1	Halogen-Free csBGA	132	COM
LCMXO2-640ZE-2MG132C	640	1.2 V	–2	Halogen-Free csBGA	132	COM
LCMXO2-640ZE-3MG132C	640	1.2 V	–3	Halogen-Free csBGA	132	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200ZE-1SG32C	1280	1.2 V	–1	Halogen-Free QFN	32	COM
LCMXO2-1200ZE-2SG32C	1280	1.2 V	–2	Halogen-Free QFN	32	COM
LCMXO2-1200ZE-3SG32C	1280	1.2 V	–3	Halogen-Free QFN	32	COM
LCMXO2-1200ZE-1TG100C	1280	1.2 V	–1	Halogen-Free TQFP	100	COM
LCMXO2-1200ZE-2TG100C	1280	1.2 V	–2	Halogen-Free TQFP	100	COM
LCMXO2-1200ZE-3TG100C	1280	1.2 V	–3	Halogen-Free TQFP	100	COM
LCMXO2-1200ZE-1MG132C	1280	1.2 V	–1	Halogen-Free csBGA	132	COM
LCMXO2-1200ZE-2MG132C	1280	1.2 V	–2	Halogen-Free csBGA	132	COM
LCMXO2-1200ZE-3MG132C	1280	1.2 V	–3	Halogen-Free csBGA	132	COM
LCMXO2-1200ZE-1TG144C	1280	1.2 V	–1	Halogen-Free TQFP	144	COM
LCMXO2-1200ZE-2TG144C	1280	1.2 V	–2	Halogen-Free TQFP	144	COM
LCMXO2-1200ZE-3TG144C	1280	1.2 V	–3	Halogen-Free TQFP	144	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000ZE-1TG100C	2112	1.2 V	–1	Halogen-Free TQFP	100	COM
LCMXO2-2000ZE-2TG100C	2112	1.2 V	–2	Halogen-Free TQFP	100	COM
LCMXO2-2000ZE-3TG100C	2112	1.2 V	–3	Halogen-Free TQFP	100	COM
LCMXO2-2000ZE-1MG132C	2112	1.2 V	–1	Halogen-Free csBGA	132	COM
LCMXO2-2000ZE-2MG132C	2112	1.2 V	–2	Halogen-Free csBGA	132	COM
LCMXO2-2000ZE-3MG132C	2112	1.2 V	–3	Halogen-Free csBGA	132	COM
LCMXO2-2000ZE-1TG144C	2112	1.2 V	–1	Halogen-Free TQFP	144	COM
LCMXO2-2000ZE-2TG144C	2112	1.2 V	–2	Halogen-Free TQFP	144	COM
LCMXO2-2000ZE-3TG144C	2112	1.2 V	–3	Halogen-Free TQFP	144	COM
LCMXO2-2000ZE-1BG256C	2112	1.2 V	–1	Halogen-Free caBGA	256	COM
LCMXO2-2000ZE-2BG256C	2112	1.2 V	–2	Halogen-Free caBGA	256	COM
LCMXO2-2000ZE-3BG256C	2112	1.2 V	–3	Halogen-Free caBGA	256	COM
LCMXO2-2000ZE-1FTG256C	2112	1.2 V	–1	Halogen-Free ftBGA	256	COM
LCMXO2-2000ZE-2FTG256C	2112	1.2 V	–2	Halogen-Free ftBGA	256	COM
LCMXO2-2000ZE-3FTG256C	2112	1.2 V	–3	Halogen-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-4000ZE-1QN84C	4320	1.2 V	–1	Halogen-Free QFN	84	COM
LCMXO2-4000ZE-2QN84C	4320	1.2 V	–2	Halogen-Free QFN	84	COM
LCMXO2-4000ZE-3QN84C	4320	1.2 V	–3	Halogen-Free QFN	84	COM
LCMXO2-4000ZE-1MG132C	4320	1.2 V	–1	Halogen-Free csBGA	132	COM
LCMXO2-4000ZE-2MG132C	4320	1.2 V	–2	Halogen-Free csBGA	132	COM
LCMXO2-4000ZE-3MG132C	4320	1.2 V	–3	Halogen-Free csBGA	132	COM
LCMXO2-4000ZE-1TG144C	4320	1.2 V	–1	Halogen-Free TQFP	144	COM
LCMXO2-4000ZE-2TG144C	4320	1.2 V	–2	Halogen-Free TQFP	144	COM
LCMXO2-4000ZE-3TG144C	4320	1.2 V	–3	Halogen-Free TQFP	144	COM
LCMXO2-4000ZE-1BG256C	4320	1.2 V	–1	Halogen-Free caBGA	256	COM
LCMXO2-4000ZE-2BG256C	4320	1.2 V	–2	Halogen-Free caBGA	256	COM
LCMXO2-4000ZE-3BG256C	4320	1.2 V	–3	Halogen-Free caBGA	256	COM
LCMXO2-4000ZE-1FTG256C	4320	1.2 V	–1	Halogen-Free ftBGA	256	COM
LCMXO2-4000ZE-2FTG256C	4320	1.2 V	–2	Halogen-Free ftBGA	256	COM
LCMXO2-4000ZE-3FTG256C	4320	1.2 V	–3	Halogen-Free ftBGA	256	COM
LCMXO2-4000ZE-1BG332C	4320	1.2 V	–1	Halogen-Free caBGA	332	COM
LCMXO2-4000ZE-2BG332C	4320	1.2 V	–2	Halogen-Free caBGA	332	COM
LCMXO2-4000ZE-3BG332C	4320	1.2 V	–3	Halogen-Free caBGA	332	COM
LCMXO2-4000ZE-1FG484C	4320	1.2 V	–1	Halogen-Free fpBGA	484	COM
LCMXO2-4000ZE-2FG484C	4320	1.2 V	–2	Halogen-Free fpBGA	484	COM
LCMXO2-4000ZE-3FG484C	4320	1.2 V	–3	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-7000ZE-1TG144C	6864	1.2 V	–1	Halogen-Free TQFP	144	COM
LCMXO2-7000ZE-2TG144C	6864	1.2 V	–2	Halogen-Free TQFP	144	COM
LCMXO2-7000ZE-3TG144C	6864	1.2 V	–3	Halogen-Free TQFP	144	COM
LCMXO2-7000ZE-1BG256C	6864	1.2 V	–1	Halogen-Free caBGA	256	COM
LCMXO2-7000ZE-2BG256C	6864	1.2 V	–2	Halogen-Free caBGA	256	COM
LCMXO2-7000ZE-3BG256C	6864	1.2 V	–3	Halogen-Free caBGA	256	COM
LCMXO2-7000ZE-1FTG256C	6864	1.2 V	–1	Halogen-Free ftBGA	256	COM
LCMXO2-7000ZE-2FTG256C	6864	1.2 V	–2	Halogen-Free ftBGA	256	COM
LCMXO2-7000ZE-3FTG256C	6864	1.2 V	–3	Halogen-Free ftBGA	256	COM
LCMXO2-7000ZE-1BG332C	6864	1.2 V	–1	Halogen-Free caBGA	332	COM
LCMXO2-7000ZE-2BG332C	6864	1.2 V	–2	Halogen-Free caBGA	332	COM
LCMXO2-7000ZE-3BG332C	6864	1.2 V	–3	Halogen-Free caBGA	332	COM
LCMXO2-7000ZE-1FG484C	6864	1.2 V	–1	Halogen-Free fpBGA	484	COM
LCMXO2-7000ZE-2FG484C	6864	1.2 V	–2	Halogen-Free fpBGA	484	COM
LCMXO2-7000ZE-3FG484C	6864	1.2 V	–3	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200ZE-1TG100CR1[1]	1280	1.2 V	–1	Halogen-Free TQFP	100	COM
LCMXO2-1200ZE-2TG100CR1[1]	1280	1.2 V	–2	Halogen-Free TQFP	100	COM
LCMXO2-1200ZE-3TG100CR1[1]	1280	1.2 V	–3	Halogen-Free TQFP	100	COM
LCMXO2-1200ZE-1MG132CR1[1]	1280	1.2 V	–1	Halogen-Free csBGA	132	COM
LCMXO2-1200ZE-2MG132CR1[1]	1280	1.2 V	–2	Halogen-Free csBGA	132	COM
LCMXO2-1200ZE-3MG132CR1[1]	1280	1.2 V	–3	Halogen-Free csBGA	132	COM
LCMXO2-1200ZE-1TG144CR1[1]	1280	1.2 V	–1	Halogen-Free TQFP	144	COM
LCMXO2-1200ZE-2TG144CR1[1]	1280	1.2 V	–2	Halogen-Free TQFP	144	COM
LCMXO2-1200ZE-3TG144CR1[1]	1280	1.2 V	–3	Halogen-Free TQFP	144	COM

1. Specifications for the “LCMXO2-1200ZE-speed package CR1” are the same as the “LCMXO2-1200ZE-speed package C” devices respectively, except as specified in the R1 Device Specifications section of this data sheet.

High-Performance Commercial Grade Devices with Voltage Regulator, Halogen Free (RoHS) Packaging

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-256HC-4SG32C	256	2.5 V / 3.3 V	–4	Halogen-Free QFN	32	COM
LCMXO2-256HC-5SG32C	256	2.5 V / 3.3 V	–5	Halogen-Free QFN	32	COM
LCMXO2-256HC-6SG32C	256	2.5 V / 3.3 V	–6	Halogen-Free QFN	32	COM
LCMXO2-256HC-4SG48C	256	2.5 V / 3.3 V	–4	Halogen-Free QFN	48	COM
LCMXO2-256HC-5SG48C	256	2.5 V / 3.3 V	–5	Halogen-Free QFN	48	COM
LCMXO2-256HC-6SG48C	256	2.5 V / 3.3 V	–6	Halogen-Free QFN	48	COM
LCMXO2-256HC-4UMG64C	256	2.5 V / 3.3 V	–4	Halogen-Free ucBGA	64	COM
LCMXO2-256HC-5UMG64C	256	2.5 V / 3.3 V	–5	Halogen-Free ucBGA	64	COM
LCMXO2-256HC-6UMG64C	256	2.5 V / 3.3 V	–6	Halogen-Free ucBGA	64	COM
LCMXO2-256HC-4TG100C	256	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	COM
LCMXO2-256HC-5TG100C	256	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	COM
LCMXO2-256HC-6TG100C	256	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	COM
LCMXO2-256HC-4MG132C	256	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-256HC-5MG132C	256	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-256HC-6MG132C	256	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-640HC-4SG48C	640	2.5 V / 3.3 V	–4	Halogen-Free QFN	48	COM
LCMXO2-640HC-5SG48C	640	2.5 V / 3.3 V	–5	Halogen-Free QFN	48	COM
LCMXO2-640HC-6SG48C	640	2.5 V / 3.3 V	–6	Halogen-Free QFN	48	COM
LCMXO2-640HC-4TG100C	640	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	COM
LCMXO2-640HC-5TG100C	640	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	COM
LCMXO2-640HC-6TG100C	640	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	COM
LCMXO2-640HC-4MG132C	640	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-640HC-5MG132C	640	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-640HC-6MG132C	640	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-640UHC-4TG144C	640	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-640UHC-5TG144C	640	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-640UHC-6TG144C	640	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200HC-4SG32C	1280	2.5 V / 3.3 V	–4	Halogen-Free QFN	32	COM
LCMXO2-1200HC-5SG32C	1280	2.5 V / 3.3 V	–5	Halogen-Free QFN	32	COM
LCMXO2-1200HC-6SG32C	1280	2.5 V / 3.3 V	–6	Halogen-Free QFN	32	COM
LCMXO2-1200HC-4TG100C	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	COM
LCMXO2-1200HC-5TG100C	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	COM
LCMXO2-1200HC-6TG100C	1280	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	COM
LCMXO2-1200HC-4MG132C	1280	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-1200HC-5MG132C	1280	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-1200HC-6MG132C	1280	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	COM
LCMXO2-1200HC-4TG144C	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-1200HC-5TG144C	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-1200HC-6TG144C	1280	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200UHC-4FTG256C	1280	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	COM
LCMXO2-1200UHC-5FTG256C	1280	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	COM
LCMXO2-1200UHC-6FTG256C	1280	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000HC-4TG100C	2112	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	COM
LCMXO2-2000HC-5TG100C	2112	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	COM
LCMXO2-2000HC-6TG100C	2112	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	COM
LCMXO2-2000HC-4MG132C	2112	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-2000HC-5MG132C	2112	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-2000HC-6MG132C	2112	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	COM
LCMXO2-2000HC-4TG144C	2112	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-2000HC-5TG144C	2112	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-2000HC-6TG144C	2112	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	COM
LCMXO2-2000HC-4BG256C	2112	2.5 V / 3.3 V	–4	Halogen-Free caBGA	256	COM
LCMXO2-2000HC-5BG256C	2112	2.5 V / 3.3 V	–5	Halogen-Free caBGA	256	COM
LCMXO2-2000HC-6BG256C	2112	2.5 V / 3.3 V	–6	Halogen-Free caBGA	256	COM
LCMXO2-2000HC-4FTG256C	2112	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	COM
LCMXO2-2000HC-5FTG256C	2112	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	COM
LCMXO2-2000HC-6FTG256C	2112	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000UHC-4FG484C	2112	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	484	COM
LCMXO2-2000UHC-5FG484C	2112	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	484	COM
LCMXO2-2000UHC-6FG484C	2112	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-4000HC-4QN84C	4320	2.5 V / 3.3 V	–4	Halogen-Free QFN	84	COM
LCMXO2-4000HC-5QN84C	4320	2.5 V / 3.3 V	–5	Halogen-Free QFN	84	COM
LCMXO2-4000HC-6QN84C	4320	2.5 V / 3.3 V	–6	Halogen-Free QFN	84	COM
LCMXO2-4000HC-4MG132C	4320	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-4000HC-5MG132C	4320	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-4000HC-6MG132C	4320	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	COM
LCMXO2-4000HC-4TG144C	4320	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-4000HC-5TG144C	4320	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-4000HC-6TG144C	4320	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	COM
LCMXO2-4000HC-4BG256C	4320	2.5 V / 3.3 V	–4	Halogen-Free caBGA	256	COM
LCMXO2-4000HC-5BG256C	4320	2.5 V / 3.3 V	–5	Halogen-Free caBGA	256	COM
LCMXO2-4000HC-6BG256C	4320	2.5 V / 3.3 V	–6	Halogen-Free caBGA	256	COM
LCMXO2-4000HC-4FTG256C	4320	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	COM
LCMXO2-4000HC-5FTG256C	4320	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	COM
LCMXO2-4000HC-6FTG256C	4320	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	COM
LCMXO2-4000HC-4BG332C	4320	2.5 V / 3.3 V	–4	Halogen-Free caBGA	332	COM
LCMXO2-4000HC-5BG332C	4320	2.5 V / 3.3 V	–5	Halogen-Free caBGA	332	COM
LCMXO2-4000HC-6BG332C	4320	2.5 V / 3.3 V	–6	Halogen-Free caBGA	332	COM
LCMXO2-4000HC-4FG484C	4320	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	484	COM
LCMXO2-4000HC-5FG484C	4320	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	484	COM
LCMXO2-4000HC-6FG484C	4320	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-7000HC-4TG144C	6864	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-7000HC-5TG144C	6864	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-7000HC-6TG144C	6864	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	COM
LCMXO2-7000HC-4BG256C	6864	2.5 V / 3.3 V	–4	Halogen-Free caBGA	256	COM
LCMXO2-7000HC-5BG256C	6864	2.5 V / 3.3 V	–5	Halogen-Free caBGA	256	COM
LCMXO2-7000HC-6BG256C	6864	2.5 V / 3.3 V	–6	Halogen-Free caBGA	256	COM
LCMXO2-7000HC-4FTG256C	6864	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	COM
LCMXO2-7000HC-5FTG256C	6864	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	COM
LCMXO2-7000HC-6FTG256C	6864	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	COM
LCMXO2-7000HC-4BG332C	6864	2.5 V / 3.3 V	–4	Halogen-Free caBGA	332	COM
LCMXO2-7000HC-5BG332C	6864	2.5 V / 3.3 V	–5	Halogen-Free caBGA	332	COM
LCMXO2-7000HC-6BG332C	6864	2.5 V / 3.3 V	–6	Halogen-Free caBGA	332	COM
LCMXO2-7000HC-4FG400C	6864	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	400	COM
LCMXO2-7000HC-5FG400C	6864	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	400	COM
LCMXO2-7000HC-6FG400C	6864	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	400	COM
LCMXO2-7000HC-4FG484C	6864	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	484	COM
LCMXO2-7000HC-5FG484C	6864	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	484	COM
LCMXO2-7000HC-6FG484C	6864	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200HC-4TG100CR1[1]	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	COM
LCMXO2-1200HC-5TG100CR1[1]	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	COM
LCMXO2-1200HC-6TG100CR1[1]	1280	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	COM
LCMXO2-1200HC-4MG132CR1[1]	1280	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-1200HC-5MG132CR1[1]	1280	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-1200HC-6MG132CR1[1]	1280	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	COM
LCMXO2-1200HC-4TG144CR1[1]	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-1200HC-5TG144CR1[1]	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-1200HC-6TG144CR1[1]	1280	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	COM

1. Specifications for the “LCMXO2-1200HC-speed package CR1” are the same as the “LCMXO2-1200HC-speed package C” devices respectively, except as specified in the R1 Device Specifications section of this data sheet.

High-Performance Commercial Grade Devices without Voltage Regulator, Halogen Free (RoHS) Packaging

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000HE-4TG100C	2112	1.2 V	–4	Halogen-Free TQFP	100	COM
LCMXO2-2000HE-5TG100C	2112	1.2 V	–5	Halogen-Free TQFP	100	COM
LCMXO2-2000HE-6TG100C	2112	1.2 V	–6	Halogen-Free TQFP	100	COM
LCMXO2-2000HE-4TG144C	2112	1.2 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-2000HE-5TG144C	2112	1.2 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-2000HE-6TG144C	2112	1.2 V	–6	Halogen-Free TQFP	144	COM
LCMXO2-2000HE-4MG132C	2112	1.2 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-2000HE-5MG132C	2112	1.2 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-2000HE-6MG132C	2112	1.2 V	–6	Halogen-Free csBGA	132	COM
LCMXO2-2000HE-4BG256C	2112	1.2 V	–4	Halogen-Free caBGA	256	COM
LCMXO2-2000HE-5BG256C	2112	1.2 V	–5	Halogen-Free caBGA	256	COM
LCMXO2-2000HE-6BG256C	2112	1.2 V	–6	Halogen-Free caBGA	256	COM
LCMXO2-2000HE-4FTG256C	2112	1.2 V	–4	Halogen-Free ftBGA	256	COM
LCMXO2-2000HE-5FTG256C	2112	1.2 V	–5	Halogen-Free ftBGA	256	COM
LCMXO2-2000HE-6FTG256C	2112	1.2 V	–6	Halogen-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000UHE-4FG484C	2112	1.2 V	–4	Halogen-Free fpBGA	484	COM
LCMXO2-2000UHE-5FG484C	2112	1.2 V	–5	Halogen-Free fpBGA	484	COM
LCMXO2-2000UHE-6FG484C	2112	1.2 V	–6	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-4000HE-4TG144C	4320	1.2 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-4000HE-5TG144C	4320	1.2 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-4000HE-6TG144C	4320	1.2 V	–6	Halogen-Free TQFP	144	COM
LCMXO2-4000HE-4MG132C	4320	1.2 V	–4	Halogen-Free csBGA	132	COM
LCMXO2-4000HE-5MG132C	4320	1.2 V	–5	Halogen-Free csBGA	132	COM
LCMXO2-4000HE-6MG132C	4320	1.2 V	–6	Halogen-Free csBGA	132	COM
LCMXO2-4000HE-4BG256C	4320	1.2 V	–4	Halogen-Free caBGA	256	COM
LCMXO2-4000HE-4MG184C	4320	1.2 V	–4	Halogen-Free csBGA	184	COM
LCMXO2-4000HE-5MG184C	4320	1.2 V	–5	Halogen-Free csBGA	184	COM
LCMXO2-4000HE-6MG184C	4320	1.2 V	–6	Halogen-Free csBGA	184	COM
LCMXO2-4000HE-5BG256C	4320	1.2 V	–5	Halogen-Free caBGA	256	COM
LCMXO2-4000HE-6BG256C	4320	1.2 V	–6	Halogen-Free caBGA	256	COM
LCMXO2-4000HE-4FTG256C	4320	1.2 V	–4	Halogen-Free ftBGA	256	COM
LCMXO2-4000HE-5FTG256C	4320	1.2 V	–5	Halogen-Free ftBGA	256	COM
LCMXO2-4000HE-6FTG256C	4320	1.2 V	–6	Halogen-Free ftBGA	256	COM
LCMXO2-4000HE-4BG332C	4320	1.2 V	–4	Halogen-Free caBGA	332	COM
LCMXO2-4000HE-5BG332C	4320	1.2 V	–5	Halogen-Free caBGA	332	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-4000HE-6BG332C	4320	1.2 V	–6	Halogen-Free caBGA	332	COM
LCMXO2-4000HE-4FG484C	4320	1.2 V	–4	Halogen-Free fpBGA	484	COM
LCMXO2-4000HE-5FG484C	4320	1.2 V	–5	Halogen-Free fpBGA	484	COM
LCMXO2-4000HE-6FG484C	4320	1.2 V	–6	Halogen-Free fpBGA	484	COM

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-7000HE-4TG144C	6864	1.2 V	–4	Halogen-Free TQFP	144	COM
LCMXO2-7000HE-5TG144C	6864	1.2 V	–5	Halogen-Free TQFP	144	COM
LCMXO2-7000HE-6TG144C	6864	1.2 V	–6	Halogen-Free TQFP	144	COM
LCMXO2-7000HE-4BG256C	6864	1.2 V	–4	Halogen-Free caBGA	256	COM
LCMXO2-7000HE-5BG256C	6864	1.2 V	–5	Halogen-Free caBGA	256	COM
LCMXO2-7000HE-6BG256C	6864	1.2 V	–6	Halogen-Free caBGA	256	COM
LCMXO2-7000HE-4FTG256C	6864	1.2 V	–4	Halogen-Free ftBGA	256	COM
LCMXO2-7000HE-5FTG256C	6864	1.2 V	–5	Halogen-Free ftBGA	256	COM
LCMXO2-7000HE-6FTG256C	6864	1.2 V	–6	Halogen-Free ftBGA	256	COM
LCMXO2-7000HE-4BG332C	6864	1.2 V	–4	Halogen-Free caBGA	332	COM
LCMXO2-7000HE-5BG332C	6864	1.2 V	–5	Halogen-Free caBGA	332	COM
LCMXO2-7000HE-6BG332C	6864	1.2 V	–6	Halogen-Free caBGA	332	COM
LCMXO2-7000HE-4FG484C	6864	1.2 V	–4	Halogen-Free fpBGA	484	COM
LCMXO2-7000HE-5FG484C	6864	1.2 V	–5	Halogen-Free fpBGA	484	COM
LCMXO2-7000HE-6FG484C	6864	1.2 V	–6	Halogen-Free fpBGA	484	COM

Ultra Low Power Industrial Grade Devices, Halogen Free (RoHS) Packaging

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-256ZE-1SG32I	256	1.2 V	–1	Halogen-Free QFN	32	IND
LCMXO2-256ZE-2SG32I	256	1.2 V	–2	Halogen-Free QFN	32	IND
LCMXO2-256ZE-3SG32I	256	1.2 V	–3	Halogen-Free QFN	32	IND
LCMXO2-256ZE-1UMG64I	256	1.2 V	–1	Halogen-Free ucBGA	64	IND
LCMXO2-256ZE-2UMG64I	256	1.2 V	–2	Halogen-Free ucBGA	64	IND
LCMXO2-256ZE-3UMG64I	256	1.2 V	–3	Halogen-Free ucBGA	64	IND
LCMXO2-256ZE-1TG100I	256	1.2 V	–1	Halogen-Free TQFP	100	IND
LCMXO2-256ZE-2TG100I	256	1.2 V	–2	Halogen-Free TQFP	100	IND
LCMXO2-256ZE-3TG100I	256	1.2 V	–3	Halogen-Free TQFP	100	IND
LCMXO2-256ZE-1MG132I	256	1.2 V	–1	Halogen-Free csBGA	132	IND
LCMXO2-256ZE-2MG132I	256	1.2 V	–2	Halogen-Free csBGA	132	IND
LCMXO2-256ZE-3MG132I	256	1.2 V	–3	Halogen-Free csBGA	132	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-640ZE-1TG100I	640	1.2 V	–1	Halogen-Free TQFP	100	IND
LCMXO2-640ZE-2TG100I	640	1.2 V	–2	Halogen-Free TQFP	100	IND
LCMXO2-640ZE-3TG100I	640	1.2 V	–3	Halogen-Free TQFP	100	IND
LCMXO2-640ZE-1MG132I	640	1.2 V	–1	Halogen-Free csBGA	132	IND
LCMXO2-640ZE-2MG132I	640	1.2 V	–2	Halogen-Free csBGA	132	IND
LCMXO2-640ZE-3MG132I	640	1.2 V	–3	Halogen-Free csBGA	132	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200ZE-1UWG25ITR[1]	1280	1.2 V	–1	Halogen-Free WLCSP	25	IND
LCMXO2-1200ZE-1UWG25ITR50[3]	1280	1.2 V	–1	Halogen-Free WLCSP	25	IND
LCMXO2-1200ZE-1UWG25ITR1K[2]	1280	1.2 V	–1	Halogen-Free WLCSP	25	IND
LCMXO2-1200ZE-1SG32I	1280	1.2 V	–1	Halogen-Free QFN	32	IND
LCMXO2-1200ZE-2SG32I	1280	1.2 V	–2	Halogen-Free QFN	32	IND
LCMXO2-1200ZE-3SG32I	1280	1.2 V	–3	Halogen-Free QFN	32	IND
LCMXO2-1200ZE-1TG100I	1280	1.2 V	–1	Halogen-Free TQFP	100	IND
LCMXO2-1200ZE-2TG100I	1280	1.2 V	–2	Halogen-Free TQFP	100	IND
LCMXO2-1200ZE-3TG100I	1280	1.2 V	–3	Halogen-Free TQFP	100	IND
LCMXO2-1200ZE-1MG132I	1280	1.2 V	–1	Halogen-Free csBGA	132	IND
LCMXO2-1200ZE-2MG132I	1280	1.2 V	–2	Halogen-Free csBGA	132	IND
LCMXO2-1200ZE-3MG132I	1280	1.2 V	–3	Halogen-Free csBGA	132	IND
LCMXO2-1200ZE-1TG144I	1280	1.2 V	–1	Halogen-Free TQFP	144	IND
LCMXO2-1200ZE-2TG144I	1280	1.2 V	–2	Halogen-Free TQFP	144	IND
LCMXO2-1200ZE-3TG144I	1280	1.2 V	–3	Halogen-Free TQFP	144	IND

1. This part number has a tape and reel quantity of 5,000 units with a minimum order quantity of 10,000 units. Order quantities must be in increments of 5,000 units. For example, a 10,000 unit order will be shipped in two reels with one reel containing 5,000 units and the other reel with less than 5,000 units (depending on test yields). Unserviced backlog will be canceled.
2. This part number has a tape and reel quantity of 1,000 units with a minimum order quantity of 1,000. Order quantities must be in increments of 1,000 units. For example, a 5,000 unit order will be shipped as 5 reels of 1000 units each.
3. This part number has a tape and reel quantity of 50 units with a minimum order quantity of 50. Order quantities must be in increments of 50 units. For example, a 1,000 unit order will be shipped as 20 reels of 50 units each.

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000ZE-1UWG49ITR[1]	2112	1.2 V	–1	Halogen-Free WLCSP	49	IND
LCMXO2-2000ZE-1UWG49ITR50[3]	2112	1.2 V	–1	Halogen-Free WLCSP	49	IND
LCMXO2-2000ZE-1UWG49ITR1K[2]	2112	1.2 V	–1	Halogen-Free WLCSP	49	IND
LCMXO2-2000ZE-1TG100I	2112	1.2 V	–1	Halogen-Free TQFP	100	IND
LCMXO2-2000ZE-2TG100I	2112	1.2 V	–2	Halogen-Free TQFP	100	IND
LCMXO2-2000ZE-3TG100I	2112	1.2 V	–3	Halogen-Free TQFP	100	IND
LCMXO2-2000ZE-1MG132I	2112	1.2 V	–1	Halogen-Free csBGA	132	IND
LCMXO2-2000ZE-2MG132I	2112	1.2 V	–2	Halogen-Free csBGA	132	IND
LCMXO2-2000ZE-3MG132I	2112	1.2 V	–3	Halogen-Free csBGA	132	IND
LCMXO2-2000ZE-1TG144I	2112	1.2 V	–1	Halogen-Free TQFP	144	IND
LCMXO2-2000ZE-2TG144I	2112	1.2 V	–2	Halogen-Free TQFP	144	IND
LCMXO2-2000ZE-3TG144I	2112	1.2 V	–3	Halogen-Free TQFP	144	IND
LCMXO2-2000ZE-1BG256I	2112	1.2 V	–1	Halogen-Free caBGA	256	IND
LCMXO2-2000ZE-2BG256I	2112	1.2 V	–2	Halogen-Free caBGA	256	IND
LCMXO2-2000ZE-3BG256I	2112	1.2 V	–3	Halogen-Free caBGA	256	IND
LCMXO2-2000ZE-1FTG256I	2112	1.2 V	–1	Halogen-Free ftBGA	256	IND
LCMXO2-2000ZE-2FTG256I	2112	1.2 V	–2	Halogen-Free ftBGA	256	IND
LCMXO2-2000ZE-3FTG256I	2112	1.2 V	–3	Halogen-Free ftBGA	256	IND

1. This part number has a tape and reel quantity of 5,000 units with a minimum order quantity of 10,000 units. Order quantities must be in increments of 5,000 units. For example, a 10,000 unit order will be shipped in two reels with one reel containing 5,000 units and the other reel with less than 5,000 units (depending on test yields). Unserviced backlog will be canceled.
2. This part number has a tape and reel quantity of 1,000 units with a minimum order quantity of 1,000. Order quantities must be in increments of 1,000 units. For example, a 5,000 unit order will be shipped as 5 reels of 1000 units each.
3. This part number has a tape and reel quantity of 50 units with a minimum order quantity of 50. Order quantities must be in increments of 50 units. For example, a 1,000 unit order will be shipped as 20 reels of 50 units each.

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-4000ZE-1QN84I	4320	1.2 V	–1	Halogen-Free QFN	84	IND
LCMXO2-4000ZE-2QN84I	4320	1.2 V	–2	Halogen-Free QFN	84	IND
LCMXO2-4000ZE-3QN84I	4320	1.2 V	–3	Halogen-Free QFN	84	IND
LCMXO2-4000ZE-1MG132I	4320	1.2 V	–1	Halogen-Free csBGA	132	IND
LCMXO2-4000ZE-2MG132I	4320	1.2 V	–2	Halogen-Free csBGA	132	IND
LCMXO2-4000ZE-3MG132I	4320	1.2 V	–3	Halogen-Free csBGA	132	IND
LCMXO2-4000ZE-1TG144I	4320	1.2 V	–1	Halogen-Free TQFP	144	IND
LCMXO2-4000ZE-2TG144I	4320	1.2 V	–2	Halogen-Free TQFP	144	IND
LCMXO2-4000ZE-3TG144I	4320	1.2 V	–3	Halogen-Free TQFP	144	IND
LCMXO2-4000ZE-1BG256I	4320	1.2 V	–1	Halogen-Free caBGA	256	IND
LCMXO2-4000ZE-2BG256I	4320	1.2 V	–2	Halogen-Free caBGA	256	IND
LCMXO2-4000ZE-3BG256I	4320	1.2 V	–3	Halogen-Free caBGA	256	IND
LCMXO2-4000ZE-1FTG256I	4320	1.2 V	–1	Halogen-Free ftBGA	256	IND
LCMXO2-4000ZE-2FTG256I	4320	1.2 V	–2	Halogen-Free ftBGA	256	IND
LCMXO2-4000ZE-3FTG256I	4320	1.2 V	–3	Halogen-Free ftBGA	256	IND
LCMXO2-4000ZE-1BG332I	4320	1.2 V	–1	Halogen-Free caBGA	332	IND
LCMXO2-4000ZE-2BG332I	4320	1.2 V	–2	Halogen-Free caBGA	332	IND
LCMXO2-4000ZE-3BG332I	4320	1.2 V	–3	Halogen-Free caBGA	332	IND
LCMXO2-4000ZE-1FG484I	4320	1.2 V	–1	Halogen-Free fpBGA	484	IND
LCMXO2-4000ZE-2FG484I	4320	1.2 V	–2	Halogen-Free fpBGA	484	IND
LCMXO2-4000ZE-3FG484I	4320	1.2 V	–3	Halogen-Free fpBGA	484	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-7000ZE-1TG144I	6864	1.2 V	–1	Halogen-Free TQFP	144	IND
LCMXO2-7000ZE-2TG144I	6864	1.2 V	–2	Halogen-Free TQFP	144	IND
LCMXO2-7000ZE-3TG144I	6864	1.2 V	–3	Halogen-Free TQFP	144	IND
LCMXO2-7000ZE-1BG256I	6864	1.2 V	–1	Halogen-Free caBGA	256	IND
LCMXO2-7000ZE-2BG256I	6864	1.2 V	–2	Halogen-Free caBGA	256	IND
LCMXO2-7000ZE-3BG256I	6864	1.2 V	–3	Halogen-Free caBGA	256	IND
LCMXO2-7000ZE-1FTG256I	6864	1.2 V	–1	Halogen-Free ftBGA	256	IND
LCMXO2-7000ZE-2FTG256I	6864	1.2 V	–2	Halogen-Free ftBGA	256	IND
LCMXO2-7000ZE-3FTG256I	6864	1.2 V	–3	Halogen-Free ftBGA	256	IND
LCMXO2-7000ZE-1BG332I	6864	1.2 V	–1	Halogen-Free caBGA	332	IND
LCMXO2-7000ZE-2BG332I	6864	1.2 V	–2	Halogen-Free caBGA	332	IND
LCMXO2-7000ZE-3BG332I	6864	1.2 V	–3	Halogen-Free caBGA	332	IND
LCMXO2-7000ZE-1FG484I	6864	1.2 V	–1	Halogen-Free fpBGA	484	IND
LCMXO2-7000ZE-2FG484I	6864	1.2 V	–2	Halogen-Free fpBGA	484	IND
LCMXO2-7000ZE-3FG484I	6864	1.2 V	–3	Halogen-Free fpBGA	484	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200ZE-1TG100IR1[1]	1280	1.2 V	–1	Halogen-Free TQFP	100	IND
LCMXO2-1200ZE-2TG100IR1[1]	1280	1.2 V	–2	Halogen-Free TQFP	100	IND
LCMXO2-1200ZE-3TG100IR1[1]	1280	1.2 V	–3	Halogen-Free TQFP	100	IND
LCMXO2-1200ZE-1MG132IR1[1]	1280	1.2 V	–1	Halogen-Free csBGA	132	IND
LCMXO2-1200ZE-2MG132IR1[1]	1280	1.2 V	–2	Halogen-Free csBGA	132	IND
LCMXO2-1200ZE-3MG132IR1[1]	1280	1.2 V	–3	Halogen-Free csBGA	132	IND
LCMXO2-1200ZE-1TG144IR1[1]	1280	1.2 V	–1	Halogen-Free TQFP	144	IND
LCMXO2-1200ZE-2TG144IR1[1]	1280	1.2 V	–2	Halogen-Free TQFP	144	IND
LCMXO2-1200ZE-3TG144IR1[1]	1280	1.2 V	–3	Halogen-Free TQFP	144	IND

1. Specifications for the “LCMXO2-1200ZE-speed package IR1” are the same as the “LCMXO2-1200ZE-speed package I” devices respectively, except as specified in the R1 Device Specifications section of this data sheet.

High-Performance Industrial Grade Devices with Voltage Regulator, Halogen Free (RoHS) Packaging

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-256HC-4SG32I	256	2.5 V / 3.3 V	–4	Halogen-Free QFN	32	IND
LCMXO2-256HC-5SG32I	256	2.5 V / 3.3 V	–5	Halogen-Free QFN	32	IND
LCMXO2-256HC-6SG32I	256	2.5 V / 3.3 V	–6	Halogen-Free QFN	32	IND
LCMXO2-256HC-4SG48I	256	2.5 V / 3.3 V	–4	Halogen-Free QFN	48	IND
LCMXO2-256HC-5SG48I	256	2.5 V / 3.3 V	–5	Halogen-Free QFN	48	IND
LCMXO2-256HC-6SG48I	256	2.5 V / 3.3 V	–6	Halogen-Free QFN	48	IND
LCMXO2-256HC-4UMG64I	256	2.5 V / 3.3 V	–4	Halogen-Free ucBGA	64	IND
LCMXO2-256HC-5UMG64I	256	2.5 V / 3.3 V	–5	Halogen-Free ucBGA	64	IND
LCMXO2-256HC-6UMG64I	256	2.5 V / 3.3 V	–6	Halogen-Free ucBGA	64	IND
LCMXO2-256HC-4TG100I	256	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	IND
LCMXO2-256HC-5TG100I	256	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	IND
LCMXO2-256HC-6TG100I	256	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	IND
LCMXO2-256HC-4MG132I	256	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-256HC-5MG132I	256	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-256HC-6MG132I	256	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-640HC-4SG48I	640	2.5 V / 3.3 V	–4	Halogen-Free QFN	48	IND
LCMXO2-640HC-5SG48I	640	2.5 V / 3.3 V	–5	Halogen-Free QFN	48	IND
LCMXO2-640HC-6SG48I	640	2.5 V / 3.3 V	–6	Halogen-Free QFN	48	IND
LCMXO2-640HC-4TG100I	640	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	IND
LCMXO2-640HC-5TG100I	640	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	IND
LCMXO2-640HC-6TG100I	640	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	IND
LCMXO2-640HC-4MG132I	640	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-640HC-5MG132I	640	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-640HC-6MG132I	640	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-640UHC-4TG144I	640	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-640UHC-5TG144I	640	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-640UHC-6TG144I	640	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200HC-4SG32I	1280	2.5 V / 3.3 V	–4	Halogen-Free QFN	32	IND
LCMXO2-1200HC-5SG32I	1280	2.5 V / 3.3 V	–5	Halogen-Free QFN	32	IND
LCMXO2-1200HC-6SG32I	1280	2.5 V / 3.3 V	–6	Halogen-Free QFN	32	IND
LCMXO2-1200HC-4TG100I	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	IND
LCMXO2-1200HC-5TG100I	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	IND
LCMXO2-1200HC-6TG100I	1280	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	IND
LCMXO2-1200HC-4MG132I	1280	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-1200HC-5MG132I	1280	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-1200HC-6MG132I	1280	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	IND
LCMXO2-1200HC-4TG144I	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-1200HC-5TG144I	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-1200HC-6TG144I	1280	2.5 V/ 3.3 V	–6	Halogen-Free TQFP	144	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200UHC-4FTG256I	1280	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	IND
LCMXO2-1200UHC-5FTG256I	1280	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	IND
LCMXO2-1200UHC-6FTG256I	1280	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000HC-4TG100I	2112	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	IND
LCMXO2-2000HC-5TG100I	2112	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	IND
LCMXO2-2000HC-6TG100I	2112	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	IND
LCMXO2-2000HC-4MG132I	2112	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-2000HC-5MG132I	2112	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-2000HC-6MG132I	2112	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	IND
LCMXO2-2000HC-4TG144I	2112	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-2000HC-5TG144I	2112	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-2000HC-6TG144I	2112	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	IND
LCMXO2-2000HC-4BG256I	2112	2.5 V / 3.3 V	–4	Halogen-Free caBGA	256	IND
LCMXO2-2000HC-5BG256I	2112	2.5 V / 3.3 V	–5	Halogen-Free caBGA	256	IND
LCMXO2-2000HC-6BG256I	2112	2.5 V / 3.3 V	–6	Halogen-Free caBGA	256	IND
LCMXO2-2000HC-4FTG256I	2112	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	IND
LCMXO2-2000HC-5FTG256I	2112	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	IND
LCMXO2-2000HC-6FTG256I	2112	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000UHC-4FG484I	2112	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	484	IND
LCMXO2-2000UHC-5FG484I	2112	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	484	IND
LCMXO2-2000UHC-6FG484I	2112	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	484	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-4000HC-4QN84I	4320	2.5 V / 3.3 V	–4	Halogen-Free QFN	84	IND
LCMXO2-4000HC-5QN84I	4320	2.5 V / 3.3 V	–5	Halogen-Free QFN	84	IND
LCMXO2-4000HC-6QN84I	4320	2.5 V / 3.3 V	–6	Halogen-Free QFN	84	IND
LCMXO2-4000HC-4TG144I	4320	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-4000HC-5TG144I	4320	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-4000HC-6TG144I	4320	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	IND
LCMXO2-4000HC-4MG132I	4320	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-4000HC-5MG132I	4320	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-4000HC-6MG132I	4320	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	IND
LCMXO2-4000HC-4BG256I	4320	2.5 V / 3.3 V	–4	Halogen-Free caBGA	256	IND
LCMXO2-4000HC-5BG256I	4320	2.5 V / 3.3 V	–5	Halogen-Free caBGA	256	IND
LCMXO2-4000HC-6BG256I	4320	2.5 V / 3.3 V	–6	Halogen-Free caBGA	256	IND
LCMXO2-4000HC-4FTG256I	4320	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	IND
LCMXO2-4000HC-5FTG256I	4320	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	IND
LCMXO2-4000HC-6FTG256I	4320	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	IND
LCMXO2-4000HC-4BG332I	4320	2.5 V / 3.3 V	–4	Halogen-Free caBGA	332	IND
LCMXO2-4000HC-5BG332I	4320	2.5 V / 3.3 V	–5	Halogen-Free caBGA	332	IND
LCMXO2-4000HC-6BG332I	4320	2.5 V / 3.3 V	–6	Halogen-Free caBGA	332	IND
LCMXO2-4000HC-4FG484I	4320	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	484	IND
LCMXO2-4000HC-5FG484I	4320	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	484	IND
LCMXO2-4000HC-6FG484I	4320	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	484	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-7000HC-4TG144I	6864	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-7000HC-5TG144I	6864	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-7000HC-6TG144I	6864	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	IND
LCMXO2-7000HC-4BG256I	6864	2.5 V / 3.3 V	–4	Halogen-Free caBGA	256	IND
LCMXO2-7000HC-5BG256I	6864	2.5 V / 3.3 V	–5	Halogen-Free caBGA	256	IND
LCMXO2-7000HC-6BG256I	6864	2.5 V / 3.3 V	–6	Halogen-Free caBGA	256	IND
LCMXO2-7000HC-4FTG256I	6864	2.5 V / 3.3 V	–4	Halogen-Free ftBGA	256	IND
LCMXO2-7000HC-5FTG256I	6864	2.5 V / 3.3 V	–5	Halogen-Free ftBGA	256	IND
LCMXO2-7000HC-6FTG256I	6864	2.5 V / 3.3 V	–6	Halogen-Free ftBGA	256	IND
LCMXO2-7000HC-4BG332I	6864	2.5 V / 3.3 V	–4	Halogen-Free caBGA	332	IND
LCMXO2-7000HC-5BG332I	6864	2.5 V / 3.3 V	–5	Halogen-Free caBGA	332	IND
LCMXO2-7000HC-6BG332I	6864	2.5 V / 3.3 V	–6	Halogen-Free caBGA	332	IND
LCMXO2-7000HC-4FG400I	6864	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	400	IND
LCMXO2-7000HC-5FG400I	6864	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	400	IND
LCMXO2-7000HC-6FG400I	6864	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	400	IND
LCMXO2-7000HC-4FG484I	6864	2.5 V / 3.3 V	–4	Halogen-Free fpBGA	484	IND
LCMXO2-7000HC-5FG484I	6864	2.5 V / 3.3 V	–5	Halogen-Free fpBGA	484	IND
LCMXO2-7000HC-6FG484I	6864	2.5 V / 3.3 V	–6	Halogen-Free fpBGA	484	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-1200HC-4TG100IR1[1]	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	100	IND
LCMXO2-1200HC-5TG100IR1[1]	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	100	IND
LCMXO2-1200HC-6TG100IR1[1]	1280	2.5 V / 3.3 V	–6	Halogen-Free TQFP	100	IND
LCMXO2-1200HC-4MG132IR1[1]	1280	2.5 V / 3.3 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-1200HC-5MG132IR1[1]	1280	2.5 V / 3.3 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-1200HC-6MG132IR1[1]	1280	2.5 V / 3.3 V	–6	Halogen-Free csBGA	132	IND
LCMXO2-1200HC-4TG144IR1[1]	1280	2.5 V / 3.3 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-1200HC-5TG144IR1[1]	1280	2.5 V / 3.3 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-1200HC-6TG144IR1[1]	1280	2.5 V / 3.3 V	–6	Halogen-Free TQFP	144	IND

1. Specifications for the “LCMXO2-1200HC-speed package IR1” are the same as the “LCMXO2-1200ZE-speed package I” devices respectively, except as specified in the R1 Device Specifications section of this data sheet.

High Performance Industrial Grade Devices Without Voltage Regulator, Halogen Free (RoHS) Packaging

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000HE-4TG100I	2112	1.2 V	–4	Halogen-Free TQFP	100	IND
LCMXO2-2000HE-5TG100I	2112	1.2 V	–5	Halogen-Free TQFP	100	IND
LCMXO2-2000HE-6TG100I	2112	1.2 V	–6	Halogen-Free TQFP	100	IND
LCMXO2-2000HE-4MG132I	2112	1.2 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-2000HE-5MG132I	2112	1.2 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-2000HE-6MG132I	2112	1.2 V	–6	Halogen-Free csBGA	132	IND
LCMXO2-2000HE-4TG144I	2112	1.2 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-2000HE-5TG144I	2112	1.2 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-2000HE-6TG144I	2112	1.2 V	–6	Halogen-Free TQFP	144	IND
LCMXO2-2000HE-4BG256I	2112	1.2 V	–4	Halogen-Free caBGA	256	IND
LCMXO2-2000HE-5BG256I	2112	1.2 V	–5	Halogen-Free caBGA	256	IND
LCMXO2-2000HE-6BG256I	2112	1.2 V	–6	Halogen-Free caBGA	256	IND
LCMXO2-2000HE-4FTG256I	2112	1.2 V	–4	Halogen-Free ftBGA	256	IND
LCMXO2-2000HE-5FTG256I	2112	1.2 V	–5	Halogen-Free ftBGA	256	IND
LCMXO2-2000HE-6FTG256I	2112	1.2 V	–6	Halogen-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-2000UHE-4FG484I	2112	1.2 V	–4	Halogen-Free fpBGA	484	IND
LCMXO2-2000UHE-5FG484I	2112	1.2 V	–5	Halogen-Free fpBGA	484	IND
LCMXO2-2000UHE-6FG484I	2112	1.2 V	–6	Halogen-Free fpBGA	484	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-4000HE-4MG132I	4320	1.2 V	–4	Halogen-Free csBGA	132	IND
LCMXO2-4000HE-5MG132I	4320	1.2 V	–5	Halogen-Free csBGA	132	IND
LCMXO2-4000HE-6MG132I	4320	1.2 V	–6	Halogen-Free csBGA	132	IND
LCMXO2-4000HE-4TG144I	4320	1.2 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-4000HE-5TG144I	4320	1.2 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-4000HE-6TG144I	4320	1.2 V	–6	Halogen-Free TQFP	144	IND
LCMXO2-4000HE-4MG184I	4320	1.2 V	–4	Halogen-Free csBGA	184	IND
LCMXO2-4000HE-5MG184I	4320	1.2 V	–5	Halogen-Free csBGA	184	IND
LCMXO2-4000HE-6MG184I	4320	1.2 V	–6	Halogen-Free csBGA	184	IND
LCMXO2-4000HE-4BG256I	4320	1.2 V	–4	Halogen-Free caBGA	256	IND
LCMXO2-4000HE-5BG256I	4320	1.2 V	–5	Halogen-Free caBGA	256	IND
LCMXO2-4000HE-6BG256I	4320	1.2 V	–6	Halogen-Free caBGA	256	IND
LCMXO2-4000HE-4FTG256I	4320	1.2 V	–4	Halogen-Free ftBGA	256	IND
LCMXO2-4000HE-5FTG256I	4320	1.2 V	–5	Halogen-Free ftBGA	256	IND
LCMXO2-4000HE-6FTG256I	4320	1.2 V	–6	Halogen-Free ftBGA	256	IND
LCMXO2-4000HE-4BG332I	4320	1.2 V	–4	Halogen-Free caBGA	332	IND
LCMXO2-4000HE-5BG332I	4320	1.2 V	–5	Halogen-Free caBGA	332	IND
LCMXO2-4000HE-6BG332I	4320	1.2 V	–6	Halogen-Free caBGA	332	IND
LCMXO2-4000HE-4FG484I	4320	1.2 V	–4	Halogen-Free fpBGA	484	IND
LCMXO2-4000HE-5FG484I	4320	1.2 V	–5	Halogen-Free fpBGA	484	IND
LCMXO2-4000HE-6FG484I	4320	1.2 V	–6	Halogen-Free fpBGA	484	IND

Part Number	LUTs	Supply Voltage	Grade	Package	Leads	Temp.
LCMXO2-7000HE-4TG144I	6864	1.2 V	–4	Halogen-Free TQFP	144	IND
LCMXO2-7000HE-5TG144I	6864	1.2 V	–5	Halogen-Free TQFP	144	IND
LCMXO2-7000HE-6TG144I	6864	1.2 V	–6	Halogen-Free TQFP	144	IND
LCMXO2-7000HE-4BG256I	6864	1.2 V	–4	Halogen-Free caBGA	256	IND
LCMXO2-7000HE-5BG256I	6864	1.2 V	–5	Halogen-Free caBGA	256	IND
LCMXO2-7000HE-6BG256I	6864	1.2 V	–6	Halogen-Free caBGA	256	IND
LCMXO2-7000HE-4FTG256I	6864	1.2 V	–4	Halogen-Free ftBGA	256	IND
LCMXO2-7000HE-5FTG256I	6864	1.2 V	–5	Halogen-Free ftBGA	256	IND
LCMXO2-7000HE-6FTG256I	6864	1.2 V	–6	Halogen-Free ftBGA	256	IND
LCMXO2-7000HE-4BG332I	6864	1.2 V	–4	Halogen-Free caBGA	332	IND
LCMXO2-7000HE-5BG332I	6864	1.2 V	–5	Halogen-Free caBGA	332	IND
LCMXO2-7000HE-6BG332I	6864	1.2 V	–6	Halogen-Free caBGA	332	IND
LCMXO2-7000HE-4FG484I	6864	1.2 V	–4	Halogen-Free fpBGA	484	IND
LCMXO2-7000HE-5FG484I	6864	1.2 V	–5	Halogen-Free fpBGA	484	IND
LCMXO2-7000HE-6FG484I	6864	1.2 V	–6	Halogen-Free fpBGA	484	IND

R1 Device Specifications

The LCMXO2-1200ZE/HC "R1" devices have the same specifications as their Standard (non-R1) counterparts except as listed below. For more details on the R1 to Standard migration refer to AN8086, Designing for Migration from MachXO2-1200-R1 to Standard Non-R1) Devices.

- The User Flash Memory (UFM) cannot be programmed through the internal WISHBONE interface. It can still be programmed through the JTAG/SPI/I^{2}C ports.
- The on-chip differential input termination resistor value is higher than intended. It is approximately 200Ω as opposed to the intended 100Ω. It is recommended to use external termination resistors for differential inputs. The on-chip termination resistors can be disabled through Lattice design software.
- Soft Error Detection logic may not produce the correct result when it is run for the first time after configuration. To use this feature, discard the result from the first operation. Subsequent operations will produce the correct result.
- Under certain conditions, IIH exceeds data sheet specifications. The following table provides more details:

Condition	Clamp	Pad Rising IIH Max.	Pad Falling IIH Min.	Steady State Pad High IIH	Steady State Pad Low IIL
VPAD > VCCIO	OFF	1 mA	–1 mA	1 mA	10 µA
VPAD = VCCIO	ON	10 µA	–10 µA	10 µA	10 µA
VPAD = VCCIO	OFF	1 mA	–1 mA	1 mA	10 µA
VPAD < VCCIO	OFF	10 µA	–10 µA	10 µA	10 µA

- The user SPI interface does not operate correctly in some situations. During master read access and slave write access, the last byte received does not generate the RRDY interrupt.
- In GDDRX2, GDDRX4 and GDDR71 modes, ECLKSYNC may have a glitch in the output under certain conditions, leading to possible loss of synchronization.
- When using the hard I^{2}C IP core, the I^{2}C status registers I2C_1_SR and I2C_2_SR may not update correctly.
- PLL Lock signal will glitch high when coming out of standby. This glitch lasts for about 10 µsec before returning low.
- Dual boot only available on HC devices, requires tying VCC and VCCIO2 to the same 3.3 V or 2.5 V supply.

MachXO2 Family Data Sheet Supplemental Information

For Further Information

A variety of technical notes for the MachXO2 family are available on the Lattice web site.

- TN1198, Power Estimation and Management for MachXO2 Devices
- TN1199, MachXO2 sysCLOCK PLL Design and Usage Guide
- TN1201, Memory Usage Guide for MachXO2 Devices
- TN1202, MachXO2 sysIO Usage Guide
- TN1203, Implementing High-Speed Interfaces with MachXO2 Devices
- TN1204, MachXO2 Programming and Configuration Usage Guide
- TN1205, Using User Flash Memory and Hardened Control Functions in MachXO2 Devices
- TN1206, MachXO2 SRAM CRC Error Detection Usage Guide
- TN1207, Using TraceID in MachXO2 Devices
- TN1074, PCB Layout Recommendations for BGA Packages
- TN1087, Minimizing System Interruption During Configuration Using TransFR Technology
- AN8086, Designing for Migration from MachXO2-1200-R1 to Standard (non-R1) Devices
- AN8066, Boundary Scan Testability with Lattice sysIO Capability
- MachXO2 Device Pinout Files
- Thermal Management document
- Lattice design tools

For further information on interface standards, refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, LVDS, DDR, DDR2, LPDDR): www.jedec.org
- PCI: www.pcisig.com

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MachXO2 Family Data Sheet Revision History

March 2017 **Data Sheet DS1035**

Date	Version	Section	Change Summary
March 2017	3.3	DC and Switching Characteristics	Updated the Absolute Maximum Ratings section. Added standards.
			Updated the sysIO Recommended Operating Conditions section. Added standards.
			Updated the sysIO Single-Ended DC Electrical Characteristics section. Added standards.
			Updated the MachXO2 External Switching Characteristics – HC/HE Devices section. Under 7:1 LVDS Outputs – GDDR71_TX.ECLK.7:1, the D_{VB} and the D_{VA} parameters were changed to D_{IB} and D_{IA}. The parameter descriptions were also modified.
			Updated the MachXO2 External Switching Characteristics – ZE Devices section. Under 7:1 LVDS Outputs – GDDR71_TX.ECLK.7:1, the D_{VB} and the D_{VA} parameters were changed to D_{IB} and D_{IA}. The parameter descriptions were also modified.
			Updated the sysCONFIG Port Timing Specifications section. Corrected the t_{INITL} units from ns to µs.
		Pinout Information	Updated the Signal Descriptions section. Revised the descriptions of the PROGRAMN, INITN, and DONE signals.
			Updated the Pinout Information Summary section. Added footnote to MachXO2-1200 32 QFN.
		Ordering Information	Updated the MachXO2 Part Number Description section. Corrected the MG184, BG256, FTG256 package information. Added “(0.8 mm Pitch)” to BG332.
			Updated the Ultra Low Power Industrial Grade Devices, Halogen Free (RoHS) Packaging section. — Updated LCMXO2-1200ZE-1UWG25ITR50 footnote. — Corrected footnote numbering typo. — Added the LCMXO2-2000ZE-1UWG49ITR50 and LCMXO2-2000ZE-1UWG49ITR1K part numbers. Updated/added footnote/s.

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Date	Version	Section	Change Summary
May 2016	3.2	All	Moved designation for 84 QFN package information from 'Advanced' to 'Final'.
		Introduction	Updated the Features section. Revised Table 1-1, MachXO2 Family Selection Guide. — Added ‘Advanced’ 48 QFN package. — Revised footnote 6. — Added footnote 9.
		DC and Switching Characteristics	Updated the MachXO2 External Switching Characteristics – HC/HE Devices section. Added footnote 12.
			Updated the MachXO2 External Switching Characteristics – ZE Devices section. Added footnote 12.
		Pinout Information	Updated the Signal Descriptions section. Added information on GND signal.
			Updated the Pinout Information Summary section. — Added ‘Advanced’ MachXO2-256 48 QFN values. — Added ‘Advanced’ MachXO2-640 48 QFN values. — Added footnote to GND. — Added footnotes 2 and 3.
		Ordering Information	Updated the MachXO2 Part Number Description section. Added ‘Advanced’ SG48 package and revised footnote.
			Updated the Ordering Information section. — Added part numbers for ‘Advanced’ QFN 48 package.
March 2016	3.1	Introduction	Updated the Features section. Revised Table 1-1, MachXO2 Family Selection Guide. — Added 32 QFN value for XO2-1200. — Added 84 QFN (7 mm x 7 mm, 0.5 mm) package. — Modified package name to 100-pin TQFP. — Modified package name to 144-pin TQFP. — Added footnote.
		Architecture	Updated the Typical I/O Behavior During Power-up section. Removed reference to TN1202.
		DC and Switching Characteristics	Updated the sysCONFIG Port Timing Specifications section. Revised $t_{DPPDONE}$ and $t_{DPPINIT}$ Max. values per PCN 03A-16, released March 2016.
		Pinout Information	Updated the Pinout Information Summary section. — Added MachXO2-1200 32 QFN values. — Added ‘Advanced’ MachXO2-4000 84 QFN values.
		Ordering Information	Updated the MachXO2 Part Number Description section. Added ‘Advanced’ QN84 package and footnote.
			Updated the Ordering Information section. — Added part numbers for 1280 LUTs QFN 32 package. — Added part numbers for 4320 LUTs QFN 84 package.
March 2015	3.0	Introduction	Updated the Features section. Revised Table 1-1, MachXO2 Family Selection Guide. — Changed 64-ball ucBGA dimension.
		Architecture	Updated the Device Configuration section. Added JTAGENB to TAP dual purpose pins.

Date	Version	Section	Change Summary
December 2014	2.9	Introduction	Updated the Features section. Revised Table 1-1, MachXO2 Family Selection Guide. — Removed XO2-4000U data. — Removed 400-ball ftBGA. — Removed 25-ball WLCSP value for XO2-2000U.
		DC and Switching Characteristics	Updated the Recommended Operating Conditions section. Adjusted Max. values for V_{CC} and V_{CCIO}.
			Updated the sysIO Recommended Operating Conditions section. Adjusted Max. values for LVCMOS 3.3, LVTTL, PCI, LVDS33 and LVPECL.
		Pinout Information	Updated the Pinout Information Summary section. Removed MachXO2-4000U.
		Ordering Information	Updated the MachXO2 Part Number Description section. Removed BG400 package.
			Updated the High-Performance Commercial Grade Devices with Voltage Regulator, Halogen Free (RoHS) Packaging section. Removed LCMXO2-4000UHC part numbers.
			Updated the High-Performance Industrial Grade Devices with Voltage Regulator, Halogen Free (RoHS) Packaging section. Removed LCMXO2-4000UHC part numbers.
November 2014	2.8	Introduction	Updated the Features section. — Revised I/Os under Flexible Logic Architecture. — Revised standby power under Ultra Low Power Devices. — Revise input frequency range under Flexible On-Chip Clocking.
			Updated Table 1-1, MachXO2 Family Selection Guide. — Added XO2-4000U data. — Removed HE and ZE device options for XO2-4000. — Added 400-ball ftBGA.
		Pinout Information	Updated the Pinout Information Summary section. Added MachXO2-4000U caBGA400 and MachXO2-7000 caBGA400.
		Ordering Information	Updated the MachXO2 Part Number Description section. Added BG400 package.
			Updated the Ordering Information section. Added MachXO2-4000U caBGA400 and MachXO2-7000 caBGA400 part numbers.
October 2014	2.7	Ordering Information	Updated the Ultra Low Power Industrial Grade Devices, Halogen Free (RoHS) Packaging section. Fixed typo in LCMXO2-2000ZE-1UWG49ITR part number package.
		Architecture	Updated the Supported Standards section. Added MIPI information to Table 2-12. Supported Input Standards and Table 2-13. Supported Output Standards.
		DC and Switching Characteristics	Updated the BLVDS section. Changed output impedance nominal values in Table 3-2, BLVDS DC Condition.
			Updated the LVPECL section. Changed output impedance nominal value in Table 3-3, LVPECL DC Condition.
			Updated the sysCONFIG Port Timing Specifications section. Updated INITN low time values.
July 2014	2.6	DC and Switching Characteristics	Updated sysIO Single-Ended DC Electrical Characteristics[1, 2] section. Updated footnote 4.
			Updated Register-to-Register Performance section. Updated footnote.
		Ordering Information	Updated UW49 package to UWG49 in MachXO2 Part Number Description.
			Updated LCMXO2-2000ZE-1UWG49CTR package in Ultra Low Power Commercial Grade Devices, Halogen Free (RoHS) Packaging.

Date	Version	Section	Change Summary
May 2014	2.5	Architecture	Updated TransFR (Transparent Field Reconfiguration) section. Updated TransFR description for PLL use during background Flash programming.
February 2014	02.4	Introduction	Included the 49 WLCSP package in the MachXO2 Family Selection Guide table.
		Architecture	Added information to Standby Mode and Power Saving Options section.
		Pinout Information	Added the XO2-2000 49 WLCSP in the Pinout Information Summary table.
		Ordering Information	Added UW49 package in MachXO2 Part Number Description.
			Added and LCMXO2-2000ZE-1UWG49CTR in Ultra Low Power Commercial Grade Devices, Halogen Free (RoHS) Packaging section.
			Added and LCMXO2-2000ZE-1UWG49ITR in Ultra Low Power Industrial Grade Devices, Halogen Free (RoHS) Packaging section.
December 2013	02.3	Architecture	Updated information on CLKOS output divider in sysCLOCK Phase Locked Loops (PLLs) section.
		DC and Switching Characteristics	Updated Static Supply Current – ZE Devices table.
			Updated footnote 4 in sysIO Single-Ended DC Electrical Characteristics table; Updated V_{IL} Max. (V) data for LVCMOS 25 and LVCMOS 28.
			Updated V_{OS} test condition in sysIO Differential Electrical Characteristics - LVDS table.
September 2013	02.2	Architecture	Removed I^2C Clock-Stretching feature per PCN #10A-13.
			Removed information on PDPR memory in RAM Mode section.
			Updated Supported Input Standards table.
		DC and Switching Characteristics	Updated Power-On-Reset Voltage Levels table.
June 2013	02.1	Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.
			sysCLOCK Phase Locked Loops (PLLs) section – Added missing cross reference to sysCLOCK PLL Timing table.
		DC and Switching Characteristics	Added slew rate information to footnote 2 of the MachXO2 External Switching Characteristics – HC/HE Devices and the MachXO2 External Switching Characteristics – ZE Devices tables.
			Power-On-Reset Voltage Levels table – Added symbols.

Date	Version	Section	Change Summary
January 2013	02.0	Introduction	Updated the total number IOs to include JTAGENB.
		Architecture	Supported Output Standards table – Added 3.3 V_{CCIO} (Typ.) to LVDS row.
			Changed SRAM CRC Error Detection to Soft Error Detection.
		DC and Switching Characteristics	Power Supply Ramp Rates table – Updated Units column for t_{RAMP} symbol.
			Added new Maximum sysIO Buffer Performance table.
			sysCLOCK PLL Timing table – Updated Min. column values for f_{IN}, f_{OUT}, f_{OUT2} and f_{PFD} parameters. Added t_{SPO} parameter. Updated footnote 6.
			MachXO2 Oscillator Output Frequency table – Updated symbol name for $t_{STABLEOSC.}$
			DC Electrical Characteristics table – Updated conditions for $I_{IL,}$ I_{IH} symbols.
			Corrected parameters tDQVBS and tDQVAS
			Corrected MachXO2 ZE parameters tDVADQ and tDVEDQ
		Pinout Information	Included the MachXO2-4000HE 184 csBGA package.
		Ordering Information	Updated part number.
April 2012	01.9	Architecture	Removed references to TN1200.
		Ordering Information	Updated the Device Status portion of the MachXO2 Part Number Description to include the 50 parts per reel for the WLCSP package.
			Added new part number and footnote 2 for LCMXO2-1200ZE-1UWG25ITR50.
			Updated footnote 1 for LCMXO2-1200ZE-1UWG25ITR.
		Supplemental Information	Removed references to TN1200.
March 2012	01.8	Introduction	Added 32 QFN packaging information to Features bullets and MachXO2 Family Selection Guide table.
		DC and Switching Characteristics	Changed ‘STANDBY’ to ‘USERSTDBY’ in Standby Mode timing diagram.
		Pinout Information	Removed footnote from Pin Information Summary tables.
			Added 32 QFN package to Pin Information Summary table.
		Ordering Information	Updated Part Number Description and Ordering Information tables for 32 QFN package.
			Updated topside mark diagram in the Ordering Information section.

Date	Version	Section	Change Summary
February 2012	01.7	All	Updated document with new corporate logo.
	01.6	—	Data sheet status changed from preliminary to final.
		Introduction	MachXO2 Family Selection Guide table – Removed references to 49-ball WLCSP.
		DC and Switching Characteristics	Updated Flash Download Time table.
			Modified Storage Temperature in the Absolute Maximum Ratings section.
			Updated I_{DK} max in Hot Socket Specifications table.
			Modified Static Supply Current tables for ZE and HC/HE devices.
			Updated Power Supply Ramp Rates table.
			Updated Programming and Erase Supply Current tables.
			Updated data in the External Switching Characteristics table.
			Corrected Absolute Maximum Ratings for Dedicated Input Voltage Applied for LCMXO2 HC.
			DC Electrical Characteristics table – Minor corrections to conditions for I_{IL}, I_{IH}.
		Pinout Information	Removed references to 49-ball WLCSP.
			Signal Descriptions table – Updated description for GND, VCC, and VCCIOx.
			Updated Pin Information Summary table – Number of VCCIOs, GNDs, VCCs, and Total Count of Bonded Pins for MachXO2-256, 640, and 640U and Dual Function I/O for MachXO2-4000 332caBGA.
		Ordering Information	Removed references to 49-ball WLCSP
August 2011	01.5	DC and Switching Characteristics	Updated ESD information.
		Ordering Information	Updated footnote for ordering WLCSP devices.
	01.4	Architecture	Updated information in Clock/Control Distribution Network and sysCLOCK Phase Locked Loops (PLLs).
		DC and Switching Characteristics	Updated I_{IL} and I_{IH} conditions in the DC Electrical Characteristics table.
		Pinout Information	Included number of 7:1 and 8:1 gearboxes (input and output) in the pin information summary tables.
			Updated Pin Information Summary table: Dual Function I/O, DQS Groups Bank 1, Total General Purpose Single-Ended I/O, Differential I/O Per Bank, Total Count of Bonded Pins, Gearboxes. Added column of data for MachXO2-2000 49 WLCSP.
		Ordering Information	Updated R1 Device Specifications text section with information on migration from MachXO2-1200-R1 to Standard (non-R1) devices.
			Corrected Supply Voltage typo for part numbers: LCMX02-2000UHE-4FG484I, LCMX02-2000UHE-5FG484I, LCMX02-2000UHE-6FG484I.
			Added footnote for WLCSP package parts.
		Supplemental Information	Removed reference to Stand-alone Power Calculator for MachXO2 Devices. Added reference to AN8086, Designing for Migration from MachXO2-1200-R1 to Standard (non-R1) Devices.

Date	Version	Section	Change Summary
May 2011	01.3	Multiple	Replaced “SED” with “SRAM CRC Error Detection” throughout the document.
		DC and Switching Characteristics	Added footnote 1 to Program Erase Specifications table.
		Pinout Information	Updated Pin Information Summary tables.
			Signal name SO/SISPISO changed to SO/SPISO in the Signal Descriptions table.
April 2011	01.2	—	Data sheet status changed from Advance to Preliminary.
		Introduction	Updated MachXO2 Family Selection Guide table.
		Architecture	Updated Supported Input Standards table.
			Updated sysMEM Memory Primitives diagram.
			Added differential SSTL and HSTL IO standards.
		DC and Switching Characteristics	Updates following parameters: POR voltage levels, DC electrical characteristics, static supply current for ZE/HE/HC devices, static power consumption contribution of different components – ZE devices, programming and erase Flash supply current.
			Added VREF specifications to sysIO recommended operating conditions.
			Updating timing information based on characterization.
			Added differential SSTL and HSTL IO standards.
		Ordering Information	Added Ordering Part Numbers for R1 devices, and devices in WLCSP packages.
			Added R1 device specifications.
January 2011	01.1	All	Included ultra-high I/O devices.
		DC and Switching Characteristics	Recommended Operating Conditions table – Added footnote 3.
			DC Electrical Characteristics table – Updated data for I_{IL}, I_{IH}. V_{HYST} typical values updated.
			Generic DDRX2 Outputs with Clock and Data Aligned at Pin (GDDRX2_TX.ECLK.Aligned) Using PCLK Pin for Clock Input tables – Updated data for T_{DIA} and T_{DIB}.
			Generic DDRX4 Outputs with Clock and Data Aligned at Pin (GDDRX4_TX.ECLK.Aligned) Using PCLK Pin for Clock Input tables – Updated data for T_{DIA} and T_{DIB}.
			Power-On-Reset Voltage Levels table - clarified note 3.
			Clarified VCCIO related recommended operating conditions specifications.
			Added power supply ramp rate requirements.
			Added Power Supply Ramp Rates table.
			Updated Programming/Erase Specifications table.
			Removed references to V_{CCP}.
		Pinout Information	Included number of 7:1 and 8:1 gearboxes (input and output) in the pin information summary tables.
			Removed references to V_{CCP}.
November 2010	01.0	—	Initial release.